TEXAS INSTRUMENTS

MSP430F5638, MSP430F5637, MSP430F5636, MSP430F5635
MSP430F5634, MSP430F5633, MSP430F5632, MSP430F5631, MSP430F5630

ZHCS410F – JUNE 2010 – REVISED SEPTEMBER 2018

MSP430F563x 混合信号微控制器

1 器件概述

1.1 特性

- 低电源电压范围：1.8V 至 3.6V
- 超低功耗
  - 激活模式 (AM)：
    所有系统时钟激活：
    在 8MHz、3.0V 且闪存程序执行时为
    270µA/MHz（典型值）
  - 待机模式 (LPM3)：
    带有晶振的看门狗和电源监视器工作、完全 RAM
    保持、快速唤醒：
    2.2V 时为 1.8µA，3.0V 时为 2.1µA（典型值）
  - 关断实时时钟 (RTC) 模式 (LPM3.5)：
    关断模式、采用晶振的 RTC 工作：
    3.0V 时为 1.1µA（典型值）
  - 关断模式 (LPM4.5)：
    3.0V 时为 0.3µA（典型值）
- 在 3µs（典型值）内从待机模式唤醒
- 16 位精简指令集 (RISC) 架构、扩展存储器、高达 20MHz 的系统时钟
- 灵活的电源管理系统
  - 内置可编程的低压降稳压器 (LDO)
  - 电源电压监控、监视、和临时限电
- 统一时钟系统
  - 针对频率稳定的锁相环 (FLL) 控制环路
  - 低功耗低频内部时钟源 (VLO)
  - 低频修整内部基准源 (REFO)
  - 32kHz 晶振 (XT1)
  - 高达 32MHz 的高频晶振 (XT2)
- 4 个定时器，分别配有 3、5 或 7 个捕捉/比较寄存器
- 两个通用串行通信接口 (USCI)
  - USCI_A0 和 USCI_A1 均支持：
    - 增强型通用异步收发器 (UART) 支持自动波特率检测
    - IrDA 编码和解码
    - 同步串行外设接口 (SPI)
  - USCI_B0 和 USCI_B1 每个都支持：
    - I^2C
    - 同步串行外设接口 (SPI)
- 全速通用串行总线 (USB)
  - 集成的 USB - 物理层 (PHY)
  - 集成 3.3V 和 1.8V USB 电源系统
  - 集成 USB- 锁相环 (PLL)
  - 8 输入和 8 输出端点
- 具有内部共用基准、采样保持、和自动扫描功能的 12 位模数转换器 (ADC)
- 具有同步功能的双通道 12 位数模转换器 (DAC)
- 电压比较器
- 硬件乘法器支持 32 位运算
- 串行板上编程，无需外部编程电压
- 6 通道内部 DMA
- 具有电源电压备用开关的 RTC 模块
- 器件比较 汇总了可用的产品系列成员

1.2 应用范围

- 模拟和数字传感器系统
- 数字电机控制
- 遥控
- 恒温器
- 数字定时器
- 手持仪表

本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。 有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。 TI 不保证翻译的准确性和有效性。 在实际设计之前，请务必参考最新版本的英文版本。

1.3 说明

TI 的 MSP430™系列超低功耗微控制器种类繁多，各成员器件配备不同的外设集以满足各类应用的 需要。该架构与五种低功耗模式配合使用，是延长便携式测量应用电池寿命的最优 选择。该器件 具有 一个强大的 16 位精简指令集 (RISC) 中央处理器 (CPU)，使用 16 位寄存器以及常数发生器，以便获得最高编码效率。该数控振荡器 (DCO) 可在 3µs（典型值）内从低功率模式唤醒至激活模式。

MSP430F563x 器件为配有以下外设的微控制器：一个高性能 12 位 ADC、一个比较器、两个 USCI、USB 2.0、一个硬件乘法器、DMA、四个 16 位定时器、一个具有报警功能的 RTC 模块以及多达 74 个 I/O 引脚。

有关完整的模块说明，请参阅*《MSP430F5xx 和 MSP430F6xx 系列用户指南》*。

器件信息(1)

器件型号	封装	封装尺寸(2)
MSP430F5638IPZ	LQFP (100)	14mm x 14mm
MSP430F5638IZQW	BGA (113)	7mm x 7mm

(1) 要获得最新的器件、封装和订购信息，请参见*封装选项附录*（节 8），或者访问 TI 网站 www.ti.com.cn。
(2) 这里显示的尺寸为近似值。要获得包含误差值的封装尺寸，请参见*机械数据*（节 8）。

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1.4 功能框图

图 1-1 给出了 MSP430F5638、MSP430F5637 和 MSP430F5636 器件的功能框图。

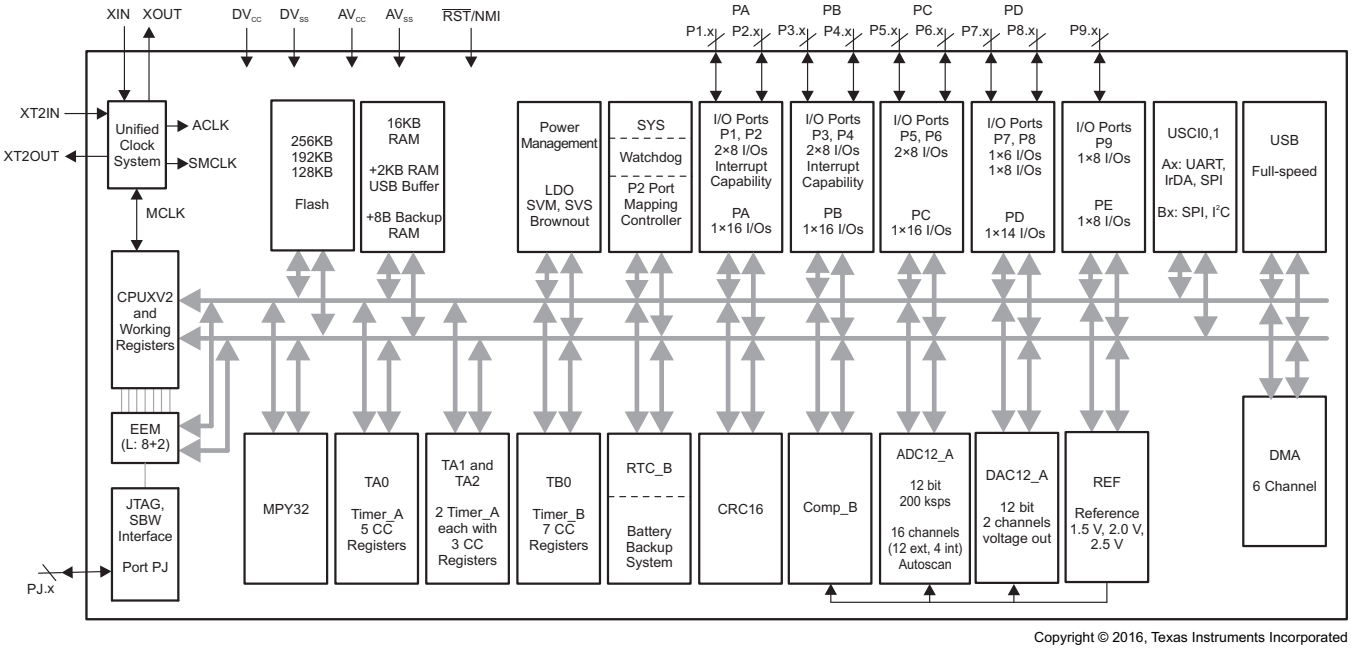


图 1-1. 功能框图 – MSP430F5638、MSP430F5637 和 MSP430F5636

图 1-2 给出了 MSP430F5635、MSP430F5634 和 MSP430F5633 器件的功能框图。

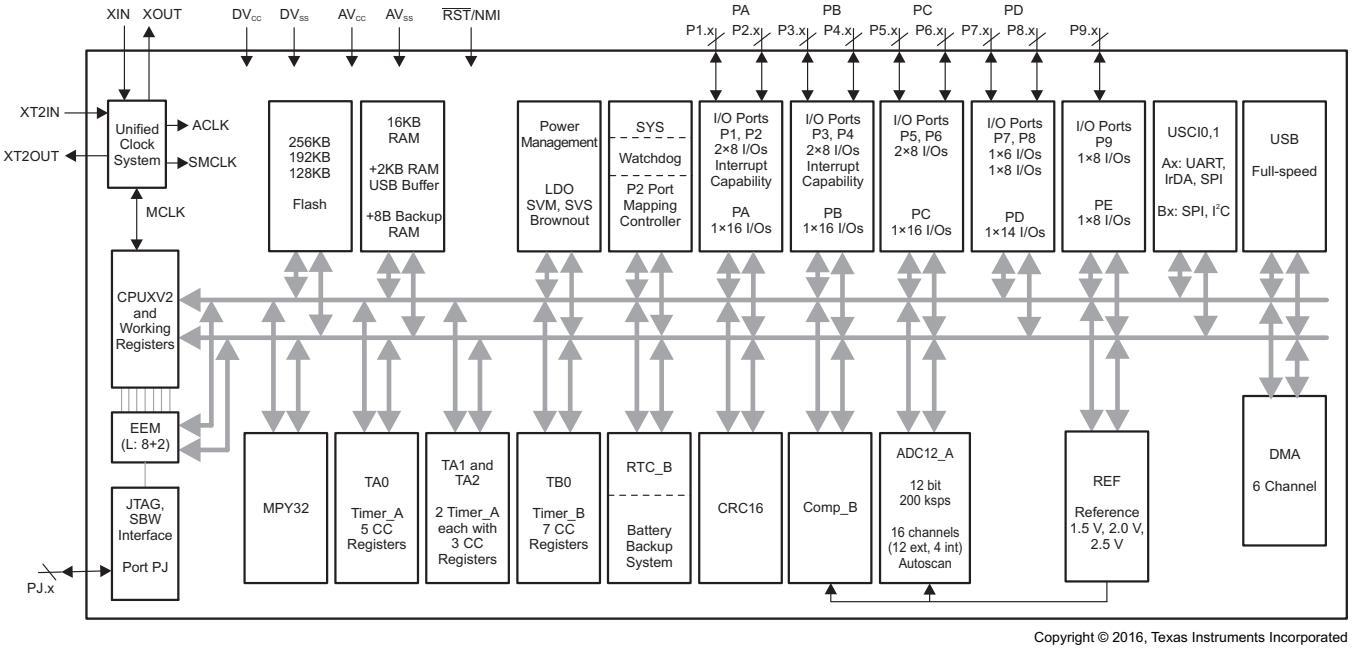
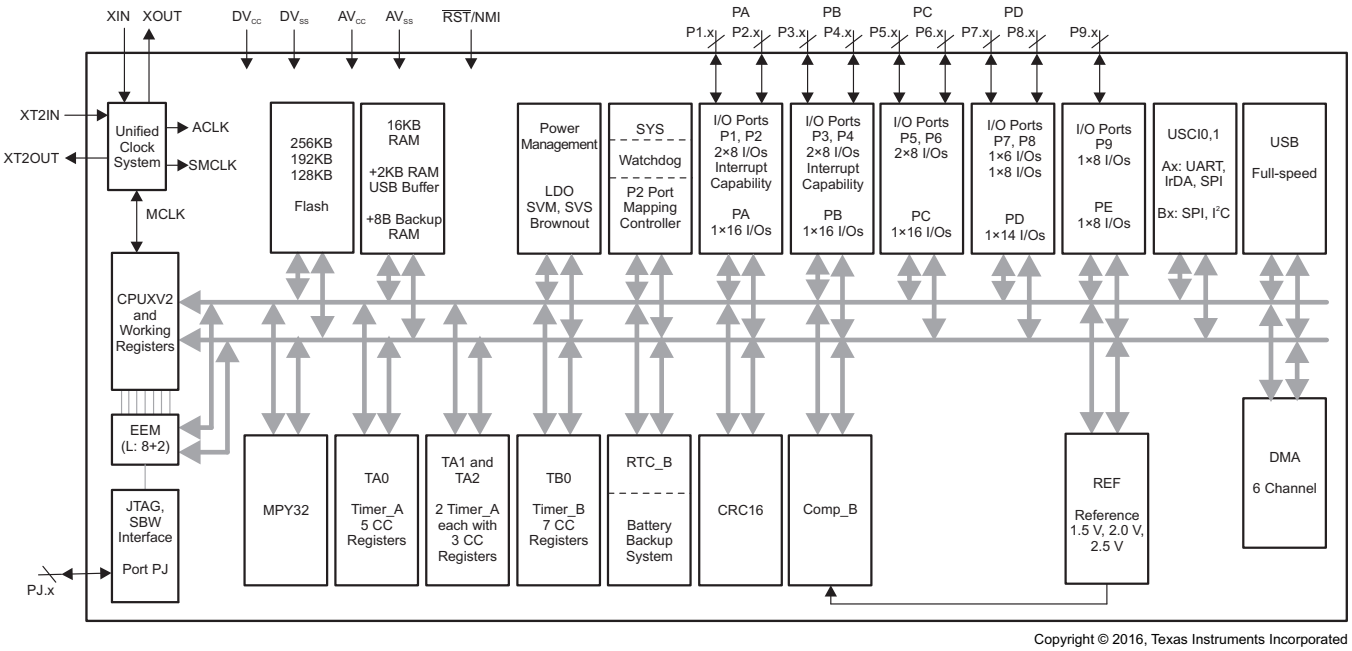


图 1-2. 功能框图 – MSP430F5635、MSP430F5634 和 MSP430F5633

图 1-3 给出了 MSP430F5632、MSP430F5631 和 MSP430F5630 器件的功能框图。



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图 **1-3.** 功能框图 **– MSP430F5632、MSP430F5631** 和 **MSP430F5630**

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2 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from December 9, 2015 to September 17, 2018 **Page**

- Added Section 3.1, *Related Products* 7
- Added typical conditions statements at the beginning of Section 5, *Specifications* 18
- Changed the MIN value of the $V_{(DVCC_BOR_hys)}$ parameter from 60 mV to 50 mV in Section 5.20, *PMM, Brownout Reset (BOR)* 30
- Updated notes (1) and (2) and added note (3) in Section 5.26, *Wake-up Times From Low-Power Modes and Reset* 32
- Removed ADC12DIV from the formula for the TYP value in the second row of the $t_{CONVERT}$ parameter in Section 5.35, *12-Bit ADC, Timing Parameters*, because ADC12CLK is after division 39
- Removed the note that started "This impedance depends on..." from the "Reference input resistance" parameter in Section 5.45, *12-Bit DAC, Reference Input Specifications* 47
- Added second row for t_{EN_CMP} with Test Conditions of "CBPWRMD = 10" and MAX value of 100 µs in Section 5.48, *Comparator_B* 49
- Renamed FCTL4.MGR0 and MGR1 in the $f_{MCLK,MGR}$ parameter in Section 5.54, *Flash Memory* to be consistent with header files 52
- 将先前的*开发工具支持* 部分替换成了节 7.3，*工具与软件* 107

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3 Device Comparison

Table 3-1 summarizes the available family members.

Table 3-1. Device Comparison(1)(2)

DEVICE	FLASH (KB)	SRAM (KB)(3)	Timer_A(4)	Timer_B(5)	USCI		ADC12_A (Ch)	DAC12_A (Ch)	Comp_B (Ch)	USB	I/O	PACKAGE
					CHANNEL A: UART, IrDA, SPI	CHANNEL B: SPI, I²C						
MSP430F5638	256	16 + 2	5, 3, 3	7	2	2	12 ext, 4 int	2	12	Yes	74	100 PZ, 113 ZQW
MSP430F5637	192	16 + 2	5, 3, 3	7	2	2	12 ext, 4 int	2	12	Yes	74	100 PZ, 113 ZQW
MSP430F5636	128	16 + 2	5, 3, 3	7	2	2	12 ext, 4 int	2	12	Yes	74	100 PZ, 113 ZQW
MSP430F5635	256	16 + 2	5, 3, 3	7	2	2	12 ext, 4 int	–	12	Yes	74	100 PZ, 113 ZQW
MSP430F5634	192	16 + 2	5, 3, 3	7	2	2	12 ext, 4 int	–	12	Yes	74	100 PZ, 113 ZQW
MSP430F5633	128	16 + 2	5, 3, 3	7	2	2	12 ext, 4 int	–	12	Yes	74	100 PZ, 113 ZQW
MSP430F5632	256	16 + 2	5, 3, 3	7	2	2	–	–	12	Yes	74	100 PZ, 113 ZQW
MSP430F5631	192	16 + 2	5, 3, 3	7	2	2	–	–	12	Yes	74	100 PZ, 113 ZQW
MSP430F5630	128	16 + 2	5, 3, 3	7	2	2	–	–	12	Yes	74	100 PZ, 113 ZQW

(1) For the most current package and ordering information, see the *Package Option Addendum* in 节 8, or see the TI website at www.ti.com.
(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/packaging.
(3) The additional 2KB of USB SRAM that is listed can be used as general-purpose SRAM when USB is not in use.
(4) Each number in the sequence represents an instantiation of Timer_A with its associated number of capture/compare registers and PWM output generators available. For example, a number sequence of 3, 5 would represent two instantiations of Timer_A, the first instantiation having 3 and the second instantiation having 5 capture/compare registers and PWM output generators, respectively.
(5) Each number in the sequence represents an instantiation of Timer_B with its associated number of capture/compare registers and PWM output generators available. For example, a number sequence of 3, 5 would represent two instantiations of Timer_B, the first instantiation having 3 and the second instantiation having 5 capture/compare registers and PWM output generators, respectively.

3.1 Related Products

For information about other devices in this family of products or related products, see the following links.

Products for TI Microcontrollers TI's low-power and high-performance MCUs, with wired and wireless connectivity options, are optimized for a broad range of applications.

Products for MSP430 Ultra-Low-Power Microcontrollers One platform. One ecosystem. Endless possibilities. Enabling the connected world with innovations in ultra-low-power microcontrollers with advanced peripherals for precise sensing and measurement.

Companion Products for MSP430F5638 Review products that are frequently purchased or used in conjunction with this product.

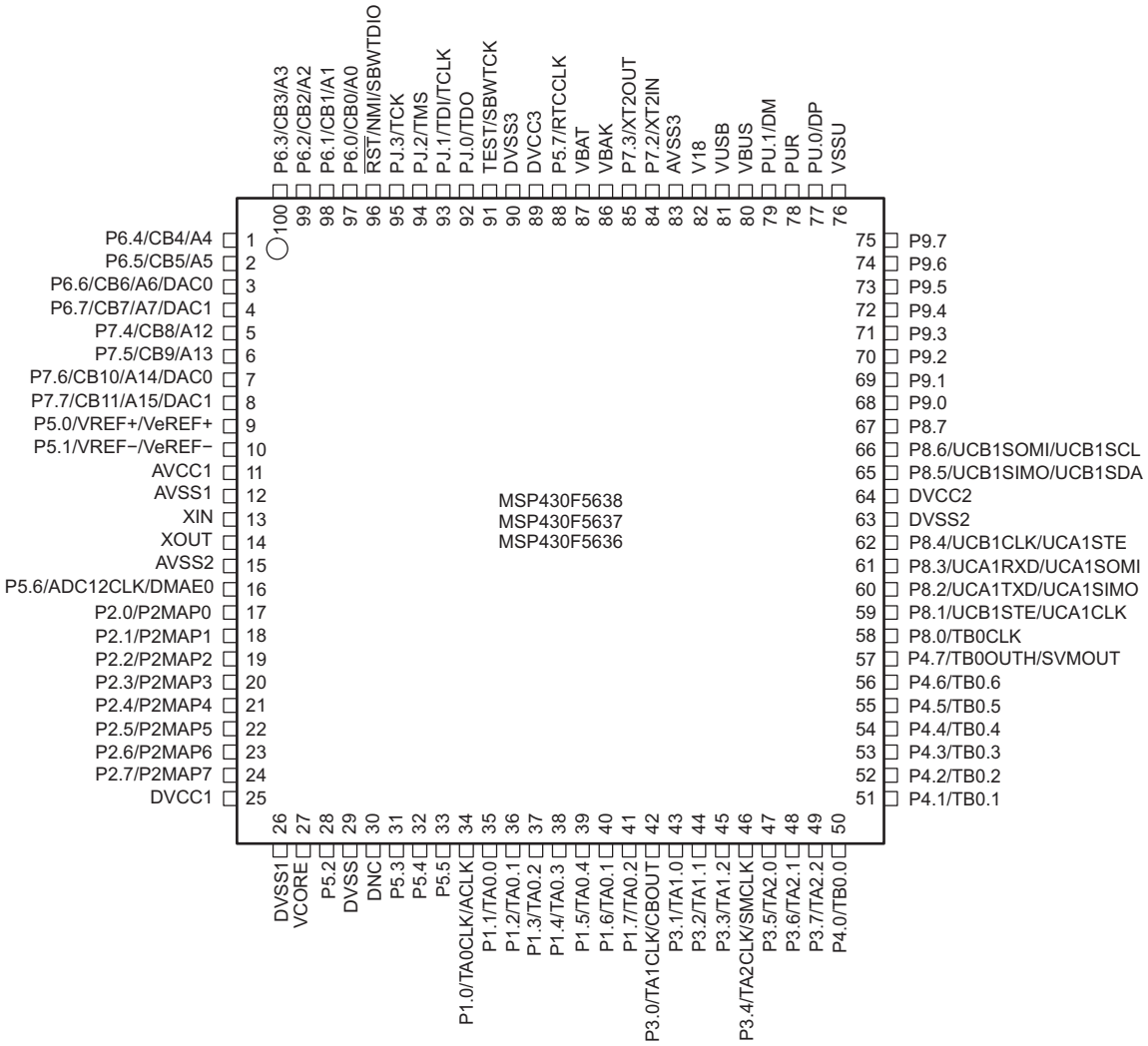
Reference Designs TI Designs Reference Design Library is a robust reference design library that spans analog, embedded processor, and connectivity. Created by TI experts to help you jump start your system design, all TI Designs include schematic or block diagrams, BOMs, and design files to speed your time to market. Search and download designs at ti.com/tidesigns.

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4 Terminal Configuration and Functions

4.1 Pin Diagrams

Figure 4-1 shows the pinout for the MSP430F5638, MSP430F5637, and MSP430F5636 devices in the 100-pin PZ package.

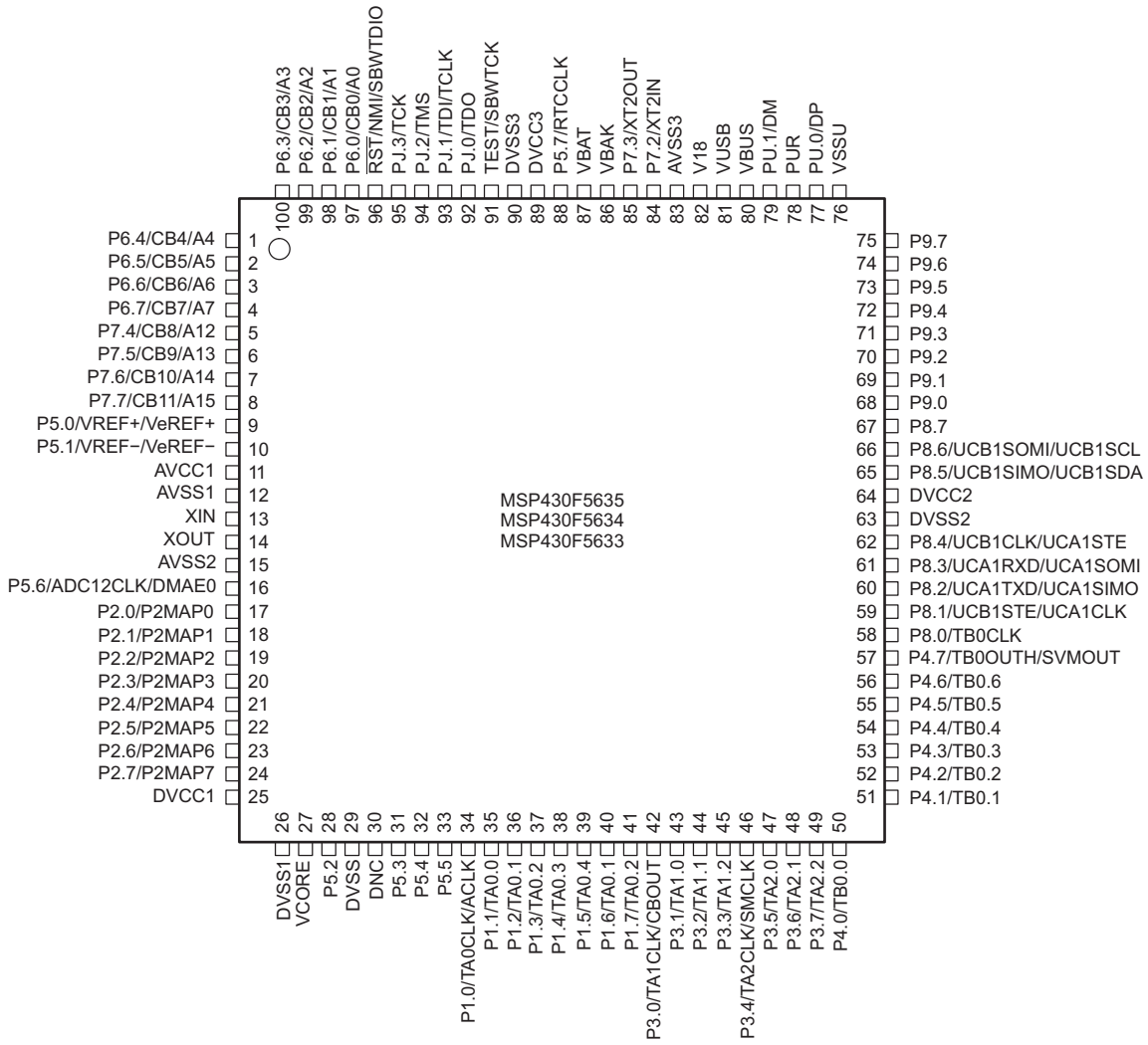


NOTE: DNC = Do not connect

Figure 4-1. 100-Pin PZ Package (Top View) – MSP430F5638, MSP430F5637, MSP430F5636

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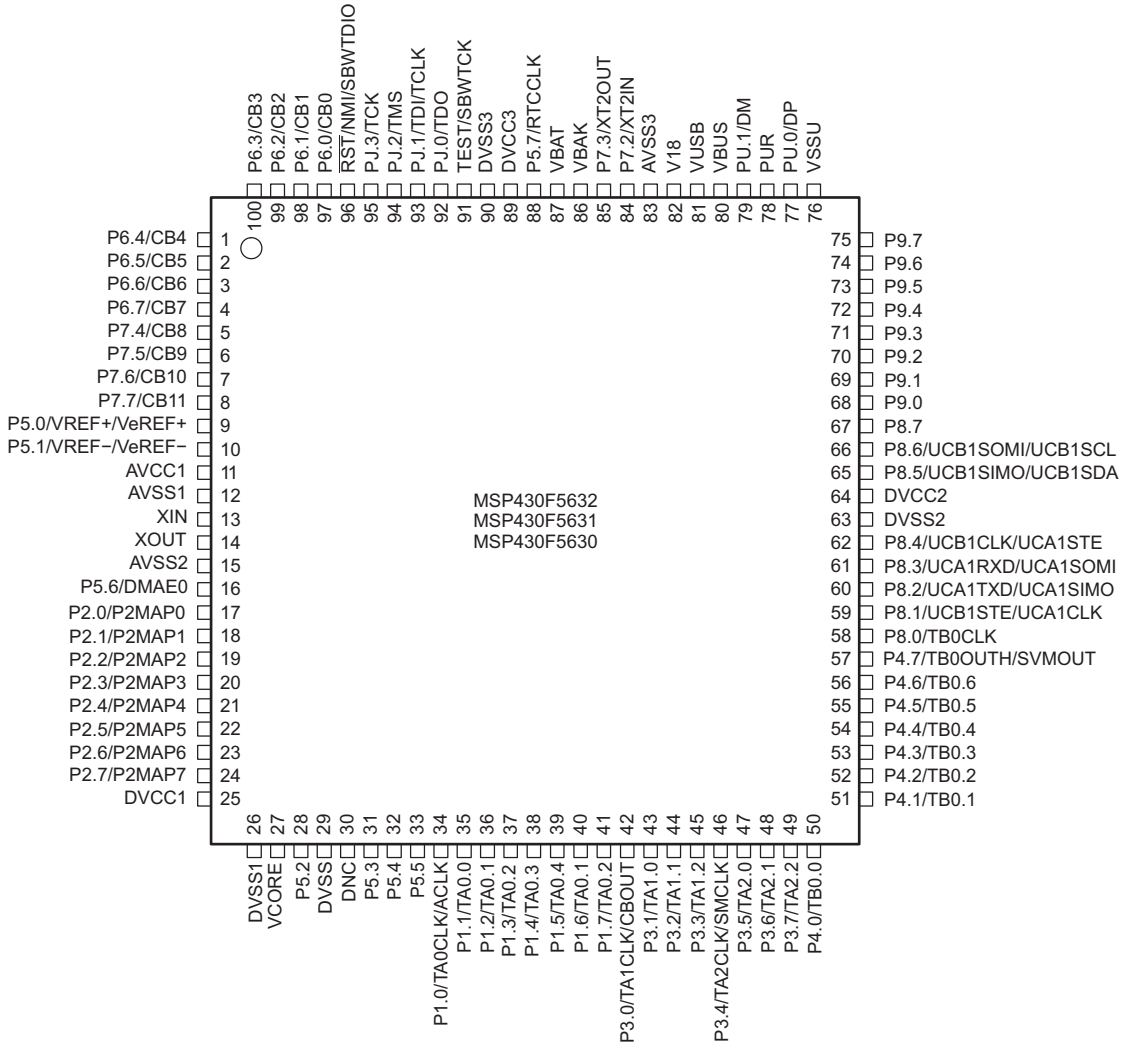
Figure 4-2 shows the pinout for the MSP430F5635, MSP430F5634, and MSP430F5633 devices in the 100-pin PZ package.



NOTE: DNC = Do not connect

Figure 4-2. 100-Pin PZ Package (Top View) – MSP430F5635, MSP430F5634, MSP430F5633

Figure 4-3 shows the pinout for the MSP430F5632, MSP430F5631, and MSP430F5630 devices in the 100-pin PZ package.

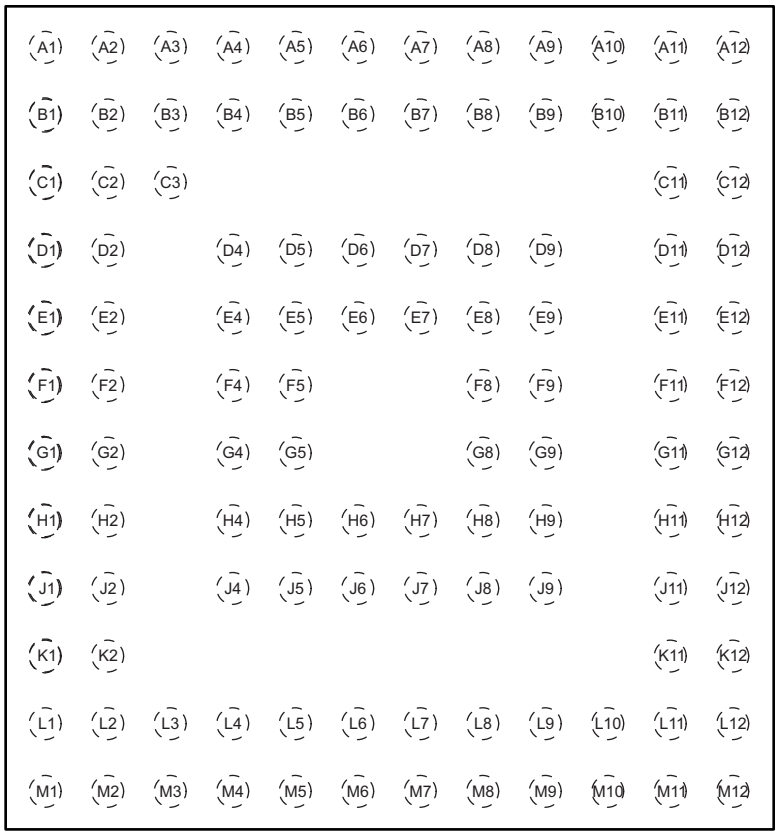


NOTE: DNC = Do not connect

Figure 4-3. 100-Pin PZ Package (Top View) – MSP430F5632, MSP430F5631, MSP430F5630

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Figure 4-4 shows the pinout for all devices in the 113-pin ZQW package. See Section 4.2 for pin assignments and descriptions.



NOTE: For terminal assignments, see Table 4-1.

Figure 4-4. 113-Pin ZQW Package (Top View) – MSP430F5638, MSP430F5637, MSP430F5636, MSP430F5635, MSP430F5634, MSP430F5633, MSP430F5632, MSP430F5631, MSP430F5630

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4.2 Signal Descriptions

Table 4-1 describes the signals for all device variants and packages.

Table 4-1. Signal Descriptions

TERMINAL			I/O (1)	DESCRIPTION
NAME	NO.			
	PZ	ZQW		
P6.4/CB4/A4	1	A1	I/O	General-purpose digital I/O Comparator_B input CB4 Analog input A4 – ADC (not available on F5632, F5631, and F5630 devices)
P6.5/CB5/A5	2	B2	I/O	General-purpose digital I/O Comparator_B input CB5 Analog input A5 – ADC (not available on F5632, F5631, and F5630 devices)
P6.6/CB6/A6/DAC0	3	B1	I/O	General-purpose digital I/O Comparator_B input CB6 Analog input A6 – ADC (not available on F5632, F5631, and F5630 devices) DAC12.0 output (not available on F5635, F5634, F5633, F5632, F5631, and F5630 devices)
P6.7/CB7/A7/DAC1	4	C2	I/O	General-purpose digital I/O Comparator_B input CB7 Analog input A7 – ADC (not available on F5632, F5631, and F5630 devices) DAC12.1 output (not available on F5635, F5634, F5633, F5632, F5631, and F5630 devices)
P7.4/CB8/A12	5	C1	I/O	General-purpose digital I/O Comparator_B input CB8 Analog input A12 –ADC (not available on F5632, F5631, and F5630 devices)
P7.5/CB9/A13	6	C3	I/O	General-purpose digital I/O Comparator_B input CB9 Analog input A13 – ADC (not available on F5632, F5631, and F5630 devices)
P7.6/CB10/A14/DAC0	7	D2	I/O	General-purpose digital I/O Comparator_B input CB10 Analog input A14 – ADC (not available on F5632, F5631, and F5630 devices) DAC12.0 output (not available on F5635, F5634, F5633, F5632, F5631, and F5630 devices)
P7.7/CB11/A15/DAC1	8	D1	I/O	General-purpose digital I/O Comparator_B input CB11 Analog input A15 – ADC (not available on F5632, F5631, and F5630 devices) DAC12.1 output (not available on F5635, F5634, F5633, F5632, F5631, and F5630 devices)
P5.0/VREF+/VeREF+	9	D4	I/O	General-purpose digital I/O Output of reference voltage to the ADC Input for an external reference voltage to the ADC
P5.1/VREF-/VeREF-	10	E4	I/O	General-purpose digital I/O Negative terminal for the reference voltage of the ADC for both sources, the internal reference voltage, or an external applied reference voltage
AVCC1	11	E1, E2		Analog power supply

(1) I = input, O = output, N/A = not available on this package offering

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Table 4-1. Signal Descriptions (continued)

TERMINAL			I/O[1]	DESCRIPTION
NAME	NO.			
	PZ	ZQW		
AVSS1	12	F2		Analog ground supply
XIN	13	F1	I	Input terminal for crystal oscillator XT1
XOUT	14	G1	O	Output terminal of crystal oscillator XT1
AVSS2	15	G2		Analog ground supply
P5.6/ADC12CLK/DMAE0	16	H1	I/O	General-purpose digital I/O Conversion clock output ADC (not available on F5632, F5631, and F5630 devices) DMA external trigger input
P2.0/P2MAP0	17	G4	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: USCI_B0 SPI slave transmit enable; USCI_A0 clock input/output
P2.1/P2MAP1	18	H2	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: USCI_B0 SPI slave in/master out; USCI_B0 I^2C data
P2.2/P2MAP2	19	J1	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: USCI_B0 SPI slave out/master in; USCI_B0 I^2C clock
P2.3/P2MAP3	20	H4	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: USCI_B0 clock input/output; USCI_A0 SPI slave transmit enable
P2.4/P2MAP4	21	J2	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: USCI_A0 UART transmit data; USCI_A0 SPI slave in/master out
P2.5/P2MAP5	22	K1	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: USCI_A0 UART receive data; USCI_A0 slave out/master in
P2.6/P2MAP6	23	K2	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: no secondary function
P2.7/P2MAP7	24	L2	I/O	General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: no secondary function
DVCC1	25	L1		Digital power supply
DVSS1	26	M1		Digital ground supply
VCORE[2]	27	M2		Regulated core power supply (internal use only, no external current loading)
P5.2	28	L3	I/O	General-purpose digital I/O
DVSS	29	M3		Digital ground supply
DNC	30	J4		Do not connect. It is strongly recommended to leave this terminal open.
P5.3	31	L4	I/O	General-purpose digital I/O
P5.4	32	M4	I/O	General-purpose digital I/O
P5.5	33	J5	I/O	General-purpose digital I/O
P1.0/TA0CLK/ACLK	34	L5	I/O	General-purpose digital I/O with port interrupt Timer TA0 clock signal TACLK input ACLK output (divided by 1, 2, 4, 8, 16, or 32)
P1.1/TA0.0	35	M5	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR0 capture: CCI0A input, compare: Out0 output BSL transmit output
P1.2/TA0.1	36	J6	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR1 capture: CCI1A input, compare: Out1 output BSL receive input

(2) VCORE is for internal use only. No external current loading is possible. VCORE should only be connected to the recommended capacitor value, C_{VCORE}.

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Table 4-1. Signal Descriptions (continued)

TERMINAL			I/O[1]	DESCRIPTION
NAME	NO.			
	PZ	ZQW		
P1.3/TA0.2	37	H6	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR2 capture: CCI2A input, compare: Out2 output
P1.4/TA0.3	38	M6	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR3 capture: CCI3A input compare: Out3 output
P1.5/TA0.4	39	L6	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR4 capture: CCI4A input, compare: Out4 output
P1.6/TA0.1	40	J7	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR1 capture: CCI1B input, compare: Out1 output
P1.7/TA0.2	41	M7	I/O	General-purpose digital I/O with port interrupt Timer TA0 CCR2 capture: CCI2B input, compare: Out2 output
P3.0/TA1CLK/CBOUT	42	L7	I/O	General-purpose digital I/O with port interrupt Timer TA1 clock input Comparator_B output
P3.1/TA1.0	43	H7	I/O	General-purpose digital I/O with port interrupt Timer TA1 capture CCR0: CCI0A/CCI0B input, compare: Out0 output
P3.2/TA1.1	44	M8	I/O	General-purpose digital I/O with port interrupt Timer TA1 capture CCR1: CCI1A/CCI1B input, compare: Out1 output
P3.3/TA1.2	45	L8	I/O	General-purpose digital I/O with port interrupt Timer TA1 capture CCR2: CCI2A/CCI2B input, compare: Out2 output
P3.4/TA2CLK/SMCLK	46	J8	I/O	General-purpose digital I/O with port interrupt Timer TA2 clock input SMCLK output
P3.5/TA2.0	47	M9	I/O	General-purpose digital I/O with port interrupt Timer TA2 capture CCR0: CCI0A/CCI0B input, compare: Out0 output
P3.6/TA2.1	48	L9	I/O	General-purpose digital I/O with port interrupt Timer TA2 capture CCR1: CCI1A/CCI1B input, compare: Out1 output
P3.7/TA2.2	49	M10	I/O	General-purpose digital I/O with port interrupt Timer TA2 capture CCR2: CCI2A/CCI2B input, compare: Out2 output
P4.0/TB0.0	50	J9	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR0: CCI0A/CCI0B input, compare: Out0 output
P4.1/TB0.1	51	M11	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR1: CCI1A/CCI1B input, compare: Out1 output
P4.2/TB0.2	52	L10	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR2: CCI2A/CCI2B input, compare: Out2 output
P4.3/TB0.3	53	M12	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR3: CCI3A/CCI3B input, compare: Out3 output
P4.4/TB0.4	54	L12	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR4: CCI4A/CCI4B input, compare: Out4 output
P4.5/TB0.5	55	L11	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR5: CCI5A/CCI5B input, compare: Out5 output
P4.6/TB0.6	56	K11	I/O	General-purpose digital I/O with port interrupt Timer TB0 capture CCR6: CCI6A/CCI6B input, compare: Out6 output

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Table 4-1. Signal Descriptions (continued)

TERMINAL			I/O[1]	DESCRIPTION
NAME	NO.			
	PZ	ZQW		
P4.7/TB0OUTH/SVMOUT	57	K12	I/O	General-purpose digital I/O with port interrupt Timer TB0: Switch all PWM outputs high impedance SVM output
P8.0/TB0CLK	58	J11	I/O	General-purpose digital I/O Timer TB0 clock input
P8.1/UCB1STE/UCA1CLK	59	J12	I/O	General-purpose digital I/O USCI_B1 SPI slave transmit enable; USCI_A1 clock input/output
P8.2/UCA1TXD/UCA1SIMO	60	H11	I/O	General-purpose digital I/O USCI_A1 UART transmit data; USCI_A1 SPI slave in/master out
P8.3/UCA1RXD/UCA1SOMI	61	H12	I/O	General-purpose digital I/O USCI_A1 UART receive data; USCI_A1 SPI slave out/master in
P8.4/UCB1CLK/UCA1STE	62	G11	I/O	General-purpose digital I/O USCI_B1 clock input/output; USCI_A1 SPI slave transmit enable
DVSS2	63	G12		Digital ground supply
DVCC2	64	F12		Digital power supply
P8.5/UCB1SIMO/UCB1SDA	65	F11	I/O	General-purpose digital I/O USCI_B1 SPI slave in/master out; USCI_B1 I^2C data
P8.6/UCB1SOMI/UCB1SCL	66	G9	I/O	General-purpose digital I/O USCI_B1 SPI slave out/master in; USCI_B1 I^2C clock
P8.7	67	E12	I/O	General-purpose digital I/O
P9.0	68	E11	I/O	General-purpose digital I/O
P9.1	69	F9	I/O	General-purpose digital I/O
P9.2	70	D12	I/O	General-purpose digital I/O
P9.3	71	D11	I/O	General-purpose digital I/O
P9.4	72	E9	I/O	General-purpose digital I/O
P9.5	73	C12	I/O	General-purpose digital I/O
P9.6	74	C11	I/O	General-purpose digital I/O
P9.7	75	D9	I/O	General-purpose digital I/O
VSSU	76	B11, B12		USB PHY ground supply
PU.0/DP	77	A12	I/O	General-purpose digital I/O, controlled by USB control register. Port U is supplied by the LDOO rail. USB data terminal DP
PUR	78	B10	I/O	USB pullup resistor pin (open drain). The voltage level at the PUR pin is used to invoke the default USB BSL. TI recommends a 1-MΩ resistor to ground. See 节 6.7.1 for more information.
PU.1/DM	79	A11	I/O	General-purpose digital I/O, controlled by USB control register. Port U is supplied by the LDOO rail. USB data terminal DM
VBUS	80	A10		USB LDO input (connect to USB power source)
VUSB	81	A9		USB LDO output
V18	82	B9		USB regulated power (internal use only, no external current loading)
AVSS3	83	A8		Analog ground supply

Table 4-1. Signal Descriptions (continued)

TERMINAL			I/O[1]	DESCRIPTION
NAME	NO.			
	PZ	ZQW		
P7.2/XT2IN	84	B8	I/O	General-purpose digital I/O Input terminal for crystal oscillator XT2
P7.3/XT2OUT	85	B7	I/O	General-purpose digital I/O Output terminal of crystal oscillator XT2
VBAK	86	A7		Capacitor for backup subsystem. Do not load this pin externally. For capacitor values, see C_{BAK} in Recommended Operating Conditions.
VBAT	87	D8		Backup or secondary supply voltage. If backup voltage is not supplied, connect to DVCC externally.
P5.7/RTCCLK	88	D7	I/O	General-purpose digital I/O RTCCLK output
DVCC3	89	A6		Digital power supply
DVSS3	90	A5		Digital ground supply
TEST/SBWTCK	91	B6	I	Test mode pin; selects digital I/O on JTAG pins Spy-Bi-Wire input clock
PJ.0/TDO	92	B5	I/O	General-purpose digital I/O Test data output port
PJ.1/TDI/TCLK	93	A4	I/O	General-purpose digital I/O Test data input or test clock input
PJ.2/TMS	94	E7	I/O	General-purpose digital I/O Test mode select
PJ.3/TCK	95	D6	I/O	General-purpose digital I/O Test clock
$\overline{\text{RST}}$/NMI/SBWTDIO	96	A3	I/O	Reset input (active low)[3] Nonmaskable interrupt input Spy-Bi-Wire data input/output
P6.0/CB0/A0	97	B4	I/O	General-purpose digital I/O Comparator_B input CB0 Analog input A0 – ADC (not available on F5632, F5631, and F5630 devices)
P6.1/CB1/A1	98	B3	I/O	General-purpose digital I/O Comparator_B input CB1 Analog input A1 – ADC (not available on F5632, F5631, and F5630 devices)
P6.2/CB2/A2	99	A2	I/O	General-purpose digital I/O Comparator_B input CB2 Analog input A2 – ADC (not available on F5632, F5631, and F5630 devices)
P6.3/CB3/A3	100	D5	I/O	General-purpose digital I/O Comparator_B input CB3 Analog input A3 – ADC (not available on F5632, F5631, and F5630 devices)

(3) When this pin is configured as reset, the internal pullup resistor is enabled by default.

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Table 4-1. Signal Descriptions (continued)

TERMINAL			I/O(1)	DESCRIPTION
NAME	NO.			
	PZ	ZQW		
Reserved	N/A	E5, E6, E8, F4, F5, F8, G5, G8, H5, H8, H9		Reserved. TI recommends connecting to ground (DVSS, AVSS).

5 Specifications

All graphs in this section are for typical conditions, unless otherwise noted.

Typical (TYP) values are specified at V_{CC} = 3.3 V and T_A = 25°C, unless otherwise noted.

5.1 Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Voltage applied at V_{CC} to V_{SS}	–0.3	4.1	V
Voltage applied to any pin (excluding VCORE, VBUS, V18)(2)	–0.3	V_{CC} + 0.3	V
Diode current at any device pin		±2	mA
Maximum junction temperature, T_J		95	°C
Storage temperature, T_{stg}(3)	–55	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages referenced to V_{SS}. VCORE is for internal device use only. No external DC loading or voltage should be applied.
(3) Higher temperature may be applied during board soldering according to the current JEDEC J-STD-020 specification with peak reflow temperatures not higher than classified on the device label on the shipping boxes or reels.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±1000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±250	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±1000 V may actually have higher performance.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Pins listed as ±250 V may actually have higher performance.

5.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage during program execution and flash programming (AVCC1 = DVCC1 = DVCC2 = DVCC3 = DV_{CC} = V_{CC})(1)(2)	PMMCOREVx = 0	1.8		3.6	V
		PMMCOREVx = 0, 1	2.0		3.6	
		PMMCOREVx = 0, 1, 2	2.2		3.6	
		PMMCOREVx = 0, 1, 2, 3	2.4		3.6	
$V_{CC,USB}$	Supply voltage during USB operation, USB PLL disabled (USB_EN = 1, UPLLEN = 0)	PMMCOREVx = 0	1.8		3.6	V
		PMMCOREVx = 0, 1	2.0		3.6	
		PMMCOREVx = 0, 1, 2	2.2		3.6	
		PMMCOREVx = 0, 1, 2, 3	2.4		3.6	
	Supply voltage during USB operation, USB PLL enabled(3) (USB_EN = 1, UPLLEN = 1)	PMMCOREVx = 2	2.2		3.6	
		PMMCOREVx = 2, 3	2.4		3.6	
V_{SS}	Supply voltage (AVSS1 = AVSS2 = AVSS3 = DVSS1 = DVSS2 = DVSS3 = V_{SS})			0		V
$V_{BAT,RTC}$	Backup-supply voltage with RTC operational	T_A = 0°C to 85°C	1.55		3.6	V
		T_A = –40°C to +85°C	1.70		3.6	
$V_{BAT,MEM}$	Backup-supply voltage with backup memory retained	T_A = –40°C to +85°C	1.20		3.6	V
T_A	Operating free-air temperature	I version	–40		85	°C
T_J	Operating junction temperature	I version	–40		85	°C
C_{BAK}	Capacitance at pin VBAK		1	4.7	10	nF

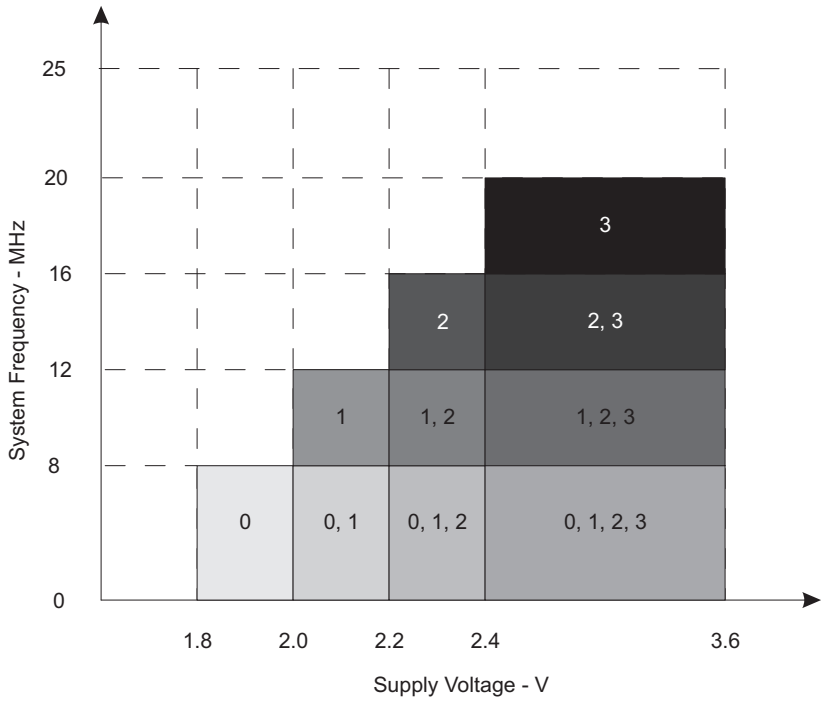
(1) TI recommends powering AV_{CC} and DV_{CC} from the same source. A maximum difference of 0.3 V between AV_{CC} and DV_{CC} can be tolerated during power up and operation.
(2) The minimum supply voltage is defined by the supervisor SVS levels when it is enabled. See the threshold parameters in Section 5.22 for the exact values and more details.
(3) USB operation with USB PLL enabled requires PMMCOREVx ≥ 2 for proper operation.

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Recommended Operating Conditions *(continued)*

			MIN	NOM	MAX	UNIT
C_{VCORE}	Capacitor at VCORE(4)			470		nF
C_{DVCC}/C_{VCORE}	Capacitor ratio of DVCC to VCORE		10			
f_{SYSTEM}	Processor frequency (maximum MCLK frequency)(5)(6) (see Figure 5-1)	PMMCOREVx = 0, 1.8 V ≤ V_{CC} ≤ 3.6 V (default condition)	0		8.0	MHz
		PMMCOREVx = 1, 2 V ≤ V_{CC} ≤ 3.6 V	0		12.0	
		PMMCOREVx = 2, 2.2 V ≤ V_{CC} ≤ 3.6 V	0		16.0	
		PMMCOREVx = 3, 2.4 V ≤ V_{CC} ≤ 3.6 V	0		20.0	
f_{SYSTEM_USB}	Minimum processor frequency for USB operation		1.5			MHz
USB_wait	Wait state cycles during USB operation			16		cycles

(4) A capacitor tolerance of ±20% or better is required.
(5) The MSP430 CPU is clocked directly with MCLK. Both the high and low phase of MCLK must not exceed the pulse duration of the specified maximum frequency.
(6) Modules may have a different maximum input clock specification. See the specification of the respective module in this data sheet.



NOTE: The numbers within the fields denote the supported PMMCOREVx settings.

Figure 5-1. Frequency vs Supply Voltage

5.4 Active Mode Supply Current Into V_{CC} Excluding External Current

over recommended operating free-air temperature (unless otherwise noted)(1)(2)(3)

PARAMETER	EXECUTION MEMORY	V_{CC}	PMMCOREVx	FREQUENCY ($f_{DCO} = f_{MCLK} = f_{SMCLK}$)								UNIT
				1 MHz		8 MHz		12 MHz		20 MHz		
				TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	
$I_{AM,\ Flash}$	Flash	3 V	0	0.32	0.36	2.1	2.4					mA
			1	0.36		2.4		3.6	4.0			
			2	0.37		2.5		3.8				
			3	0.39		2.7		4.0		6.6		
$I_{AM,\ RAM}$	RAM	3 V	0	0.18	0.21	1.0	1.2					mA
			1	0.20		1.2		1.7	1.9			
			2	0.22		1.3		2.0				
			3	0.23		1.4		2.1		3.6		

(1) All inputs are tied to 0 V or to V_{CC}. Outputs do not source or sink any current.
(2) The currents are characterized with a Micro Crystal MS1V-T1K crystal with a load capacitance of 12.5 pF. The internal and external load capacitance are chosen to closely match the required 12.5 pF.
(3) Characterized with program executing typical data processing. USB disabled (VUSBEN = 0, SLDOEN = 0).
f_{ACLK} = 32786 Hz, $f_{DCO} = f_{MCLK} = f_{SMCLK}$ at specified frequency.
XTS = CPUOFF = SCG0 = SCG1 = OSCOFF = SMCLKOFF = 0.

5.5 Low-Power Mode Supply Currents (Into V_{CC}) Excluding External Current

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1)(2)

PARAMETER		V_{CC}	PMMCOREVx	TEMPERATURE (T_A)								UNIT
				–40°C		25°C		60°C		85°C		
				TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	
$I_{LPM0,1MHz}$	Low-power mode 0(3)(4)	2.2 V	0	71		75	87	81		85	99	µA
		3 V	3	78		83	98	89		94	108	
I_{LPM2}	Low-power mode 2(5)(4)	2.2 V	0	6.3		6.7	9.9	9.0		11	16	µA
		3 V	3	6.6		7.0	11	10		12	18	
$I_{LPM3,XT1LF}$	Low-power mode 3, crystal mode(6)(4)	2.2 V	0	1.6		1.8	2.4	4.7		6.5	10.5	µA
			1	1.6		1.9		4.8		6.6		
			2	1.7		2.0		4.9		6.7		
		3 V	0	1.9		2.1	2.7	5.0		6.8	10.8	
			1	1.9		2.1		5.1		7.0		
			2	2.0		2.2		5.2		7.1		
			3	2.0		2.2	2.9	5.4		7.3	12.6	

(1) All inputs are tied to 0 V or to V_{CC}. Outputs do not source or sink any current.
(2) The currents are characterized with a Micro Crystal CC4V-T1A SMD crystal with a load capacitance of 9 pF. The internal and external load capacitance are chosen to closely match the required 9 pF.
(3) Current for watchdog timer clocked by SMCLK included. ACLK = low-frequency crystal operation (XTS = 0, XT1DRIVEx = 0).
CPUOFF = 1, SCG0 = 0, SCG1 = 0, OSCOFF = 0 (LPM0), f_{ACLK} = 32768 Hz, f_{MCLK} = 0 MHz, $f_{SMCLK} = f_{DCO}$ = 1 MHz
USB disabled (VUSBEN = 0, SLDOEN = 0).
(4) Current for brownout included. Low-side supervisor (SVS_L) and low-side monitor (SVM_L) disabled. High-side supervisor (SVS_H) and high-side monitor (SVM_H) disabled. RAM retention enabled.
(5) Current for watchdog timer clocked by ACLK and RTC clocked by LFXT1 (32768 Hz) included. ACLK = low-frequency crystal operation (XTS = 0, XT1DRIVEx = 0).
CPUOFF = 1, SCG0 = 0, SCG1 = 1, OSCOFF = 0 (LPM2), f_{ACLK} = 32768 Hz, f_{MCLK} = 0 MHz, $f_{SMCLK} = f_{DCO}$ = 0 MHz; DCO setting = 1 MHz operation, DCO bias generator enabled.
USB disabled (VUSBEN = 0, SLDOEN = 0).
(6) Current for watchdog timer clocked by ACLK and RTC clocked by LFXT1 (32768 Hz) included. ACLK = low-frequency crystal operation (XTS = 0, XT1DRIVEx = 0).
CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3), f_{ACLK} = 32768 Hz, $f_{MCLK} = f_{SMCLK} = f_{DCO}$ = 0 MHz
USB disabled (VUSBEN = 0, SLDOEN = 0).

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Low-Power Mode Supply Currents (Into V_{CC}) Excluding External Current *(continued)*

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)[1][2]

PARAMETER		V_{CC}	PMMCOREVx	TEMPERATURE (T_A)								UNIT
				–40°C		25°C		60°C		85°C		
				TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	
$I_{LPM3,VLO,WDT}$	Low-power mode 3, VLO mode, Watchdog enabled[7][4]	3 V	0	0.9		1.2	1.9	4.0		5.9	10.3	µA
			1	0.9		1.2		4.1		6.0		
			2	1.0		1.3		4.2		6.1		
			3	1.0		1.3	2.2	4.3		6.3	11.3	
I_{LPM4}	Low-power mode 4[8][4]	3 V	0	0.9		1.1	1.8	3.9		5.8	10	µA
			1	0.9		1.1		4.0		5.9		
			2	1.0		1.2		4.1		6.1		
			3	1.0		1.2	2.1	4.2		6.2	11	
$I_{LPM3.5,RTC,VCC}$	Low-power mode 3.5 (LPM3.5) current with active RTC into primary supply pin DV_{CC}[9]	3 V				0.5				0.8	1.4	µA
$I_{LPM3.5,RTC,VBAT}$	Low-power mode 3.5 (LPM3.5) current with active RTC into backup supply pin VBAT[10]	3 V				0.6				0.8	1.4	µA
$I_{LPM3.5,RTC,TOT}$	Total low-power mode 3.5 (LPM3.5) current with active RTC[11]	3 V		1.0		1.1		1.3		1.6	2.8	µA
$I_{LPM4.5}$	Low-power mode 4.5 (LPM4.5)[12]	3 V		0.2		0.3	0.6	0.7		0.9	1.4	µA

(7) Current for watchdog timer clocked by VLO included.
CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3), $f_{ACLK} = f_{MCLK} = f_{SMCLK} = f_{DCO} = 0$ MHz
USB disabled (VUSBEN = 0, SLDOEN = 0).
(8) CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 1 (LPM4), $f_{DCO} = f_{ACLK} = f_{MCLK} = f_{SMCLK} = 0$ MHz
USB disabled (VUSBEN = 0, SLDOEN = 0).
(9) $V_{VBAT} = V_{CC} – 0.2$ V, $f_{DCO} = f_{MCLK} = f_{SMCLK} = 0$ MHz, $f_{ACLK} = 32768$ Hz, PMMREGOFF = 1, RTC in backup domain active
(10) $V_{VBAT} = V_{CC} – 0.2$ V, $f_{DCO} = f_{MCLK} = f_{SMCLK} = 0$ MHz, $f_{ACLK} = 32768$ Hz, PMMREGOFF = 1, RTC in backup domain active, no current drawn on VBAK
(11) $f_{DCO} = f_{MCLK} = f_{SMCLK} = 0$ MHz, $f_{ACLK} = 32768$ Hz, PMMREGOFF = 1, RTC in backup domain active, no current drawn on VBAK
(12) Internal regulator disabled. No data retention.
CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 1, PMMREGOFF = 1 (LPM4.5), $f_{DCO} = f_{ACLK} = f_{MCLK} = f_{SMCLK} = 0$ MHz

5.6 Thermal Resistance Characteristics

PARAMETER			VALUE	UNIT
$R\theta_{JA}$	Junction-to-ambient thermal resistance, still air[1]	QFP (PZ)	122	°C/W
		BGA (ZQW)	108	
$R\theta_{JC(TOP)}$	Junction-to-case (top) thermal resistance[2]	QFP (PZ)	83	°C/W
		BGA (ZQW)	72	
$R\theta_{JB}$	Junction-to-board thermal resistance[3]	QFP (PZ)	98	°C/W
		BGA (ZQW)	76	

(1) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, High-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
(2) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
(3) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.

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5.7 Schmitt-Trigger Inputs – General-Purpose I/O[1]

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage		1.8 V	0.80		1.40	V
			3 V	1.50		2.10	
V_{IT-}	Negative-going input threshold voltage		1.8 V	0.45		1.00	V
			3 V	0.75		1.65	
V_{hys}	Input voltage hysteresis ($V_{IT+} - V_{IT-}$)		1.8 V	0.3		0.8	V
			3 V	0.4		1.0	
R_{Pull}	Pullup or pulldown resistor[2]	For pullup: $V_{IN} = V_{SS}$ For pulldown: $V_{IN} = V_{CC}$		20	35	50	kΩ
C_I	Input capacitance	$V_{IN} = V_{SS}$ or V_{CC}			5		pF

(1) Same parametrics apply to clock input pin when crystal bypass mode is used on XT1 (XIN) or XT2 (XT2IN).
(2) Also applies to $\overline{RST}$ pin when pullup or pulldown resistor is enabled.

5.8 Inputs – Ports P1, P2, P3, and P4[1]

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$t_{(int)}$	External interrupt timing[2]	Port P1, P2, P3, P4: P1.x to P4.x, External trigger pulse duration to set interrupt flag	2.2 V, 3 V	20		ns

(1) Some devices may contain additional ports with interrupts. See the block diagram and terminal function descriptions.
(2) An external signal sets the interrupt flag every time the minimum interrupt pulse duration $t_{(int)}$ is met. It may be set by trigger signals shorter than $t_{(int)}$.

5.9 Leakage Current – General-Purpose I/O

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$I_{lkg(Px.x)}$	High-impedance leakage current	See [1][2]	1.8 V, 3 V		±50	nA

(1) The leakage current is measured with V_{SS} or V_{CC} applied to the corresponding pins, unless otherwise noted.
(2) The leakage of the digital port pins is measured individually. The port pin is selected for input and the pullup or pulldown resistor is disabled.

5.10 Outputs – General-Purpose I/O (Full Drive Strength)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
V_{OH}	High-level output voltage	$I_{(OHmax)}$ = –3 mA[1]	1.8 V	V_{CC} – 0.25	V_{CC}	V
		$I_{(OHmax)}$ = –10 mA[2]		V_{CC} – 0.60	V_{CC}	
		$I_{(OHmax)}$ = –5 mA[1]	3 V	V_{CC} – 0.25	V_{CC}	
		$I_{(OHmax)}$ = –15 mA[2]		V_{CC} – 0.60	V_{CC}	
V_{OL}	Low-level output voltage	$I_{(OLmax)}$ = 3 mA[1]	1.8 V	V_{SS}	V_{SS} + 0.25	V
		$I_{(OLmax)}$ = 10 mA[2]		V_{SS}	V_{SS} + 0.60	
		$I_{(OLmax)}$ = 5 mA[1]	3 V	V_{SS}	V_{SS} + 0.25	
		$I_{(OLmax)}$ = 15 mA[2]		V_{SS}	V_{SS} + 0.60	

(1) The maximum total current, $I_{(OHmax)}$ and $I_{(OLmax)}$, for all outputs combined should not exceed ±48 mA to hold the maximum voltage drop specified.
(2) The maximum total current, $I_{(OHmax)}$ and $I_{(OLmax)}$, for all outputs combined should not exceed ±100 mA to hold the maximum voltage drop specified.

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5.11 Outputs – General-Purpose I/O (Reduced Drive Strength)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
V_{OH}	High-level output voltage	$I_{(OHmax)}$ = –1 mA(2)	1.8 V	V_{CC} – 0.25	V_{CC}	V
		$I_{(OHmax)}$ = –3 mA(3)		V_{CC} – 0.60	V_{CC}	
		$I_{(OHmax)}$ = –2 mA(2)	3 V	V_{CC} – 0.25	V_{CC}	
		$I_{(OHmax)}$ = –6 mA(3)		V_{CC} – 0.60	V_{CC}	
V_{OL}	Low-level output voltage	$I_{(OLmax)}$ = 1 mA(2)	1.8 V	V_{SS}	V_{SS} + 0.25	V
		$I_{(OLmax)}$ = 3 mA(3)		V_{SS}	V_{SS} + 0.60	
		$I_{(OLmax)}$ = 2 mA(2)	3 V	V_{SS}	V_{SS} + 0.25	
		$I_{(OLmax)}$ = 6 mA(3)		V_{SS}	V_{SS} + 0.60	

(1) Selecting reduced drive strength may reduce EMI.
(2) The maximum total current, $I_{(OHmax)}$ and $I_{(OLmax)}$, for all outputs combined, should not exceed ±48 mA to hold the maximum voltage drop specified.
(3) The maximum total current, $I_{(OHmax)}$ and $I_{(OLmax)}$, for all outputs combined, should not exceed ±100 mA to hold the maximum voltage drop specified.

5.12 Output Frequency – Ports P1, P2, and P3

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$f_{Px.y}$	Port output frequency (with load)	P3.4/TA2CLK/SMCLK/S27, C_L = 20 pF, R_L = 1 kΩ(1) or 3.2 kΩ(2)(3)	V_{CC} = 1.8 V, PMMCOREVx = 0		8	MHz
			V_{CC} = 3 V, PMMCOREVx = 3		20	
f_{Port_CLK}	Clock output frequency	P1.0/TA0CLK/ACLK/S39, P3.4/TA2CLK/SMCLK/S27, P2.0/P2MAP0 (P2MAP0 = PM_MCLK), C_L = 20 pF(3)	V_{CC} = 1.8 V, PMMCOREVx = 0		8	MHz
			V_{CC} = 3 V, PMMCOREVx = 3		20	

(1) Full drive strength of port: A resistive divider with 2 × 0.5 kΩ between V_{CC} and V_{SS} is used as load. The output is connected to the center tap of the divider.
(2) Reduced drive strength of port: A resistive divider with 2 × 1.6 kΩ between V_{CC} and V_{SS} is used as load. The output is connected to the center tap of the divider.
(3) The output voltage reaches at least 10% and 90% V_{CC} at the specified toggle frequency.

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5.13 Typical Characteristics – Outputs, Reduced Drive Strength (PxDS.y = 0)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

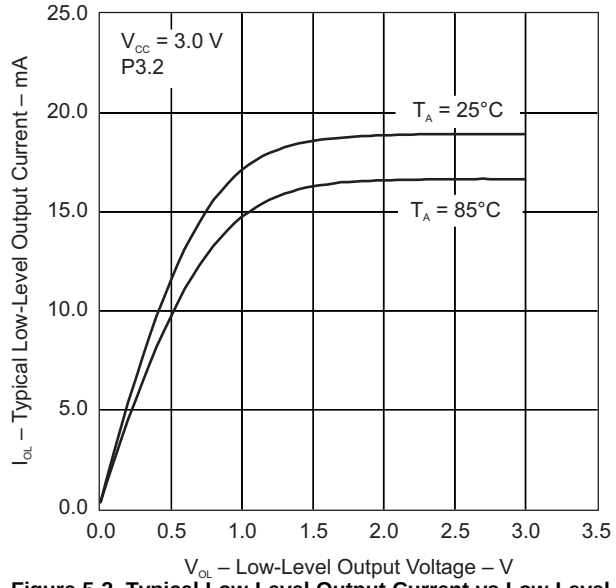


Figure 5-2. Typical Low-Level Output Current vs Low-Level Output Voltage

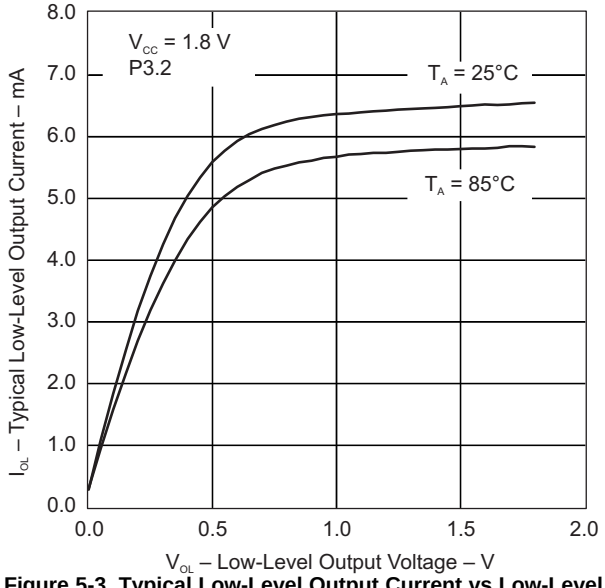


Figure 5-3. Typical Low-Level Output Current vs Low-Level Output Voltage

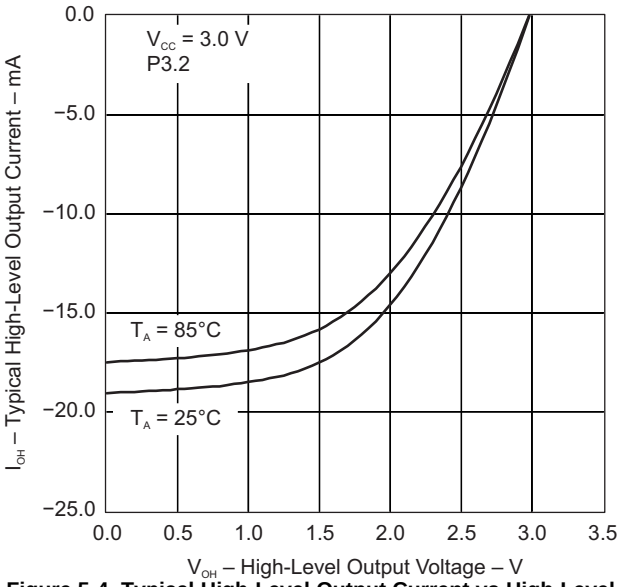


Figure 5-4. Typical High-Level Output Current vs High-Level Output Voltage

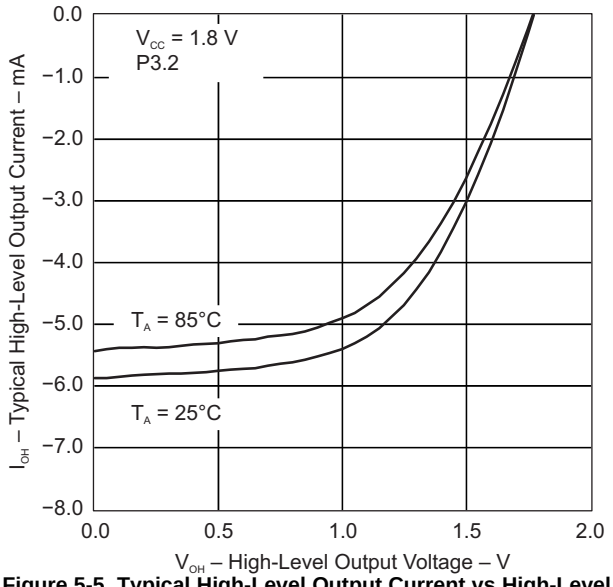


Figure 5-5. Typical High-Level Output Current vs High-Level Output Voltage

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5.14 Typical Characteristics – Outputs, Full Drive Strength (PxDS.y = 1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

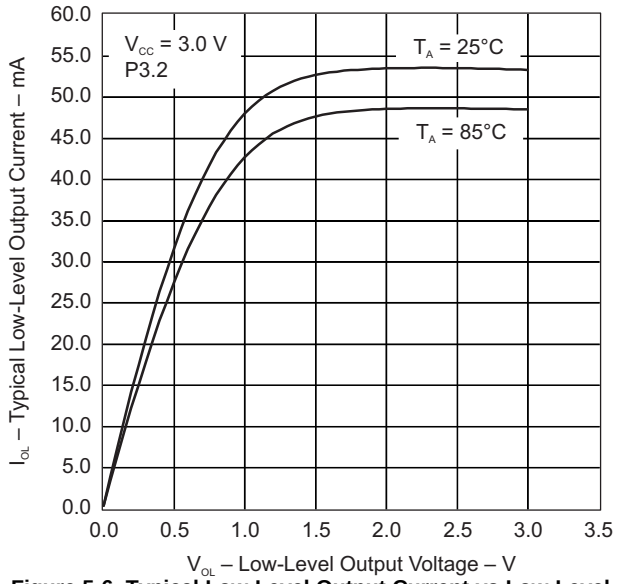


Figure 5-6. Typical Low-Level Output Current vs Low-Level Output Voltage

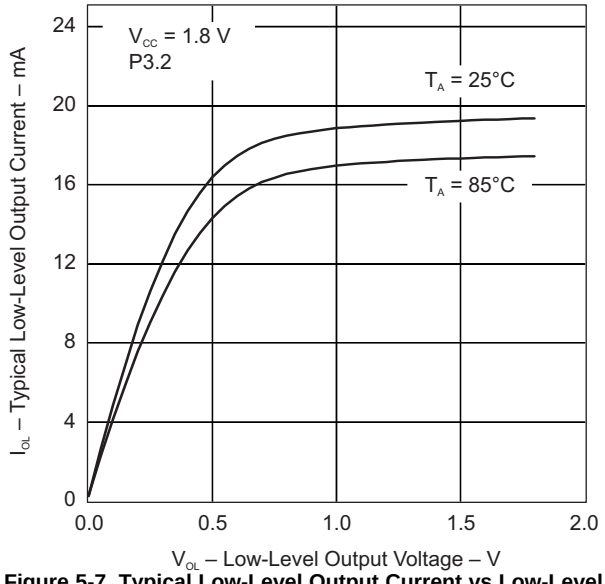


Figure 5-7. Typical Low-Level Output Current vs Low-Level Output Voltage

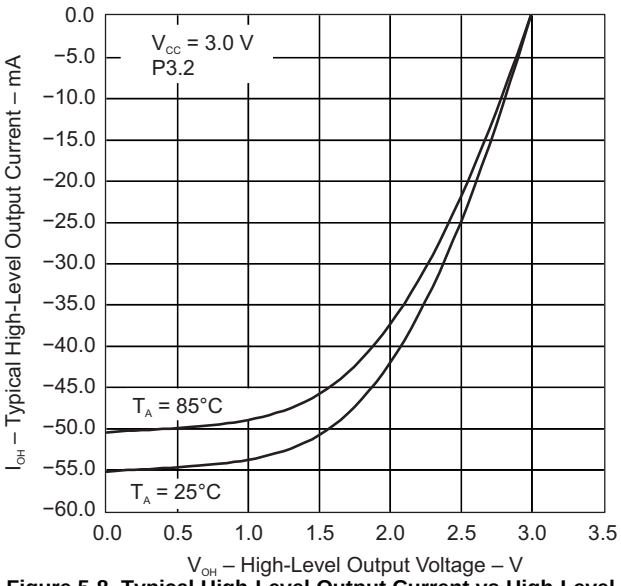


Figure 5-8. Typical High-Level Output Current vs High-Level Output Voltage

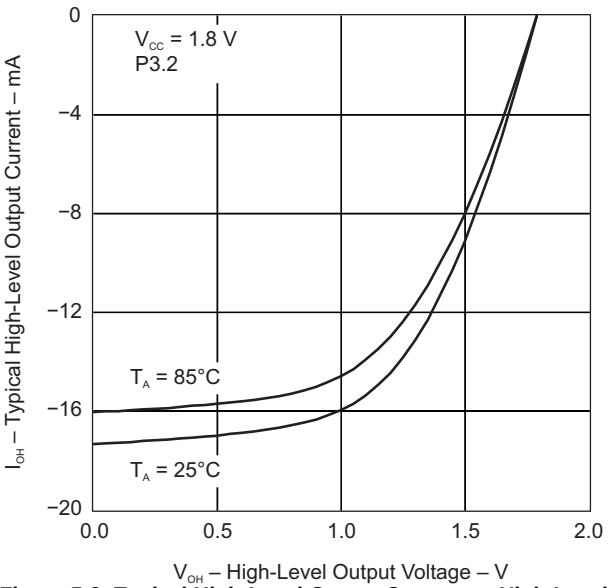


Figure 5-9. Typical High-Level Output Current vs High-Level Output Voltage

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5.15 Crystal Oscillator, XT1, Low-Frequency Mode(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$\Delta I_{DVCC,LF}$	Differential XT1 oscillator crystal current consumption from lowest drive setting, LF mode	f_{OSC} = 32768 Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 1, T_A = 25°C	3 V		0.075		µA
		f_{OSC} = 32768 Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 2, T_A = 25°C			0.170		
		f_{OSC} = 32768 Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 3, T_A = 25°C			0.290		
$f_{XT1,LF0}$	XT1 oscillator crystal frequency, LF mode	XTS = 0, XT1BYPASS = 0			32768		Hz
$f_{XT1,LF,SW}$	XT1 oscillator logic-level square-wave input frequency, LF mode	XTS = 0, XT1BYPASS = 1(2) (3)		10	32.768	50	kHz
OA_{LF}	Oscillation allowance for LF crystals(4)	XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 0, $f_{XT1,LF}$ = 32768 Hz, $C_{L,eff}$ = 6 pF			210		kΩ
		XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 1, $f_{XT1,LF}$ = 32768 Hz, $C_{L,eff}$ = 12 pF			300		
$C_{L,eff}$	Integrated effective load capacitance, LF mode(5)	XTS = 0, XCAPx = 0(6)			1		pF
		XTS = 0, XCAPx = 1			5.5		
		XTS = 0, XCAPx = 2			8.5		
		XTS = 0, XCAPx = 3			12.0		
	Duty cycle, LF mode	XTS = 0, Measured at ACLK, $f_{XT1,LF}$ = 32768 Hz		30%		70%	
$f_{Fault,LF}$	Oscillator fault frequency, LF mode(7)	XTS = 0(8)		10		10000	Hz
$t_{START,LF}$	Start-up time, LF mode	f_{OSC} = 32768 Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 0, T_A = 25°C, $C_{L,eff}$ = 6 pF	3 V		1000		ms
		f_{OSC} = 32768 Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVEx = 3, T_A = 25°C, $C_{L,eff}$ = 12 pF			500		

(1) To improve EMI on the XT1 oscillator, the following guidelines should be observed.
- Keep the trace between the device and the crystal as short as possible.
- Design a good ground plane around the oscillator pins.
- Prevent crosstalk from other clock or data lines into oscillator pins XIN and XOUT.
- Avoid running PCB traces underneath or adjacent to the XIN and XOUT pins.
- Use assembly materials and processes that avoid any parasitic load on the oscillator XIN and XOUT pins.
- If conformal coating is used, make sure that it does not induce capacitive or resistive leakage between the oscillator pins.

(2) When XT1BYPASS is set, XT1 circuit is automatically powered down. Input signal is a digital square wave with parametrics defined in the Schmitt-trigger Inputs section of this datasheet.

(3) Maximum frequency of operation of the entire device cannot be exceeded.

(4) Oscillation allowance is based on a safety factor of 5 for recommended crystals. The oscillation allowance is a function of the XT1DRIVEx settings and the effective load. In general, comparable oscillator allowance can be achieved based on the following guidelines, but should be evaluated based on the actual crystal selected for the application:
- For XT1DRIVEx = 0, $C_{L,eff} \le 6$ pF.
- For XT1DRIVEx = 1, 6 pF $\le C_{L,eff} \le 9$ pF.
- For XT1DRIVEx = 2, 6 pF $\le C_{L,eff} \le 10$ pF.
- For XT1DRIVEx = 3, $C_{L,eff} \ge 6$ pF.

(5) Includes parasitic bond and package capacitance (approximately 2 pF per pin). Because the PCB adds additional capacitance, TI recommends verifying the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.

(6) Requires external capacitors at both terminals. Values are specified by crystal manufacturers.

(7) Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies in between might set the flag.

(8) Measured with logic-level input frequency but also applies to operation with crystals.

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5.16 Crystal Oscillator, XT2

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1) (2)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$I_{DVCC,XT2}$	XT2 oscillator crystal current consumption	f_{OSC} = 4 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVEx = 0, T_A = 25°C	3 V		200		µA
		f_{OSC} = 12 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVEx = 1, T_A = 25°C			260		
		f_{OSC} = 20 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVEx = 2, T_A = 25°C			325		
		f_{OSC} = 32 MHz, XT2OFF = 0, XT2BYPASS = 0, XT2DRIVEx = 3, T_A = 25°C			450		
$f_{XT2,HF0}$	XT2 oscillator crystal frequency, mode 0	XT2DRIVEx = 0, XT2BYPASS = 0(3)		4		8	MHz
$f_{XT2,HF1}$	XT2 oscillator crystal frequency, mode 1	XT2DRIVEx = 1, XT2BYPASS = 0(3)		8		16	MHz
$f_{XT2,HF2}$	XT2 oscillator crystal frequency, mode 2	XT2DRIVEx = 2, XT2BYPASS = 0(3)		16		24	MHz
$f_{XT2,HF3}$	XT2 oscillator crystal frequency, mode 3	XT2DRIVEx = 3, XT2BYPASS = 0(3)		24		32	MHz
$f_{XT2,HF,SW}$	XT2 oscillator logic-level square-wave input frequency	XT2BYPASS = 1(4) (3)		0.7		32	MHz
OA_{HF}	Oscillation allowance for HF crystals(5)	XT2DRIVEx = 0, XT2BYPASS = 0, $f_{XT2,HF0}$ = 6 MHz, $C_{L,eff}$ = 15 pF			450		Ω
		XT2DRIVEx = 1, XT2BYPASS = 0, $f_{XT2,HF1}$ = 12 MHz, $C_{L,eff}$ = 15 pF			320		
		XT2DRIVEx = 2, XT2BYPASS = 0, $f_{XT2,HF2}$ = 20 MHz, $C_{L,eff}$ = 15 pF			200		
		XT2DRIVEx = 3, XT2BYPASS = 0, $f_{XT2,HF3}$ = 32 MHz, $C_{L,eff}$ = 15 pF			200		
$t_{START,HF}$	Start-up time	f_{OSC} = 6 MHz XT2BYPASS = 0, XT2DRIVEx = 0, T_A = 25°C, $C_{L,eff}$ = 15 pF	3 V		0.5		ms
		f_{OSC} = 20 MHz XT2BYPASS = 0, XT2DRIVEx = 3, T_A = 25°C, $C_{L,eff}$ = 15 pF			0.3		
$C_{L,eff}$	Integrated effective load capacitance, HF mode(6) (1)				1		pF
	Duty cycle	Measured at ACLK, $f_{XT2,HF2}$ = 20 MHz		40%	50%	60%	
$f_{Fault,HF}$	Oscillator fault frequency(7)	XT2BYPASS = 1(8)		30		300	kHz

(1) Requires external capacitors at both terminals. Values are specified by crystal manufacturers.
(2) To improve EMI on the XT2 oscillator the following guidelines should be observed.
- Keep the traces between the device and the crystal as short as possible.
- Design a good ground plane around the oscillator pins.
- Prevent crosstalk from other clock or data lines into oscillator pins XT2IN and XT2OUT.
- Avoid running PCB traces underneath or adjacent to the XT2IN and XT2OUT pins.
- Use assembly materials and processes that avoid any parasitic load on the oscillator XT2IN and XT2OUT pins.
- If conformal coating is used, make sure that it does not induce capacitive or resistive leakage between the oscillator pins.

(3) Maximum frequency of operation of the entire device cannot be exceeded.
(4) When XT2BYPASS is set, the XT2 circuit is automatically powered down.
(5) Oscillation allowance is based on a safety factor of 5 for recommended crystals.
(6) Includes parasitic bond and package capacitance (approximately 2 pF per pin). Because the PCB adds additional capacitance, TI recommends verifying the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.
(7) Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies between the MIN and MAX specifications might set the flag.
(8) Measured with logic-level input frequency but also applies to operation with crystals.

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5.17 Internal Very-Low-Power Low-Frequency Oscillator (VLO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
f_{VLO}	VLO frequency	Measured at ACLK	1.8 V to 3.6 V	6	9.4	14	kHz
df_{VLO}/d_T	VLO frequency temperature drift	Measured at ACLK (1)	1.8 V to 3.6 V		0.5		%/°C
df_{VLO}/dV_{CC}	VLO frequency supply voltage drift	Measured at ACLK (2)	1.8 V to 3.6 V		4		%/V
	Duty cycle	Measured at ACLK	1.8 V to 3.6 V	40%	50%	60%	

(1) Calculated using the box method: (MAX(–40°C to +85°C) – MIN(–40°C to +85°C)) / MIN(–40°C to +85°C) / (85°C – (–40°C))
(2) Calculated using the box method: (MAX(1.8 V to 3.6 V) – MIN(1.8 V to 3.6 V)) / MIN(1.8 V to 3.6 V) / (3.6 V – 1.8 V)

5.18 Internal Reference, Low-Frequency Oscillator (REFO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
I_{REFO}	REFO oscillator current consumption	T_A = 25°C	1.8 V to 3.6 V		3		µA
f_{REFO}	REFO frequency calibrated	Measured at ACLK	1.8 V to 3.6 V		32768		Hz
	REFO absolute tolerance calibrated	Full temperature range	1.8 V to 3.6 V			±3.5%	
		T_A = 25°C	3 V			±1.5%	
df_{REFO}/d_T	REFO frequency temperature drift	Measured at ACLK (1)	1.8 V to 3.6 V		0.01		%/°C
df_{REFO}/dV_{CC}	REFO frequency supply voltage drift	Measured at ACLK (2)	1.8 V to 3.6 V		1.0		%/V
	Duty cycle	Measured at ACLK	1.8 V to 3.6 V	40%	50%	60%	
t_{START}	REFO start-up time	40%/60% duty cycle	1.8 V to 3.6 V		25		µs

(1) Calculated using the box method: (MAX(–40°C to +85°C) – MIN(–40°C to +85°C)) / MIN(–40°C to +85°C) / (85°C – (–40°C))
(2) Calculated using the box method: (MAX(1.8 V to 3.6 V) – MIN(1.8 V to 3.6 V)) / MIN(1.8 V to 3.6 V) / (3.6 V – 1.8 V)

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5.19 DCO Frequency

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{DCO(0,0)}$	DCO frequency (0, 0)	DCORSELx = 0, DCOx = 0, MODx = 0	0.07		0.20	MHz
$f_{DCO(0,31)}$	DCO frequency (0, 31)	DCORSELx = 0, DCOx = 31, MODx = 0	0.70		1.70	MHz
$f_{DCO(1,0)}$	DCO frequency (1, 0)	DCORSELx = 1, DCOx = 0, MODx = 0	0.15		0.36	MHz
$f_{DCO(1,31)}$	DCO frequency (1, 31)	DCORSELx = 1, DCOx = 31, MODx = 0	1.47		3.45	MHz
$f_{DCO(2,0)}$	DCO frequency (2, 0)	DCORSELx = 2, DCOx = 0, MODx = 0	0.32		0.75	MHz
$f_{DCO(2,31)}$	DCO frequency (2, 31)	DCORSELx = 2, DCOx = 31, MODx = 0	3.17		7.38	MHz
$f_{DCO(3,0)}$	DCO frequency (3, 0)	DCORSELx = 3, DCOx = 0, MODx = 0	0.64		1.51	MHz
$f_{DCO(3,31)}$	DCO frequency (3, 31)	DCORSELx = 3, DCOx = 31, MODx = 0	6.07		14.0	MHz
$f_{DCO(4,0)}$	DCO frequency (4, 0)	DCORSELx = 4, DCOx = 0, MODx = 0	1.3		3.2	MHz
$f_{DCO(4,31)}$	DCO frequency (4, 31)	DCORSELx = 4, DCOx = 31, MODx = 0	12.3		28.2	MHz
$f_{DCO(5,0)}$	DCO frequency (5, 0)	DCORSELx = 5, DCOx = 0, MODx = 0	2.5		6.0	MHz
$f_{DCO(5,31)}$	DCO frequency (5, 31)	DCORSELx = 5, DCOx = 31, MODx = 0	23.7		54.1	MHz
$f_{DCO(6,0)}$	DCO frequency (6, 0)	DCORSELx = 6, DCOx = 0, MODx = 0	4.6		10.7	MHz
$f_{DCO(6,31)}$	DCO frequency (6, 31)	DCORSELx = 6, DCOx = 31, MODx = 0	39.0		88.0	MHz
$f_{DCO(7,0)}$	DCO frequency (7, 0)	DCORSELx = 7, DCOx = 0, MODx = 0	8.5		19.6	MHz
$f_{DCO(7,31)}$	DCO frequency (7, 31)	DCORSELx = 7, DCOx = 31, MODx = 0	60		135	MHz
$S_{DCORSEL}$	Frequency step between range DCORSEL and DCORSEL + 1	$S_{RSEL} = f_{DCO(DCORSEL+1,DCO)}/f_{DCO(DCORSEL,DCO)}$	1.2		2.3	ratio
S_{DCO}	Frequency step between tap DCO and DCO + 1	$S_{DCO} = f_{DCO(DCORSEL,DCO+1)}/f_{DCO(DCORSEL,DCO)}$	1.02		1.12	ratio
	Duty cycle	Measured at SMCLK	40%	50%	60%	
df_{DCO}/dT	DCO frequency temperature drift	f_{DCO} = 1 MHz		0.1		%/°C
df_{DCO}/dV_{CC}	DCO frequency voltage drift	f_{DCO} = 1 MHz		1.9		%/V

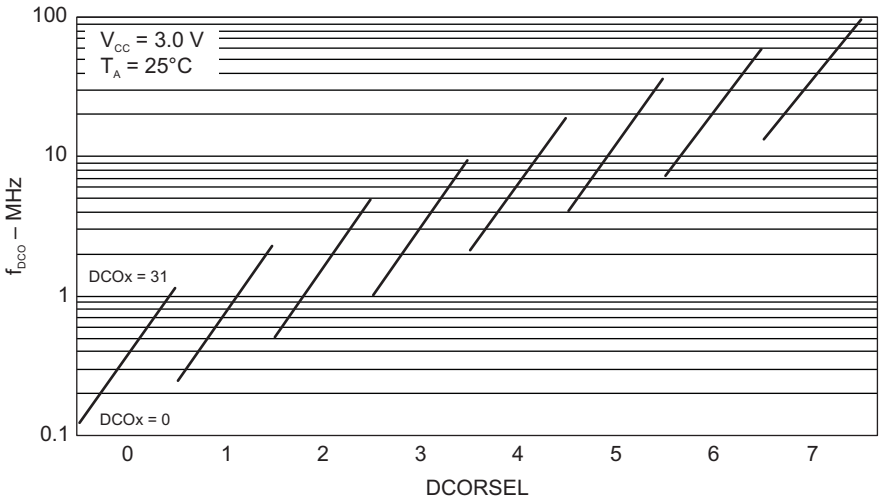


Figure 5-10. Typical DCO Frequency

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5.20 PMM, Brownout Reset (BOR)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{(DVCC_BOR_IT-)}$	BOR_H on voltage, DV_{CC} falling level	$\lvert dDV_{CC}/d_t \rvert$ < 3 V/s			1.45	V
$V_{(DVCC_BOR_IT+)}$	BOR_H off voltage, DV_{CC} rising level	$\lvert dDV_{CC}/d_t \rvert$ < 3 V/s	0.80	1.30	1.50	V
$V_{(DVCC_BOR_hys)}$	BOR_H hysteresis		50		250	mV
t_{RESET}	Pulse duration required at $\overline{RST}$/NMI pin to accept a reset		2			µs

5.21 PMM, Core Voltage

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{CORE3}(AM)	Core voltage, active mode, PMMCOREV = 3	2.4 V ≤ DV_{CC} ≤ 3.6 V, 0 mA ≤ I(V_{CORE}) ≤ 21 mA		1.90		V
V_{CORE2}(AM)	Core voltage, active mode, PMMCOREV = 2	2.2 V ≤ DV_{CC} ≤ 3.6 V, 0 mA ≤ I(V_{CORE}) ≤ 21 mA		1.80		V
V_{CORE1}(AM)	Core voltage, active mode, PMMCOREV = 1	2 V ≤ DV_{CC} ≤ 3.6 V, 0 mA ≤ I(V_{CORE}) ≤ 17 mA		1.60		V
V_{CORE0}(AM)	Core voltage, active mode, PMMCOREV = 0	1.8 V ≤ DV_{CC} ≤ 3.6 V, 0 mA ≤ I(V_{CORE}) ≤ 13 mA		1.40		V
V_{CORE3}(LPM)	Core voltage, low-current mode, PMMCOREV = 3	2.4 V ≤ DV_{CC} ≤ 3.6 V, 0 µA ≤ I(V_{CORE}) ≤ 30 µA		1.94		V
V_{CORE2}(LPM)	Core voltage, low-current mode, PMMCOREV = 2	2.2 V ≤ DV_{CC} ≤ 3.6 V, 0 µA ≤ I(V_{CORE}) ≤ 30 µA		1.84		V
V_{CORE1}(LPM)	Core voltage, low-current mode, PMMCOREV = 1	2 V ≤ DV_{CC} ≤ 3.6 V, 0 µA ≤ I(V_{CORE}) ≤ 30 µA		1.64		V
V_{CORE0}(LPM)	Core voltage, low-current mode, PMMCOREV = 0	1.8 V ≤ DV_{CC} ≤ 3.6 V, 0 µA ≤ I(V_{CORE}) ≤ 30 µA		1.44		V

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5.22 PMM, SVS High Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVSH)}$	SVS current consumption	SVSHE = 0, DV_{CC} = 3.6 V		0		nA
		SVSHE = 1, DV_{CC} = 3.6 V, SVSHFP = 0		200		
		SVSHE = 1, DV_{CC} = 3.6 V, SVSHFP = 1		2.0		µA
$V_{(SVSH_IT-)}$	SVS_H on voltage level(1)	SVSHE = 1, SVSHRVL = 0	1.59	1.64	1.69	V
		SVSHE = 1, SVSHRVL = 1	1.79	1.84	1.91	
		SVSHE = 1, SVSHRVL = 2	1.98	2.04	2.11	
		SVSHE = 1, SVSHRVL = 3	2.10	2.16	2.23	
$V_{(SVSH_IT+)}$	SVS_H off voltage level(1)	SVSHE = 1, SVSMHRRL = 0	1.62	1.74	1.81	V
		SVSHE = 1, SVSMHRRL = 1	1.88	1.94	2.01	
		SVSHE = 1, SVSMHRRL = 2	2.07	2.14	2.21	
		SVSHE = 1, SVSMHRRL = 3	2.20	2.26	2.33	
		SVSHE = 1, SVSMHRRL = 4	2.32	2.40	2.48	
		SVSHE = 1, SVSMHRRL = 5	2.56	2.70	2.84	
		SVSHE = 1, SVSMHRRL = 6	2.85	3.00	3.15	
		SVSHE = 1, SVSMHRRL = 7	2.85	3.00	3.15	
$t_{pd(SVSH)}$	SVS_H propagation delay	SVSHE = 1, dV_{DVCC}/dt = 10 mV/µs, SVSHFP = 1		2.5		µs
		SVSHE = 1, dV_{DVCC}/dt = 1 mV/µs, SVSHFP = 0		20		
$t_{(SVSH)}$	SVS_H on or off delay time	SVSHE = 0→1, SVSHFP = 1		12.5		µs
		SVSHE = 0→1, SVSHFP = 0		100		
dV_{DVCC}/dt	DV_{CC} rise time		0		1000	V/s

(1) The SVS_H settings available depend on the VCORE (PMMCOREVx) setting. See the *Power Management Module and Supply Voltage Supervisor* chapter in the *MSP430x5xx and MSP430x6xx Family User's Guide* on recommended settings and usage.

5.23 PMM, SVM High Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVMH)}$	SVM_H current consumption	SVMHE = 0, DVCC = 3.6 V		0		nA
		SVMHE = 1, DVCC = 3.6 V, SVMHFP = 0		200		
		SVMHE = 1, DVCC = 3.6 V, SVMHFP = 1		2.0		µA
$V_{(SVMH)}$	SVM_H on or off voltage level(1)	SVMHE = 1, SVSMHRRL = 0	1.65	1.74	1.86	V
		SVMHE = 1, SVSMHRRL = 1	1.85	1.94	2.02	
		SVMHE = 1, SVSMHRRL = 2	2.02	2.14	2.22	
		SVMHE = 1, SVSMHRRL = 3	2.18	2.26	2.35	
		SVMHE = 1, SVSMHRRL = 4	2.32	2.40	2.48	
		SVMHE = 1, SVSMHRRL = 5	2.56	2.70	2.84	
		SVMHE = 1, SVSMHRRL = 6	2.85	3.00	3.15	
		SVMHE = 1, SVSMHRRL = 7	2.85	3.00	3.15	
		SVMHE = 1, SVMHOVPE = 1		3.75		
$t_{pd(SVMH)}$	SVM_H propagation delay	SVMHE = 1, dV_{DVCC}/dt = 10 mV/µs, SVMHFP = 1		2.5		µs
		SVMHE = 1, dV_{DVCC}/dt = 1 mV/µs, SVMHFP = 0		20		
$t_{(SVMH)}$	SVM_H on or off delay time	SVMHE = 0→1, SVSMFP = 1		12.5		µs
		SVMHE = 0→1, SVMHFP = 0		100		

(1) The SVM_H settings available depend on the VCORE (PMMCOREVx) setting. See the *Power Management Module and Supply Voltage Supervisor* chapter in the *MSP430x5xx and MSP430x6xx Family User's Guide* on recommended settings and usage.

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5.24 PMM, SVS Low Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVSL)}$	SVS_L current consumption	SVSLE = 0, PMMCOREV = 2		0		nA
		SVSLE = 1, PMMCOREV = 2, SVSLFP = 0		200		
		SVSLE = 1, PMMCOREV = 2, SVSLFP = 1		2.0		µA
$t_{pd(SVSL)}$	SVS_L propagation delay	SVSLE = 1, dV_{CORE}/dt = 10 mV/µs, SVSLFP = 1		2.5		µs
		SVSLE = 1, dV_{CORE}/dt = 1 mV/µs, SVSLFP = 0		20		
$t_{(SVSL)}$	SVS_L on or off delay time	SVSLE = 0→1, SVSLFP = 1		12.5		µs
		SVSLE = 0→1, SVSLFP = 0		100		

5.25 PMM, SVM Low Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(SVML)}$	SVM_L current consumption	SVMLE = 0, PMMCOREV = 2		0		nA
		SVMLE = 1, PMMCOREV = 2, SVMLFP = 0		200		
		SVMLE = 1, PMMCOREV = 2, SVMLFP = 1		2.0		µA
$t_{pd(SVML)}$	SVM_L propagation delay	SVMLE = 1, dV_{CORE}/dt = 10 mV/µs, SVMLFP = 1		2.5		µs
		SVMLE = 1, dV_{CORE}/dt = 1 mV/µs, SVMLFP = 0		20		
$t_{(SVML)}$	SVM_L on or off delay time	SVMLE = 0→1, SVMLFP = 1		12.5		µs
		SVMLE = 0→1, SVMLFP = 0		100		

5.26 Wake-up Times From Low-Power Modes and Reset

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{WAKE-UP-FAST}$	Wake-up time from LPM2, LPM3, or LPM4 to active mode(1)	PMMCOREV = SVSMLRRL = n (where n = 0, 1, 2, or 3), SVSLFP = 1	f_{MCLK} ≥ 4 MHz		3	6.5	µs
			1 MHz < f_{MCLK} < 4 MHz		4	8.0	
$t_{WAKE-UP-SLOW}$	Wake-up time from LPM2, LPM3, or LPM4 to active mode(2)(3)	PMMCOREV = SVSMLRRL = n (where n = 0, 1, 2, or 3), SVSLFP = 0			150	165	µs
$t_{WAKE-UP-LPM5}$	Wake-up time from LPM3.5 or LPM4.5 to active mode(4)				2	3	ms
$t_{WAKE-UP-RESET}$	Wake-up time from $\overline{RST}$ or BOR event to active mode(4)				2	3	ms

(1) This value represents the time from the wake-up event to the first active edge of MCLK. The wake-up time depends on the performance mode of the low-side supervisor (SVS_L) and low-side monitor (SVM_L). $t_{WAKE-UP-FAST}$ is possible with SVS_L and SVM_L in full performance mode or disabled. For specific register settings, see the *Low-Side SVS and SVM Control and Performance Mode Selection* section in the *Power Management Module and Supply Voltage Supervisor* chapter of the *MSP430x5xx and MSP430x6xx Family User's Guide*.

(2) This value represents the time from the wake-up event to the first active edge of MCLK. The wake-up time depends on the performance mode of the low-side supervisor (SVS_L) and low-side monitor (SVM_L). $t_{WAKE-UP-SLOW}$ is set with SVS_L and SVM_L in normal mode (low current mode). For specific register settings, see the *Low-Side SVS and SVM Control and Performance Mode Selection* section in the *Power Management Module and Supply Voltage Supervisor* chapter of the *MSP430x5xx and MSP430x6xx Family User's Guide*.

(3) The wake-up times from LPM0 and LPM1 to AM are not specified. They are proportional to MCLK cycle time but are not affected by the performance mode settings as for LPM2, LPM3, and LPM4.

(4) This value represents the time from the wake-up event to the reset vector execution.

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5.27 Timer_A, Timers TA0, TA1, and TA2

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{TA}	Timer_A input clock frequency	Internal: SMCLK or ACLK, External: TACLK, Duty cycle = 50% ±10%	1.8 V, 3 V		20	MHz
$t_{TA,cap}$	Timer_A capture timing	All capture inputs, Minimum pulse duration required for capture	1.8 V, 3 V	20		ns

5.28 Timer_B, Timer TB0

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{TB}	Timer_B input clock frequency	Internal: SMCLK or ACLK, External: TBCLK, Duty cycle = 50% ±10%	1.8 V, 3 V		20	MHz
$t_{TB,cap}$	Timer_B capture timing	All capture inputs, Minimum pulse duration required for capture	1.8 V, 3 V	20		ns

5.29 Battery Backup

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
I_{VBAT}	Current into VBAT terminal if no primary battery is connected	VBAT = 1.7 V, DVCC not connected, RTC running	T_A = –40°C			0.43		µA
			T_A = 25°C			0.52		
			T_A = 60°C			0.58		
			T_A = 85°C			0.64		
		VBAT = 2.2 V, DVCC not connected, RTC running	T_A = –40°C			0.50		
			T_A = 25°C			0.59		
			T_A = 60°C			0.64		
			T_A = 85°C			0.71		
		VBAT = 3 V, DVCC not connected, RTC running	T_A = –40°C			0.68		
			T_A = 25°C			0.75		
			T_A = 60°C			0.79		
			T_A = 85°C			0.86		
V_{SWITCH}	Switch-over level (V_{CC} to VBAT)	C_{VCC} = 4.7 µF	General			V_{SVSH_IT-}		V
			SVSHRL = 0		1.59		1.69	
			SVSHRL = 1		1.79		1.91	
			SVSHRL = 2		1.98		2.11	
			SVSHRL = 3		2.10		2.23	
R_{ON_VBAT}	ON-resistance of switch between VBAT and VBAK	V_{BAT} = 1.8 V		0 V		0.35	1	kΩ
V_{BAT3}	VBAT to ADC input channel 12: V_{BAT} divided, $V_{BAT3} = V_{BAT}/3$			1.8 V		0.6	±5%	V
				3 V		1.0	±5%	
				3.6 V		1.2	±5%	
$t_{Sample,\ VBAT3}$	VBAT to ADC: Sampling time required if VBAT3 selected	ADC12ON = 1, Error of conversion result ≤ 1 LSB			1000			ns
V_{CHVx}	Charger end voltage	CHVx = 2			2.65	2.7	2.9	V
R_{CHARGE}	Charge limiting resistor	CHCx = 1					5	kΩ
		CHCx = 2					10	
		CHCx = 3					20	

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5.30 USCI (UART Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{USCI}	USCI input clock frequency	Internal: SMCLK or ACLK, External: UCLK, Duty cycle = 50% ±10%			f_{SYSTEM}	MHz
f_{BITCLK}	BITCLK clock frequency (equals baud rate in MBaud)				1	MHz
t_τ	UART receive deglitch time(1)		2.2 V	50	600	ns
			3 V	50	600	

(1) Pulses on the UART receive input (UCxRX) shorter than the UART receive deglitch time are suppressed. To ensure that pulses are correctly recognized their width should exceed the maximum specification of the deglitch time.

5.31 USCI (SPI Master Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1)
(see Figure 5-11 and Figure 5-12)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{USCI}	USCI input clock frequency	SMCLK or ACLK, Duty cycle = 50% ±10%			f_{SYSTEM}	MHz
$t_{SU,MI}$	SOMI input data setup time	PMMCOREV = 0	1.8 V	55		ns
			3 V	38		
		PMMCOREV = 3	2.4 V	30		
			3 V	25		
$t_{HD,MI}$	SOMI input data hold time	PMMCOREV = 0	1.8 V	0		ns
			3 V	0		
		PMMCOREV = 3	2.4 V	0		
			3 V	0		
$t_{VALID,MO}$	SIMO output data valid time(2)	UCLK edge to SIMO valid, C_L = 20 pF, PMMCOREV = 0	1.8 V		20	ns
			3 V		18	
		UCLK edge to SIMO valid, C_L = 20 pF, PMMCOREV = 3	2.4 V		16	
			3 V		15	
$t_{HD,MO}$	SIMO output data hold time(3)	C_L = 20 pF, PMMCOREV = 0	1.8 V	–10		ns
			3 V	–8		
		C_L = 20 pF, PMMCOREV = 3	2.4 V	–10		
			3 V	–8		

(1) $f_{UCxCLK} = 1/2t_{LO/HI}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(USCI)} + t_{SU,SI(Slave)}, t_{SU,MI(USCI)} + t_{VALID,SO(Slave)})$
For the slave parameters $t_{SU,SI(Slave)}$ and $t_{VALID,SO(Slave)}$, see the SPI parameters of the attached slave.
(2) Specifies the time to drive the next valid data to the SIMO output after the output changing UCLK clock edge. See the timing diagrams in Figure 5-11 and Figure 5-12.
(3) Specifies how long data on the SIMO output is valid after the output changing UCLK clock edge. Negative values indicate that the data on the SIMO output can become invalid before the output changing clock edge observed on UCLK. See the timing diagrams in Figure 5-11 and Figure 5-12.

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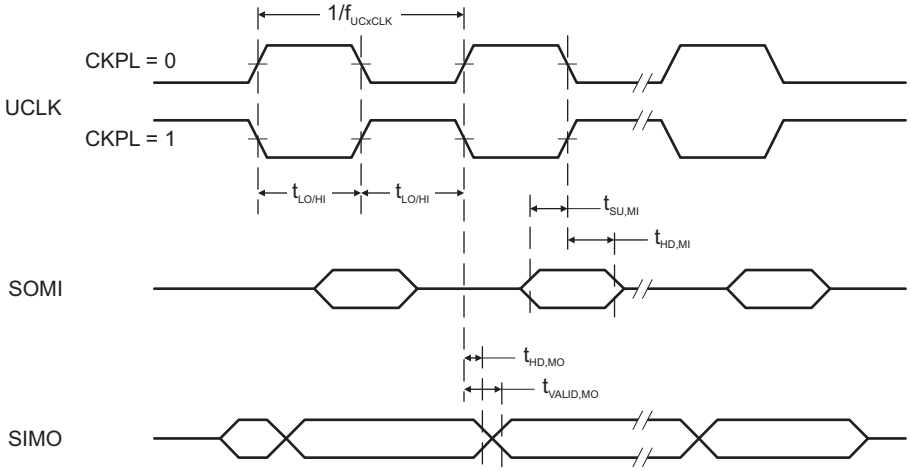


Figure 5-11. SPI Master Mode, CKPH = 0

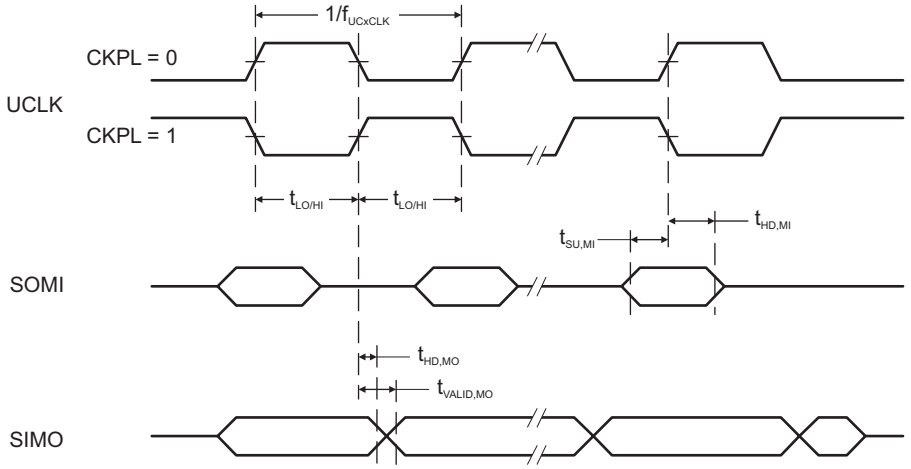


Figure 5-12. SPI Master Mode, CKPH = 1

5.32 USCI (SPI Slave Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)[1]
(see Figure 5-13 and Figure 5-14)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$t_{STE,LEAD}$	STE lead time, STE low to clock	PMMCOREV = 0	1.8 V	11		ns
			3 V	8		
		PMMCOREV = 3	2.4 V	7		
			3 V	6		
$t_{STE,LAG}$	STE lag time, Last clock to STE high	PMMCOREV = 0	1.8 V	3		ns
			3 V	3		
		PMMCOREV = 3	2.4 V	3		
			3 V	3		
$t_{STE,ACC}$	STE access time, STE low to SOMI data out	PMMCOREV = 0	1.8 V		66	ns
			3 V		50	
		PMMCOREV = 3	2.4 V		36	
			3 V		30	
$t_{STE,DIS}$	STE disable time, STE high to SOMI high impedance	PMMCOREV = 0	1.8 V		30	ns
			3 V		23	
		PMMCOREV = 3	2.4 V		16	
			3 V		13	
$t_{SU,SI}$	SIMO input data setup time	PMMCOREV = 0	1.8 V	5		ns
			3 V	5		
		PMMCOREV = 3	2.4 V	2		
			3 V	2		
$t_{HD,SI}$	SIMO input data hold time	PMMCOREV = 0	1.8 V	5		ns
			3 V	5		
		PMMCOREV = 3	2.4 V	5		
			3 V	5		
$t_{VALID,SO}$	SOMI output data valid time[2]	UCLK edge to SOMI valid, C_L = 20 pF, PMMCOREV = 0	1.8 V		76	ns
			3 V		60	
		UCLK edge to SOMI valid, C_L = 20 pF, PMMCOREV = 3	2.4 V		44	
			3 V		40	
$t_{HD,SO}$	SOMI output data hold time[3]	C_L = 20 pF, PMMCOREV = 0	1.8 V	18		ns
			3 V	12		
		C_L = 20 pF, PMMCOREV = 3	2.4 V	10		
			3 V	8		

(1) $f_{UCxCLK} = 1/2t_{LO/HI}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(Master)} + t_{SU,SI(USCI)}, t_{SU,MI(Master)} + t_{VALID,SO(USCI)})$
For the master parameters $t_{SU,MI(Master)}$ and $t_{VALID,MO(Master)}$, see the SPI parameters of the attached master.
(2) Specifies the time to drive the next valid data to the SOMI output after the output changing UCLK clock edge. See the timing diagrams in Figure 5-13 and Figure 5-14.
(3) Specifies how long data on the SOMI output is valid after the output changing UCLK clock edge. See the timing diagrams in Figure 5-13 and Figure 5-14.

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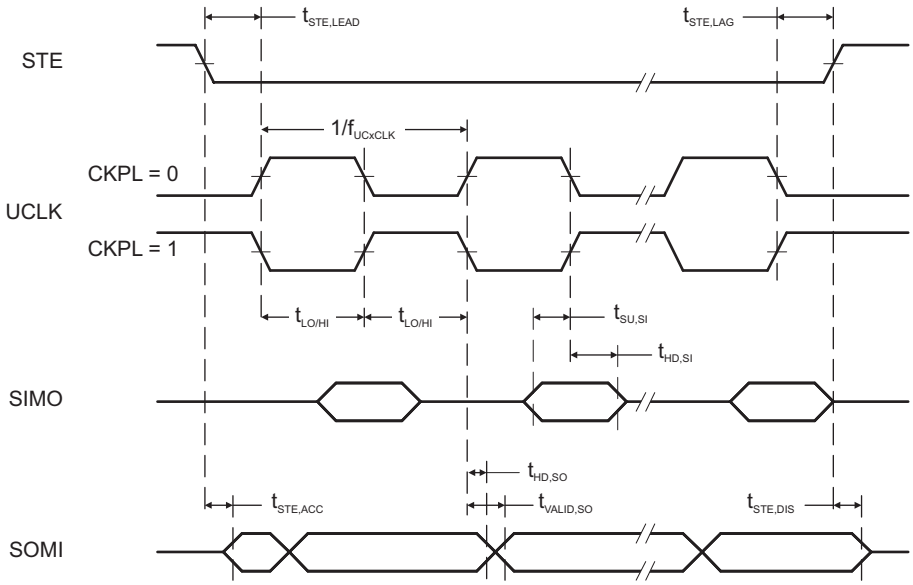


Figure 5-13. SPI Slave Mode, CKPH = 0

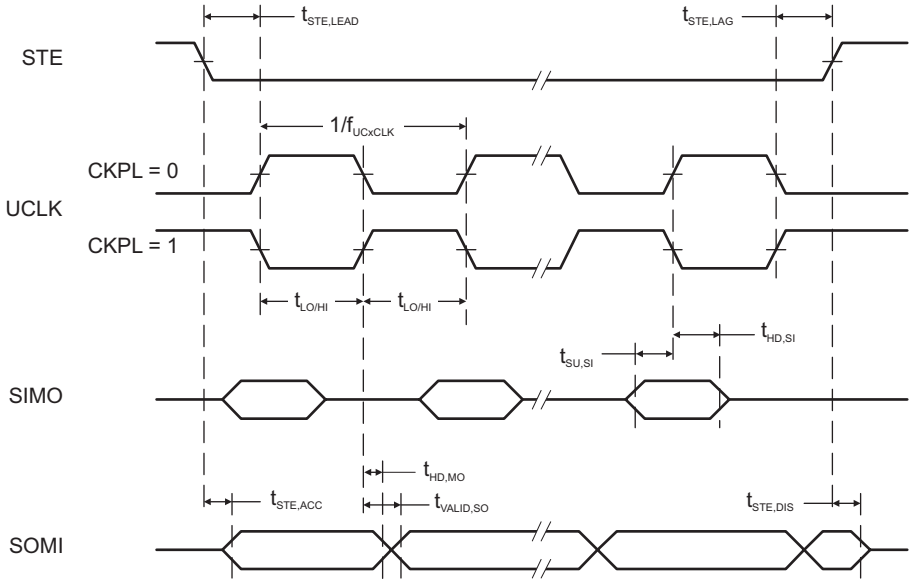


Figure 5-14. SPI Slave Mode, CKPH = 1

5.33 USCI (I^2C Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5-15)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{USCI}	USCI input clock frequency	Internal: SMCLK or ACLK, External: UCLK Duty cycle = 50% ±10%			f_{SYSTEM}	MHz
f_{SCL}	SCL clock frequency		2.2 V, 3 V	0	400	kHz
$t_{HD,STA}$	Hold time (repeated) START	$f_{SCL} \le 100$ kHz	2.2 V, 3 V	4.0		µs
		$f_{SCL} > 100$ kHz		0.6		
$t_{SU,STA}$	Setup time for a repeated START	$f_{SCL} \le 100$ kHz	2.2 V, 3 V	4.7		µs
		$f_{SCL} > 100$ kHz		0.6		
$t_{HD,DAT}$	Data hold time		2.2 V, 3 V	0		ns
$t_{SU,DAT}$	Data setup time		2.2 V, 3 V	250		ns
$t_{SU,STO}$	Setup time for STOP	$f_{SCL} \le 100$ kHz	2.2 V, 3 V	4.0		µs
		$f_{SCL} > 100$ kHz		0.6		
t_{SP}	Pulse duration of spikes suppressed by input filter		2.2 V	50	600	ns
			3 V	50	600	

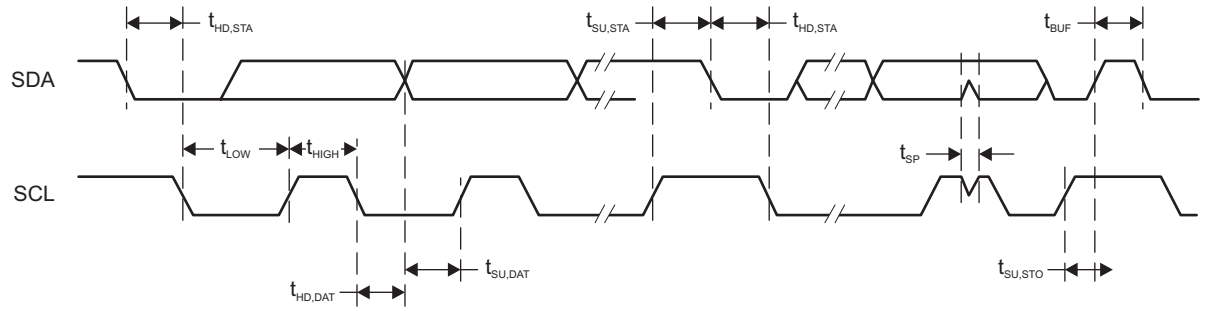


Figure 5-15. I^2C Mode Timing

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5.34 12-Bit ADC, Power Supply and Input Range Conditions

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
AV_{CC}	Analog supply voltage	AVCC and DVCC are connected together, AVSS and DVSS are connected together, $V_{(AVSS)} = V_{(DVSS)} = 0$ V		2.2		3.6	V
$V_{(Ax)}$	Analog input voltage range(2)	All ADC12 analog input pins Ax		0		AV_{CC}	V
I_{ADC12_A}	Operating supply current into AV_{CC} terminal(3)	$f_{ADC12CLK}$ = 5 MHz(4)	2.2 V		150	200	µA
			3 V		150	250	
C_I	Input capacitance	Only one terminal Ax can be selected at one time	2.2 V		20	25	pF
R_I	Input MUX ON resistance	$0 V \le V_{IN} \le V_{(AVCC)}$		10	200	1900	Ω

(1) The leakage current is specified by the digital I/O input leakage.
(2) The analog input voltage range must be within the selected reference voltage range V_{R+} to V_{R-} for valid conversion results. If the reference voltage is supplied by an external source or if the internal voltage is used and REFOUT = 1, then decoupling capacitors are required. See Section 5.40 and Section 5.41.
(3) The internal reference supply current is not included in current consumption parameter I_{ADC12}.
(4) ADC12ON = 1, REFON = 0, SHT0 = 0, SHT1 = 0, ADC12DIV = 0

5.35 12-Bit ADC, Timing Parameters

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$f_{ADC12CLK}$	ADC conversion clock	For specified performance of ADC12 linearity parameters using an external reference voltage or AVCC as reference(1)	2.2 V, 3 V	0.45	4.8	5.0	MHz
		For specified performance of ADC12 linearity parameters using the internal reference(2)		0.45	2.4	4.0	
		For specified performance of ADC12 linearity parameters using the internal reference(3)		0.45	2.4	2.7	
$f_{ADC12OSC}$	Internal ADC12 oscillator(4)	ADC12DIV = 0, $f_{ADC12CLK} = f_{ADC12OSC}$	2.2 V, 3 V	4.2	4.8	5.4	MHz
$t_{CONVERT}$	Conversion time	REFON = 0, Internal oscillator, ADC12OSC used for ADC conversion clock	2.2 V, 3 V	2.4		3.1	µs
		External $f_{ADC12CLK}$ from ACLK, MCLK or SMCLK, ADC12SSEL ≠ 0			13 × 1 / $f_{ADC12CLK}$		
t_{Sample}	Sampling time	R_S = 400 Ω, R_I = 200 Ω, C_I = 20 pF, $\tau = (R_S + R_I) \times C_I$(5)	2.2 V, 3 V	1000			ns

(1) REFOUT = 0, external reference voltage: SREF2 = 0, SREF1 = 1, SREF0 = 0. AVCC as reference voltage: SREF2 = 0, SREF1 = 0, SREF0 = 0. The specified performance of the ADC12 linearity is ensured when using the ADC12OSC. For other clock sources, the specified performance of the ADC12 linearity is ensured with $f_{ADC12CLK}$ maximum of 5 MHz.
(2) SREF2 = 0, SREF1 = 1, SREF0 = 0, ADC12SR = 0, REFOUT = 1
(3) SREF2 = 0, SREF1 = 1, SREF0 = 0, ADC12SR = 0, REFOUT = 0. The specified performance of the ADC12 linearity is ensured when using the ADC12OSC divided by 2.
(4) The ADC12OSC is sourced directly from MODOSC inside the UCS.
(5) Approximately 10 Tau (τ) are needed to get an error of less than ±0.5 LSB:
$t_{Sample} = \ln(2^{n+1}) \times (R_S + R_I) \times C_I + 800$ ns, where n = ADC resolution = 12, R_S = external source resistance

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5.36 12-Bit ADC, Linearity Parameters Using an External Reference Voltage

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
E_I	Integral linearity error (1)	1.4 V ≤ dVREF ≤ 1.6 V (2)	2.2 V, 3 V			±2	LSB
		1.6 V < dVREF (2)				±1.7	
E_D	Differential linearity error (1)	(2)	2.2 V, 3 V			±1	LSB
E_O	Offset error (3)	dVREF ≤ 2.2 V (2)	2.2 V, 3 V		±3	±5.6	LSB
		dVREF > 2.2 V (2)	2.2 V, 3 V		±1.5	±3.5	
E_G	Gain error (3)	(2)	2.2 V, 3 V		±1	±2.5	LSB
E_T	Total unadjusted error	dVREF ≤ 2.2 V (2)	2.2 V, 3 V		±3.5	±7.1	LSB
		dVREF > 2.2 V (2)	2.2 V, 3 V		±2	±5	

(1) Parameters are derived using the histogram method.
(2) The external reference voltage is selected by: SREF2 = 0 or 1, SREF1 = 1, SREF0 = 0. dVREF = V_{R+} - V_{R-}. V_{R+} < AVCC. V_{R-} > AVSS. Unless otherwise mentioned, dVREF > 1.5 V. Impedance of the external reference voltage R < 100 Ω, and two decoupling capacitors, 10 µF and 100 nF, should be connected to VREF+/VREF- to decouple the dynamic current. See also the *MSP430F5xx and MSP430F6xx Family User's Guide*.
(3) Parameters are derived using a best fit curve.

5.37 12-Bit ADC, Linearity Parameters Using AVCC as Reference Voltage

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
E_I	Integral linearity error (1)	See (2)	2.2 V, 3 V			±1.7	LSB
E_D	Differential linearity error (1)	See (2)	2.2 V, 3 V			±1	LSB
E_O	Offset error (3)	See (2)	2.2 V, 3 V		±1	±2	LSB
E_G	Gain error (3)	See (2)	2.2 V, 3 V		±2	±4	LSB
E_T	Total unadjusted error	See (2)	2.2 V, 3 V		±2	±5	LSB

(1) Parameters are derived using the histogram method.
(2) AVCC as reference voltage is selected by: SREF2 = 0, SREF1 = 0, SREF0 = 0.
(3) Parameters are derived using a best fit curve.

5.38 12-Bit ADC, Linearity Parameters Using the Internal Reference Voltage

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS (1)		V_{CC}	MIN	TYP	MAX	UNIT
E_I	Integral linearity error (2)	ADC12SR = 0, REFOUT = 1	$f_{ADC12CLK}$ ≤ 4.0 MHz	2.2 V, 3 V			±1.7	LSB
		ADC12SR = 0, REFOUT = 0	$f_{ADC12CLK}$ ≤ 2.7 MHz				±2.5	
E_D	Differential linearity error (2)	ADC12SR = 0, REFOUT = 1	$f_{ADC12CLK}$ ≤ 4.0 MHz	2.2 V, 3 V	–1		+1.5	LSB
		ADC12SR = 0, REFOUT = 1	$f_{ADC12CLK}$ ≤ 2.7 MHz				±1	
		ADC12SR = 0, REFOUT = 0	$f_{ADC12CLK}$ ≤ 2.7 MHz		–1		+2.5	
E_O	Offset error (3)	ADC12SR = 0, REFOUT = 1	$f_{ADC12CLK}$ ≤ 4.0 MHz	2.2 V, 3 V		±2	±4	LSB
		ADC12SR = 0, REFOUT = 0	$f_{ADC12CLK}$ ≤ 2.7 MHz			±2	±4	
E_G	Gain error (3)	ADC12SR = 0, REFOUT = 1	$f_{ADC12CLK}$ ≤ 4.0 MHz	2.2 V, 3 V		±1	±2.5	LSB
		ADC12SR = 0, REFOUT = 0	$f_{ADC12CLK}$ ≤ 2.7 MHz				±1% (4)	VREF
E_T	Total unadjusted error	ADC12SR = 0, REFOUT = 1	$f_{ADC12CLK}$ ≤ 4.0 MHz	2.2 V, 3 V		±2	±5	LSB
		ADC12SR = 0, REFOUT = 0	$f_{ADC12CLK}$ ≤ 2.7 MHz				±1% (4)	VREF

(1) The external reference voltage is selected by: SREF2 = 0, SREF1 = 0, SREF0 = 1. dVREF = V_{R+} - V_{R-}.
(2) Parameters are derived using the histogram method.
(3) Parameters are derived using a best fit curve.
(4) The gain error and the total unadjusted error are dominated by the accuracy of the integrated reference module absolute accuracy. In this mode the reference voltage used by the ADC12_A is not available on a pin.

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5.39 12-Bit ADC, Temperature Sensor and Built-In V_{MID} (1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{SENSOR}	Temperature sensor voltage (2) (see Figure 5-16)	ADC12ON = 1, INCH = 0Ah, T_A = 0°C	2.2 V		680		mV
			3 V		680		
TC_{SENSOR}	Temperature coefficient of sensor (2)	ADC12ON = 1, INCH = 0Ah	2.2 V		2.25		mV/°C
			3 V		2.25		
$t_{SENSOR(sample)}$	Sample time required if channel 10 is selected (3)	ADC12ON = 1, INCH = 0Ah, Error of conversion result ≤ 1 LSB	2.2 V	100			µs
			3 V	100			
V_{MID}	AV_{CC} divider at channel 11	ADC12ON = 1, INCH = 0Bh, $V_{MID} \approx 0.5 \times V_{AVCC}$	2.2 V	1.06	1.1	1.14	V
			3 V	1.46	1.5	1.54	
$t_{VMID(sample)}$	Sample time required if channel 11 is selected (4)	ADC12ON = 1, INCH = 0Bh, Error of conversion result ≤ 1 LSB	2.2 V, 3 V	1000			ns

(1) The temperature sensor is provided by the REF module. See the REF module parametric, I_{REF+}, regarding the current consumption of the temperature sensor.
(2) The temperature sensor offset can be significant. TI recommends a single-point calibration to minimize the offset error of the built-in temperature sensor. The TLV structure contains calibration values for 30°C ±3°C and 85°C ±3°C for each of the available reference voltage levels. The sensor voltage can be computed as $V_{SENSE} = TC_{SENSOR} \times$ (Temperature,°C) + V_{SENSOR}, where TC_{SENSOR} and V_{SENSOR} can be computed from the calibration values for higher accuracy. See also the *MSP430F5xx and MSP430F6xx Family User's Guide*.
(3) The typical equivalent impedance of the sensor is 51 kΩ. The sample time required includes the sensor-on time $t_{SENSOR(on)}$.
(4) The on-time $t_{VMID(on)}$ is included in the sampling time $t_{VMID(sample)}$; no additional on time is needed.

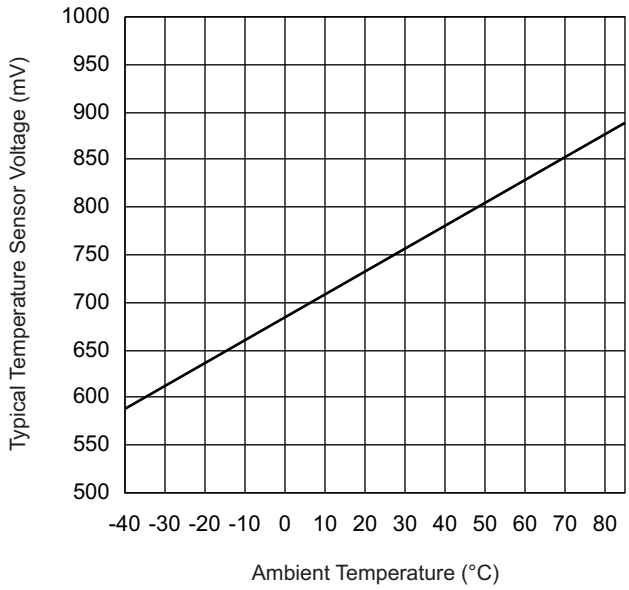


Figure 5-16. Typical Temperature Sensor Voltage

5.40 REF, External Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
V_{eREF+}	Positive external reference voltage input	$V_{eREF+} > V_{REF-}/V_{eREF-}$ (2)		1.4	AV_{CC}	V
V_{REF-}/V_{eREF-}	Negative external reference voltage input	$V_{eREF+} > V_{REF-}/V_{eREF-}$ (3)		0	1.2	V
$V_{eREF+} - V_{REF-}/V_{eREF-}$	Differential external reference voltage input	$V_{eREF+} > V_{REF-}/V_{eREF-}$ (4)		1.4	AV_{CC}	V
I_{VeREF+}, $I_{VREF-/VeREF-}$	Static input current	1.4 V ≤ V_{eREF+} ≤ V_{AVCC} , V_{eREF-} = 0 V, $f_{ADC12CLK}$ = 5 MHz, ADC12SHTx = 1h, Conversion rate 200 ksps	2.2 V, 3 V	–26	26	µA
		1.4 V ≤ V_{eREF+} ≤ V_{AVCC} , V_{eREF-} = 0 V, $f_{ADC12CLK}$ = 5 MHz, ADC12SHTx = 8h, Conversion rate 20 ksps	2.2 V, 3 V	–1.2	+1.2	
$C_{VREF+/-}$	Capacitance at VREF+ or VREF- terminal(5)			10		µF

(1) The external reference is used during ADC conversion to charge and discharge the capacitance array. The input capacitance, C_i, is also the dynamic load for an external reference during conversion. The dynamic impedance of the reference supply should follow the recommendations on analog-source impedance to let the charge settle for 12-bit accuracy.
(2) The accuracy limits the minimum positive external reference voltage. Lower reference voltage levels may be applied with reduced accuracy requirements.
(3) The accuracy limits the maximum negative external reference voltage. Higher reference voltage levels may be applied with reduced accuracy requirements.
(4) The accuracy limits minimum external differential reference voltage. Lower differential reference voltage levels may be applied with reduced accuracy requirements.
(5) Connect two decoupling capacitors, 10 µF and 100 nF, to VREF to decouple the dynamic current required for an external reference source if it is used for the ADC12_A. Also see the *MSP430x5xx and MSP430x6xx Family User's Guide*.

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5.41 REF, Built-In Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
V_{REF+}	Positive built-in reference voltage output	REFVSEL = {2} for 2.5 V, REFON = REFOUT = 1 , I_{VREF+} = 0 A		3 V		2.5	±1%	V
		REFVSEL = {1} for 2 V, REFON = REFOUT = 1, I_{VREF+} = 0 A		3 V		2.0	±1%	
		REFVSEL = {0} for 1.5 V, REFON = REFOUT = 1, I_{VREF+} = 0 A		2.2 V, 3 V		1.5	±1%	
$AV_{CC(min)}$	AVCC minimum voltage, Positive built-in reference active	REFVSEL = {0} for 1.5 V			2.2			V
		REFVSEL = {1} for 2 V			2.3			
		REFVSEL = {2} for 2.5 V			2.8			
I_{REF+}	Operating supply current into AVCC terminal (2) (3)	ADC12SR = 1(4), REFON = 1, REFOUT = 0, REFBURST = 0		3 V		70	100	µA
		ADC12SR = 1(4), REFON = 1, REFOUT = 1, REFBURST = 0				0.45	0.75	mA
		ADC12SR = 0(4), REFON = 1, REFOUT = 0, REFBURST = 0				210	310	µA
		ADC12SR = 0(4), REFON = 1, REFOUT = 1, REFBURST = 0				0.95	1.7	mA
$I_{L(VREF+)}$	Load-current regulation, VREF+ terminal(5)	REFVSEL = {0, 1, 2}, I_{VREF+} = +10 µA , –1000 µA, AV_{CC} = $AV_{CC(min)}$ for each reference level, REFVSEL = {0, 1, 2}, REFON = REFOUT = 1				1500	2500	µV/mA
C_{VREF+}	Capacitance at VREF+ terminal	REFON = REFOUT = 1(6), 0 mA ≤ I_{VREF+} ≤ I_{VREF+}(max)		2.2 V, 3 V	20		100	pF
TC_{REF+}	Temperature coefficient of built-in reference(7)	I_{VREF+} is a constant in the range of 0 mA ≤ I_{VREF+} ≤ –1 mA	REFOUT = 0	2.2 V, 3 V		20		ppm/°C
TC_{REF+}	Temperature coefficient of built-in reference(7)	I_{VREF+} is a constant in the range of 0 mA ≤ I_{VREF+} ≤ –1 mA	REFOUT = 1	2.2 V, 3 V		20	50	ppm/°C
PSRR_DC	Power supply rejection ratio (DC)	AV_{CC} = AV_{CC}(min) to AV_{CC}(max), T_A = 25°C, REFVSEL = {0, 1, 2}, REFON = 1, REFOUT = 0 or 1				120	300	µV/V
PSRR_AC	Power supply rejection ratio (AC)	AV_{CC} = AV_{CC}(min) to AV_{CC}(max), T_A = 25°C, REFVSEL = {0, 1, 2}, REFON = 1, REFOUT = 0 or 1				1		mV/V
t_{SETTLE}	Settling time of reference voltage(8)	AV_{CC} = AV_{CC}(min) to AV_{CC}(max), REFVSEL = {0, 1, 2}, REFOUT = 0, REFON = 0 → 1				75		µs
		AV_{CC} = AV_{CC}(min) to AV_{CC}(max), C_{VREF} = C_{VREF}(max), REFVSEL = {0, 1, 2}, REFOUT = 1, REFON = 0 → 1				75		

(1) The reference is supplied to the ADC by the REF module and is buffered locally inside the ADC. The ADC uses two internal buffers, one smaller and one larger for driving the V_{REF+} terminal. When REFOUT = 1, the reference is available at the V_{REF+} terminal, as well as, used as the reference for the conversion and uses the larger buffer. When REFOUT = 0, the reference is only used as the reference for the conversion and uses the smaller buffer.
(2) The internal reference current is supplied by the AVCC terminal. Consumption is independent of the ADC12ON control bit, unless a conversion is active. REFOUT = 0 represents the current contribution of the smaller buffer. REFOUT = 1 represents the current contribution of the larger buffer without external load.
(3) The temperature sensor is provided by the REF module. Its current is supplied by terminal AVCC and is equivalent to I_{REF+} with REFON = 1 and REFOUT = 0.
(4) For devices without the ADC12, the parametric with ADC12SR = 0 are applicable.
(5) Contribution only due to the reference and buffer including package. This does not include resistance due to PCB traces or other external factors.
(6) Connect two decoupling capacitors, 10 µF and 100 nF, to VREF to decouple the dynamic current required for an external reference source if it is used for the ADC12_A. Also see the *MSP430x5xx and MSP430x6xx Family User's Guide*.
(7) Calculated using the box method: (MAX(–40°C to +85°C) – MIN(–40°C to +85°C)) / MIN(–40°C to +85°C)/(85°C – (–40°C)).
(8) The condition is that the error in a conversion started after t_{REFON} is less than ±0.5 LSB. The settling time depends on the external capacitive load when REFOUT = 1.

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5.42 12-Bit DAC, Supply Specifications

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
AV_{CC}	Analog supply voltage	AV_{CC} = DV_{CC}, AV_{SS} = DV_{SS} = 0 V		2.20		3.60	V
I_{DD}	Supply current, single DAC channel(1) (2)	DAC12AMPx = 2, DAC12IR = 0, DAC12OG = 1, DAC12_xDAT = 0800h, VeREF+ = VREF+ = 1.5 V	3 V		65	110	µA
		DAC12AMPx = 2, DAC12IR = 1, DAC12_xDAT = 0800h, VeREF+ = VREF+ = AV_{CC}	2.2 V, 3 V		125	165	
		DAC12AMPx = 5, DAC12IR = 1, DAC12_xDAT = 0800h, VeREF+ = VREF+ = AV_{CC}			250	350	
		DAC12AMPx = 7, DAC12IR = 1, DAC12_xDAT = 0800h, VeREF+ = VREF+ = AV_{CC}			750	1100	
PSRR	Power supply rejection ratio(3) (4)	DAC12_xDAT = 800h, VeREF+ = 1.5 V, ΔAV_{CC} = 100 mV	2.2 V		70		dB
		DAC12_xDAT = 800h, VeREF+ = 1.5 V or 2.5 V, ΔAV_{CC} = 100 mV	3 V		70		

(1) No load at the output pin, DAC12_0 or DAC12_1, assuming that the control bits for the shared pins are set properly.
(2) Current into reference terminals not included. If DAC12IR = 1 current flows through the input divider; see Reference Input specifications.
(3) PSRR = 20 log (ΔAV_{CC} / ΔV_{DAC12_xOUT})
(4) The internal reference is not used.

5.43 12-Bit DAC, Linearity Specifications

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see 图 5-17)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
	Resolution	12-bit monotonic			12			bits
INL	Integral nonlinearity(1)	VeREF+ = 1.5 V, DAC12AMPx = 7, DAC12IR = 1		2.2 V		±2	±4(2)	LSB
		VeREF+ = 2.5 V, DAC12AMPx = 7, DAC12IR = 1		3 V		±2	±4	
DNL	Differential nonlinearity(1)	VeREF+ = 1.5 V, DAC12AMPx = 7, DAC12IR = 1		2.2 V		±0.4	±1(2)	LSB
		VeREF+ = 2.5 V, DAC12AMPx = 7, DAC12IR = 1		3 V		±0.4	±1	
E_O	Offset voltage	Without calibration(1) (3)	VeREF+ = 1.5 V, DAC12AMPx = 7, DAC12IR = 1	2.2 V			±21(2)	mV
			VeREF+ = 2.5 V, DAC12AMPx = 7, DAC12IR = 1	3 V			±21	
		With calibration(1) (3)	VeREF+ = 1.5 V, DAC12AMPx = 7, DAC12IR = 1	2.2 V			±1.5(2)	
			VeREF+ = 2.5 V, DAC12AMPx = 7, DAC12IR = 1	3 V			±1.5	
$d_{E(O)}/d_T$	Offset error temperature coefficient(1)	With calibration		2.2 V, 3 V		±10		µV/°C
E_G	Gain error	VeREF+ = 1.5 V		2.2 V			±2.5	%FSR
		VeREF+ = 2.5 V		3 V			±2.5	
$d_{E(G)}/d_T$	Gain temperature coefficient(1)			2.2 V, 3 V		10		ppm of FSR/ °C

(1) Parameters calculated from the best-fit curve from 0x0F to 0xFFF. The best-fit curve method is used to deliver coefficients "a" and "b" of the first-order equation: y = a + bx. V_{DAC12_xOUT} = E_O + (1 + E_G) × (VeREF+ / 4095) × DAC12_xDAT, DAC12IR = 1.
(2) This parameter is not production tested.
(3) The offset calibration works on the output operational amplifier. Offset calibration is triggered by setting the DAC12CALON bit.

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12-Bit DAC, Linearity Specifications *(continued)*

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see 图 5-17)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
t_{Offset_Cal}	Time for offset calibration (4)	DAC12AMPx = 2	2.2 V, 3 V			165	ms
		DAC12AMPx = 3, 5				66	
		DAC12AMPx = 4, 6, 7				16.5	

(4) The offset calibration can be done if DAC12AMPx = {2, 3, 4, 5, 6, 7}. The output operational amplifier is switched off with DAC12AMPx = {0, 1}. TI recommends configuring the DAC12 module before initiating calibration. Port activity during calibration may effect accuracy and is not recommended.

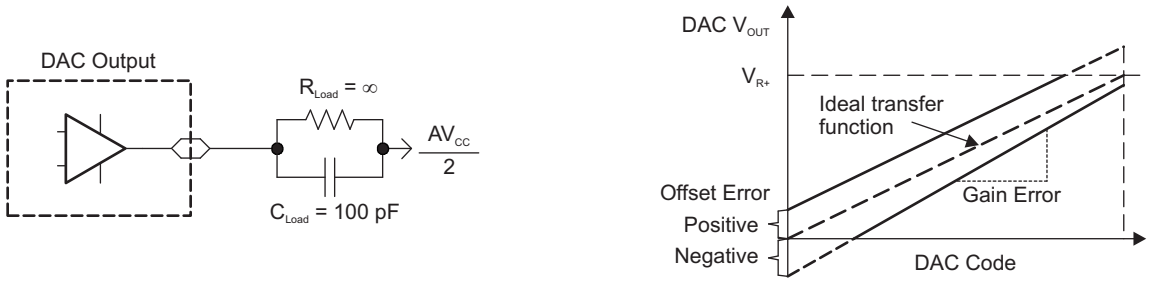


图 5-17. Linearity Test Load Conditions and Gain/Offset Definition

5.44 12-Bit DAC, Output Specifications

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_O	Output voltage range (1) (see 图 5-18)	No load, VeREF+ = AV_{CC}, DAC12_xDAT = 0h, DAC12IR = 1, DAC12AMPx = 7	2.2 V, 3 V	0		0.005	V
		No load, VeREF+ = AV_{CC}, DAC12_xDAT = 0FFFh, DAC12IR = 1, DAC12AMPx = 7		AV_{CC} – 0.05		AV_{CC}	
		R_{Load} = 3 kΩ, VeREF+ = AV_{CC}, DAC12_xDAT = 0h, DAC12IR = 1, DAC12AMPx = 7		0		0.1	
		R_{Load} = 3 kΩ, VeREF+ = AV_{CC}, DAC12_xDAT = 0FFFh, DAC12IR = 1, DAC12AMPx = 7		AV_{CC} – 0.13		AV_{CC}	
$C_{L(DAC12)}$	Maximum DAC12 load capacitance		2.2 V, 3 V			100	pF
$I_{L(DAC12)}$	Maximum DAC12 load current	DAC12AMPx = 2, DAC12_xDAT = 0FFFh, $V_{O/P(DAC12)}$ > AV_{CC} – 0.3	2.2 V, 3 V	–1			mA
		DAC12AMPx = 2, DAC12_xDAT = 0h, $V_{O/P(DAC12)}$ < 0.3 V				1	
$R_{O/P(DAC12)}$	Output resistance (see 图 5-18)	R_{Load} = 3 kΩ, $V_{O/P(DAC12)}$ < 0.3 V, DAC12AMPx = 2, DAC12_xDAT = 0h	2.2 V, 3 V		150	250	Ω
		R_{Load} = 3 kΩ, $V_{O/P(DAC12)}$ > AV_{CC} – 0.3 V, DAC12_xDAT = 0FFFh			150	250	
		R_{Load} = 3 kΩ, 0.3 V ≤ $V_{O/P(DAC12)}$ ≤ AV_{CC} – 0.3 V				6	

(1) Data is valid after the offset calibration of the output amplifier.

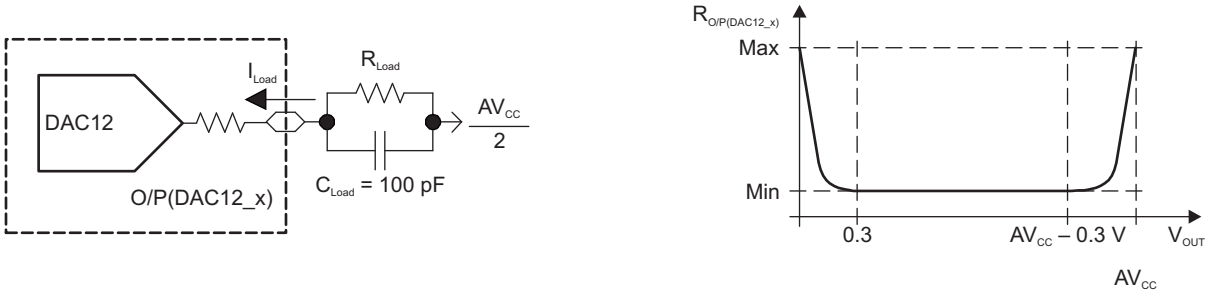


图 5-18. DAC12_x Output Resistance Tests

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5.45 12-Bit DAC, Reference Input Specifications

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
VeREF+	Reference input voltage range	DAC12IR = 0 (1) (2)	2.2 V, 3 V		AV_{CC} / 3	AV_{CC} + 0.2	V
		DAC12IR = 1 (3) (4)			AV_{CC}	AV_{CC} + 0.2	
$Ri_{(VREF+)}$, $Ri_{(VeREF+)}$	Reference input resistance	DAC12_0 IR = DAC12_1 IR = 0	2.2 V, 3 V	20			MΩ
		DAC12_0 IR = 1, DAC12_1 IR = 0			48		kΩ
		DAC12_0 IR = 0, DAC12_1 IR = 1			48		
		DAC12_0 IR = DAC12_1 IR = 1, DAC12_0 SREFx = DAC12_1 SREFx (5)			24		

(1) For a full-scale output, the reference input voltage can be as high as 1/3 of the maximum output voltage swing (AVCC).
(2) The maximum voltage applied at reference input voltage terminal VeREF+ = $(AV_{CC} – V_{E(O)}) / (3 × (1 + E_G))$.
(3) For a full-scale output, the reference input voltage can be as high as the maximum output voltage swing (AVCC).
(4) The maximum voltage applied at reference input voltage terminal VeREF+ = $(AV_{CC} – V_{E(O)}) / (1 + E_G)$.
(5) When DAC12IR = 1 and DAC12SREFx = 0 or 1 for both channels, the reference input resistive dividers for each DAC are in parallel reducing the reference input resistance.

5.46 12-Bit DAC, Dynamic Specifications

$V_{REF} = V_{CC}$, DAC12IR = 1 (see 图 5-19 and 图 5-20), over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
t_{ON}	DAC12 on time	DAC12_xDAT = 800h, $Error_{V(O)}$ < ±0.5 LSB (1) (see 图 5-19)	DAC12AMPx = 0 → {2, 3, 4}	2.2 V, 3 V		60	120	µs
			DAC12AMPx = 0 → {5, 6}			15	30	
			DAC12AMPx = 0 → 7			6	12	
$t_{S(FS)}$	Settling time, full scale	DAC12_xDAT = 80h → F7Fh → 80h	DAC12AMPx = 2	2.2 V, 3 V		100	200	µs
			DAC12AMPx = 3, 5			40	80	
			DAC12AMPx = 4, 6, 7			15	30	
$t_{S(C-C)}$	Settling time, code to code	DAC12_xDAT = 3F8h → 408h → 3F8h, BF8h → C08h → BF8h	DAC12AMPx = 2	2.2 V, 3 V		5		µs
			DAC12AMPx = 3, 5			2		
			DAC12AMPx = 4, 6, 7			1		
SR	Slew rate	DAC12_xDAT = 80h → F7Fh → 80h (2)	DAC12AMPx = 2	2.2 V, 3 V	0.05	0.35		V/µs
			DAC12AMPx = 3, 5		0.35	1.10		
			DAC12AMPx = 4, 6, 7		1.50	5.20		
	Glitch energy	DAC12_xDAT = 800h → 7FFh → 800h	DAC12AMPx = 7	2.2 V, 3 V		35		nV-s

(1) R_{Load} and C_{Load} connected to AV_{SS} (not $AV_{CC}/2$) in 图 5-19.
(2) Slew rate applies to output voltage steps ≥ 200 mV.

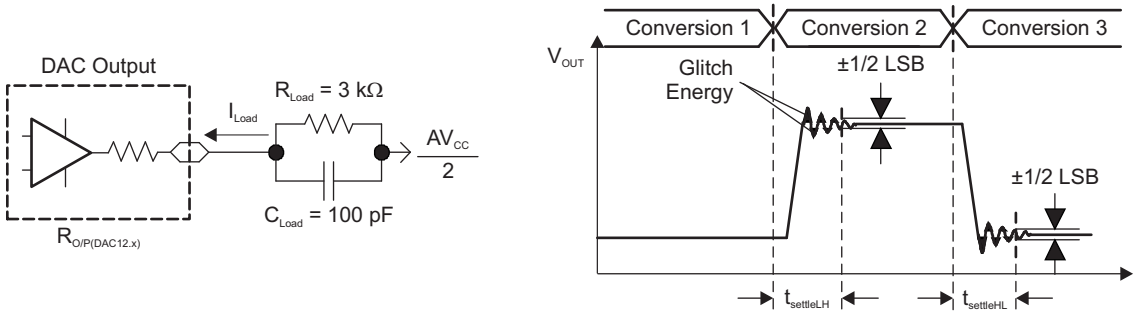


图 5-19. Settling Time and Glitch Energy Testing

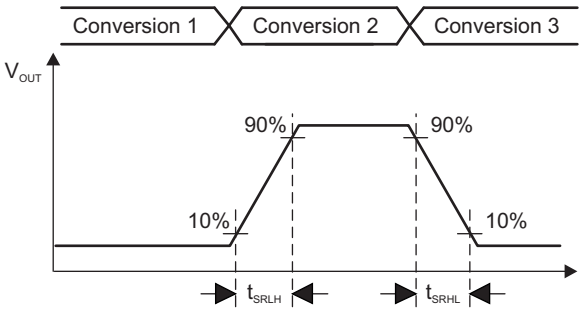


图 5-20. Slew Rate Testing

5.47 12-Bit DAC, Dynamic Specifications (Continued)

over recommended ranges of supply voltage and T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
BW_{-3dB}	3-dB bandwidth, V_{DC} = 1.5 V, V_{AC} = 0.1 V_{PP} (see 图 5-21)	DAC12AMPx = {2, 3, 4}, DAC12SREFx = 2, DAC12IR = 1, DAC12_xDAT = 800h	2.2 V, 3 V	40			kHz
		DAC12AMPx = {5, 6}, DAC12SREFx = 2, DAC12IR = 1, DAC12_xDAT = 800h		180			
		DAC12AMPx = 7, DAC12SREFx = 2, DAC12IR = 1, DAC12_xDAT = 800h		550			
	Channel-to-channel crosstalk(1) (see 图 5-22)	DAC12_0DAT = 800h, No load, DAC12_1DAT = 80h ↔ F7Fh, R_{Load} = 3 kΩ, f_{DAC12_1OUT} = 10 kHz at 50/50 duty cycle	2.2 V, 3 V		–80		dB
		DAC12_0DAT = 80h ↔ F7Fh, R_{Load} = 3 kΩ, DAC12_1DAT = 800h, No load, f_{DAC12_0OUT} = 10 kHz at 50/50 duty cycle			–80		

(1) R_{Load} = 3 kΩ, C_{Load} = 100 pF

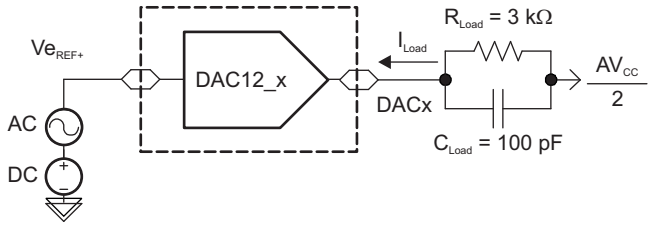


图 5-21. Test Conditions for 3-dB Bandwidth Specification

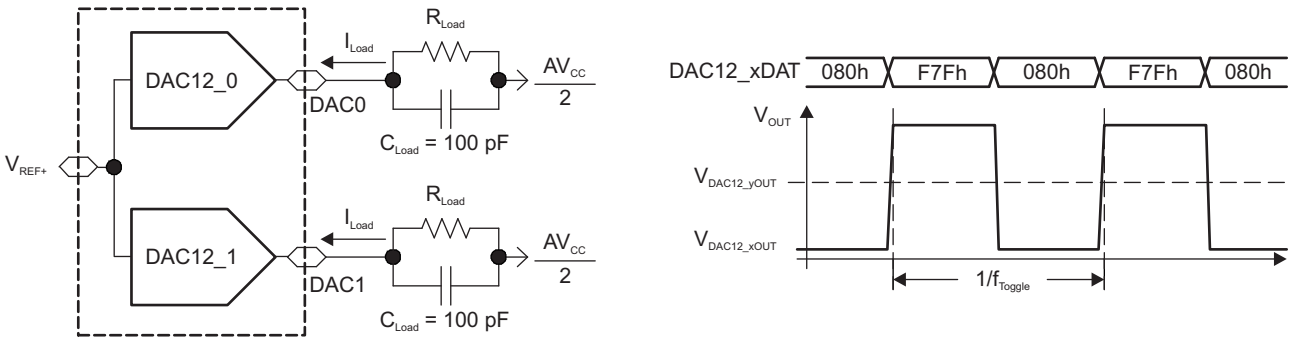


图 5-22. Crosstalk Test Conditions

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5.48 Comparator_B

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage			1.8		3.6	V
I_{AVCC_COMP}	Comparator operating supply current into AVCC terminal, excludes reference resistor ladder	CBPWRMD = 00	1.8 V			40	µA
			2.2 V		30	50	
			3 V		40	65	
		CBPWRMD = 01	2.2 V, 3 V		10	30	
		CBPWRMD = 10	2.2 V, 3 V		0.1	0.5	
I_{AVCC_REF}	Quiescent current of local reference voltage amplifier into AVCC terminal	CBREFACC = 1, CBREFLx = 01				22	µA
V_{IC}	Common-mode input range			0		V_{CC} – 1	V
V_{OFFSET}	Input offset voltage	CBPWRMD = 00				±20	mV
		CBPWRMD = 01, 10				±10	
C_{IN}	Input capacitance				5		pF
R_{SIN}	Series input resistance	On (switch closed)			3	4	kΩ
		Off (switch open)		50			MΩ
t_{PD}	Propagation delay, response time	CBPWRMD = 00, CBF = 0				450	ns
		CBPWRMD = 01, CBF = 0				600	
		CBPWRMD = 10, CBF = 0				50	µs
$t_{PD,filter}$	Propagation delay with filter active	CBPWRMD = 00, CBON = 1, CBF = 1, CBFDLY = 00		0.35	0.6	1.0	µs
		CBPWRMD = 00, CBON = 1, CBF = 1, CBFDLY = 01		0.6	1.0	1.8	
		CBPWRMD = 00, CBON = 1, CBF = 1, CBFDLY = 10		1.0	1.8	3.4	
		CBPWRMD = 00, CBON = 1, CBF = 1, CBFDLY = 11		1.8	3.4	6.5	
t_{EN_CMP}	Comparator enable time, settling time	CBON = 0 to CBON = 1, CBPWRMD = 00, 01			1	2	µs
		CBON = 0 to CBON = 1, CBPWRMD = 10				100	
t_{EN_REF}	Resistor reference enable time	CBON = 0 to CBON = 1			0.3	1.5	µs
V_{CB_REF}	Reference voltage for a given tap	VIN = reference into resistor ladder, n = 0 to 31		VIN × (n + 0.5) / 32	VIN × (n + 1) / 32	VIN × (n + 1.5) / 32	V

5.49 Ports PU.0 and PU.1

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
V_{OH}	High-level output voltage	V_{USB} = 3.3 V ±10%, I_{OH} = –25 mA	2.4		V
V_{OL}	Low-level output voltage	V_{USB} = 3.3 V ±10%, I_{OL} = 25 mA		0.4	V
V_{IH}	High-level input voltage	V_{USB} = 3.3 V ±10%	2.0		V
V_{IL}	Low-level input voltage	V_{USB} = 3.3 V ±10%		0.8	V

5.50 USB Output Ports DP and DM

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
V_{OH}	D+, D– single ended	USB 2.0 load conditions	2.8	3.6	V
V_{OL}	D+, D– single ended	USB 2.0 load conditions	0	0.3	V
$Z_{(DRV)}$	D+, D– impedance	Including external series resistor of 27 Ω	28	44	Ω
t_{RISE}	Rise time	Full speed, differential, C_L = 50 pF, 10%/90%, Rpu on D+	4	20	ns
t_{FALL}	Fall time	Full speed, differential, C_L = 50 pF, 10%/90%, Rpu on D+	4	20	ns

5.51 USB Input Ports DP and DM

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		MIN	MAX	UNIT
$V_{(CM)}$	Differential input common-mode range	0.8	2.5	V
$Z_{(IN)}$	Input impedance	300		kΩ
V_{CRS}	Crossover voltage	1.3	2.0	V
V_{IL}	Static SE input logic low level		0.8	V
V_{IH}	Static SE input logic high level	2.0		V
VDI	Differential input voltage		0.2	V

5.52 USB-PWR (USB Power System)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{LAUNCH}	V_{BUS} detection threshold				3.75	V
V_{BUS}	USB bus voltage	Normal operation	3.76		5.5	V
V_{USB}	USB LDO output voltage			3.3	±9%	V
V_{18}	Internal USB voltage(1)			1.8		V
I_{USB_EXT}	Maximum external current from VUSB terminal(2)	USB LDO is on			12	mA
I_{DET}	USB LDO current overload detection(3)		60		100	mA
$I_{SUSPEND}$	Operating supply current into VBUS terminal.(4)	USB LDO is on, USB PLL disabled			250	µA
C_{BUS}	VBUS terminal recommended capacitance			4.7		µF
C_{USB}	VUSB terminal recommended capacitance			220		nF
C_{18}	V18 terminal recommended capacitance			220		nF
t_{ENABLE}	Settling time V_{USB} and V_{18}	Within 2%, recommended capacitances			2	ms
R_{PUR}	Pullup resistance of PUR terminal(5)		70	110	150	Ω

(1) This voltage is for internal use only. No external DC loading should be applied.
(2) This represents additional current that can be supplied to the application from the VUSB terminal beyond the needs of the USB operation.
(3) A current overload is detected when the total current supplied from the USB LDO, including I_{USB_EXT}, exceeds this value.
(4) Does not include current contribution of R_{pu} and R_{pd} as outlined in the USB specification.
(5) This value, in series with an external resistor between PUR and D+, produces the R_{pu} as outlined in the USB specification.

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5.53 USB-PLL (USB Phase-Locked Loop)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		MIN	TYP	MAX	UNIT
I_{PLL}	Operating supply current			7	mA
f_{PLL}	PLL frequency		48		MHz
f_{UPD}	PLL reference frequency	1.5		3	MHz
t_{LOCK}	PLL lock time			2	ms
t_{Jitter}	PLL jitter		1000		ps

5.54 Flash Memory

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		T_J	MIN	TYP	MAX	UNIT
$DV_{CC(PGM/ERASE)}$	Program and erase supply voltage		1.8		3.6	V
I_{PGM}	Average supply current from DVCC during program			3	5	mA
I_{ERASE}	Average supply current from DVCC during erase			6	11	mA
I_{MERASE}, I_{BANK}	Average supply current from DVCC during mass erase or bank erase			6	11	mA
t_{CPT}	Cumulative program time(1)				16	ms
	Program and erase endurance		10^4	10^5		cycles
$t_{Retention}$	Data retention duration	25°C	100			years
t_{Word}	Word or byte program time(2)		64		85	µs
$t_{Block, 0}$	Block program time for first byte or word(2)		49		65	µs
$t_{Block, 1–(N–1)}$	Block program time for each additional byte or word, except for last byte or word(2)		37		49	µs
$t_{Block, N}$	Block program time for last byte or word(2)		55		73	µs
$t_{Seg\ Erase}$	Erase time for segment, mass erase, and bank erase when available(2)		23		32	ms
$f_{MCLK,MGR}$	MCLK frequency in marginal read mode (FCTL4.MGR0 = 1 or FCTL4.MGR1 = 1)		0		1	MHz

(1) The cumulative program time must not be exceeded when writing to a 128-byte flash block. This parameter applies to all programming methods: individual word or byte write and block write modes.
(2) These values are hardwired into the state machine of the flash controller.

5.55 JTAG and Spy-Bi-Wire Interface

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{SBW}	Spy-Bi-Wire input frequency	2.2 V, 3 V	0		20	MHz
$t_{SBW,Low}$	Spy-Bi-Wire low clock pulse duration	2.2 V, 3 V	0.025		15	µs
$t_{SBW, En}$	Spy-Bi-Wire enable time (TEST high to acceptance of first clock edge)(1)	2.2 V, 3 V			1	µs
$t_{SBW,Rst}$	Spy-Bi-Wire return to normal operation time		15		100	µs
f_{TCK}	TCK input frequency (4-wire JTAG)(2)	2.2 V	0		5	MHz
		3 V	0		10	MHz
$R_{internal}$	Internal pulldown resistance on TEST	2.2 V, 3 V	45	60	80	kΩ

(1) Tools that access the Spy-Bi-Wire interface must wait for the $t_{SBW,En}$ time after pulling the TEST/SBWTCK pin high before applying the first SBWTCK clock edge.
(2) f_{TCK} may be restricted to meet the timing requirements of the module selected.

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6 Detailed Description

6.1 Overview

The MSP430F563x devices include a high-performance 12-bit ADC, a comparator, two USCIs, USB 2.0, a hardware multiplier, DMA, four 16-bit timers, an RTC module with alarm capabilities, and up to 74 I/O pins.

6.2 CPU

The MSP430 CPU has a 16-bit RISC architecture that is highly transparent to the application. All operations, other than program-flow instructions, are performed as register operations in conjunction with seven addressing modes for source operand and four addressing modes for destination operand.

The CPU is integrated with 16 registers that provide reduced instruction execution time. The register-to-register operation execution time is one cycle of the CPU clock.

Four of the registers, R0 to R3, are dedicated as program counter, stack pointer, status register, and constant generator, respectively. The remaining registers are general-purpose registers (see 图 6-1).

Peripherals are connected to the CPU using data, address, and control buses. Peripherals can be managed with all instructions.

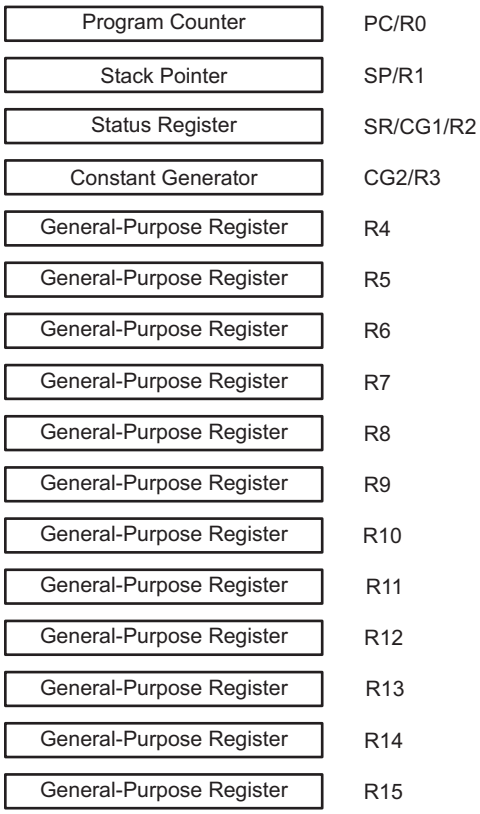


图 6-1. Integrated CPU Registers

6.3 Instruction Set

The instruction set consists of the original 51 instructions with three formats and seven address modes and additional instructions for the expanded address range. Each instruction can operate on word and byte data. 表 6-1 lists examples of the three types of instruction formats; 表 6-2 lists the address modes.

表 6-1. Instruction Word Formats

INSTRUCTION WORD FORMAT	EXAMPLE	OPERATION
Dual operands, source-destination	ADD R4,R5	R4 + R5 → R5
Single operands, destination only	CALL R8	PC → (TOS), R8 → PC
Relative jump, un/conditional	JNE	Jump-on-equal bit = 0

表 6-2. Address Mode Descriptions

ADDRESS MODE	S(1)	D(1)	SYNTAX	EXAMPLE	OPERATION
Register	+	+	MOV Rs,Rd	MOV R10,R11	R10 → R11
Indexed	+	+	MOV X(Rn),Y(Rm)	MOV 2(R5),6(R6)	M(2+R5) → M(6+R6)
Symbolic (PC relative)	+	+	MOV EDE,TONI		M(EDE) → M(TONI)
Absolute	+	+	MOV &MEM, &TCDAT		M(MEM) → M(TCDAT)
Indirect	+		MOV @Rn,Y(Rm)	MOV @R10,Tab(R6)	M(R10) → M(Tab+R6)
Indirect auto-increment	+		MOV @Rn+,Rm	MOV @R10+,R11	M(R10) → R11 R10 + 2 → R10
Immediate	+		MOV #X,TONI	MOV #45,TONI	#45 → M(TONI)

(1) S = source, D = destination

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6.4 Operating Modes

These devices have one active mode and seven software-selectable low-power modes of operation. An interrupt event can wake up the device from any of the low-power modes, service the request, and restore back to the low-power mode on return from the interrupt program.

Software can configure the following operating modes:

- Active mode (AM)
  - All clocks are active
- Low-power mode 0 (LPM0)
  - CPU is disabled
  - ACLK and SMCLK remain active, MCLK is disabled
  - FLL loop control remains active
- Low-power mode 1 (LPM1)
  - CPU is disabled
  - FLL loop control is disabled
  - ACLK and SMCLK remain active, MCLK is disabled
- Low-power mode 2 (LPM2)
  - CPU is disabled
  - MCLK, FLL loop control, and DCOCLK are disabled
  - DC generator of the DCO remains enabled
  - ACLK remains active
- Low-power mode 3 (LPM3)
  - CPU is disabled
  - MCLK, FLL loop control, and DCOCLK are disabled
  - DC generator of the DCO is disabled
  - ACLK remains active
- Low-power mode 4 (LPM4)
  - CPU is disabled
  - ACLK is disabled
  - MCLK, FLL loop control, and DCOCLK are disabled
  - DC generator of the DCO is disabled
  - Crystal oscillator is stopped
  - Complete data retention
- Low-power mode 3.5 (LPM3.5)
  - Internal regulator disabled
  - No data retention
  - RTC enabled and clocked by low-frequency oscillator
  - Wake-up signal from $\overline{\text{RST}}$/NMI, RTC_B, P1, P2, P3, and P4
- Low-power mode 4.5 (LPM4.5)
  - Internal regulator disabled
  - No data retention
  - Wake-up signal from $\overline{\text{RST}}$/NMI, P1, P2, P3, and P4

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6.5 Interrupt Vector Addresses

The interrupt vectors and the power-up start address are in the address range 0FFFFh to 0FF80h (see 表 6-3). The vector contains the 16-bit address of the appropriate interrupt-handler instruction sequence.

表 6-3. Interrupt Sources, Flags, and Vectors of MSP430F563x Configurations

INTERRUPT SOURCE	INTERRUPT FLAG	SYSTEM INTERRUPT	WORD ADDRESS	PRIORITY
System Reset Power-Up, External Reset Watchdog Time-out, Key Violation Flash Memory Key Violation	WDTIFG, KEYV (SYSRSTIV)(1)(2)	Reset	0FFFEh	63, highest
System NMI PMM Vacant Memory Access JTAG Mailbox	SVMLIFG, SVMHIFG, DLYLIFG, DLYHIFG, VLRLIFG, VLRHIFG, VMAIFG, JMBNIFG, JMBOUTIFG (SYSSNIV)(1)	(Non)maskable	0FFFCh	62
User NMI NMI Oscillator Fault Flash Memory Access Violation	NMIIFG, OFIFG, ACCVIFG, BUSIFG (SYSUNIV)(1)(2)	(Non)maskable	0FFFAh	61
Comp_B	Comparator B interrupt flags (CBIV)(1)(3)	Maskable	0FFF8h	60
Timer TB0	TB0CCR0 CCIFG0(3)	Maskable	0FFF6h	59
Timer TB0	TB0CCR1 CCIFG1 to TB0CCR6 CCIFG6, TB0IFG (TBIV)(1) (3)	Maskable	0FFF4h	58
Watchdog Interval Timer Mode	WDTIFG	Maskable	0FFF2h	57
USCI_A0 Receive or Transmit	UCA0RXIFG, UCA0TXIFG (UCA0IV)(1)(3)	Maskable	0FFF0h	56
USCI_B0 Receive or Transmit	UCB0RXIFG, UCB0TXIFG (UCB0IV)(1)(3)	Maskable	0FFEEh	55
ADC12_A(4)	ADC12IFG0 to ADC12IFG15 (ADC12IV)(1)(3)	Maskable	0FFECh	54
Timer TA0	TA0CCR0 CCIFG0(3)	Maskable	0FFEAh	53
Timer TA0	TA0CCR1 CCIFG1 to TA0CCR4 CCIFG4, TA0IFG (TA0IV)(1)(3)	Maskable	0FFE8h	52
USB_UBM	USB interrupts (USBIV)(1)(3)	Maskable	0FFE6h	51
DMA	DMA0IFG, DMA1IFG, DMA2IFG, DMA3IFG, DMA4IFG, DMA5IFG (DMAIV)(1)(3)	Maskable	0FFE4h	50
Timer TA1	TA1CCR0 CCIFG0(3)	Maskable	0FFE2h	49
Timer TA1	TA1CCR1 CCIFG1 to TA1CCR2 CCIFG2, TA1IFG (TA1IV)(1)(3)	Maskable	0FFE0h	48
I/O Port P1	P1IFG.0 to P1IFG.7 (P1IV)(1) (3)	Maskable	0FFDEh	47
USCI_A1 Receive or Transmit	UCA1RXIFG, UCA1TXIFG (UCA1IV)(1)(3)	Maskable	0FFDCh	46
USCI_B1 Receive or Transmit	UCB1RXIFG, UCB1TXIFG (UCB1IV)(1)(3)	Maskable	0FFDAh	45
I/O Port P2	P2IFG.0 to P2IFG.7 (P2IV)(1) (3)	Maskable	0FFD8h	44
Reserved	Reserved	Maskable	0FFD6h	43
RTC_B	RTCRDYIFG, RTCTEVIFG, RTCAIFG, RT0PSIFG, RT1PSIFG, RTCOFIFG (RTCIV)(1)(3)	Maskable	0FFD4h	42
DAC12_A(5)	DAC12_0IFG, DAC12_1IFG(1)(3)	Maskable	0FFD2h	41
Timer TA2	TA2CCR0 CCIFG0(3)	Maskable	0FFD0h	40
Timer TA2	TA2CCR1 CCIFG1 to TA2CCR2 CCIFG2, TA2IFG (TA2IV)(1)(3)	Maskable	0FFCEh	39
I/O Port P3	P3IFG.0 to P3IFG.7 (P3IV)(1)(3)	Maskable	0FFCCh	38
I/O Port P4	P4IFG.0 to P4IFG.7 (P4IV)(1)(3)	Maskable	0FFCAh	37

(1) Multiple source flags
(2) A reset is generated if the CPU tries to fetch instructions from within peripheral space or vacant memory space. (Non)maskable: the individual interrupt-enable bit can disable an interrupt event, but the general-interrupt enable cannot disable it.
(3) Interrupt flags are in the module.
(4) Only on devices with peripheral module ADC12_A, otherwise reserved.
(5) Only on devices with peripheral module DAC12_A, otherwise reserved.

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表 6-3. Interrupt Sources, Flags, and Vectors of MSP430F563x Configurations (continued)

INTERRUPT SOURCE	INTERRUPT FLAG	SYSTEM INTERRUPT	WORD ADDRESS	PRIORITY
Reserved	Reserved(6)		0FFC8h	36
			⋮	⋮
			0FF80h	0, lowest

(6) Reserved interrupt vectors at addresses are not used in this device and can be used for regular program code if necessary. To maintain compatibility with other devices, TI recommends reserving these locations.

6.6 Memory

表 6-4 summarizes the memory map for all device variants.

表 6-4. Memory Organization(1)(2)

		MSP430F5636 MSP430F5633 MSP430F5630	MSP430F5637 MSP430F5634 MSP430F5631	MSP430F5638 MSP430F5635 MSP430F5632
Memory (flash) Main: interrupt vector	Total Size	128KB 00FFFFh–00FF80h	192KB 00FFFFh–00FF80h	256KB 00FFFFh–00FF80h
Main: code memory	Bank 3	N/A	N/A	64KB 047FFFh–038000h
	Bank 2	N/A	64KB 037FFFh–028000h	64KB 037FFFh–028000h
	Bank 1	64KB 027FFFh–018000h	64KB 027FFFh–018000h	64KB 027FFFh–018000h
	Bank 0	64KB 017FFFh–008000h	64KB 017FFFh–008000h	64KB 017FFFh–008000h
RAM	Sector 3	4KB 0063FFh–005400h	4KB 0063FFh–005400h	4KB 0063FFh–005400h
	Sector 2	4KB 0053FFh–004400h	4KB 0053FFh–004400h	4KB 0053FFh–004400h
	Sector 1	4KB 0043FFh–003400h	4KB 0043FFh–003400h	4KB 0043FFh–003400h
	Sector 0	4KB 0033FFh–002400h	4KB 0033FFh–002400h	4KB 0033FFh–002400h
USB RAM(3)	Size RAM	2KB 0023FFh–001C00h	2KB 0023FFh–001C00h	2KB 0023FFh–001C00h
Information memory (flash)	Info A	128 B 0019FFh–001980h	128 B 0019FFh–001980h	128 B 0019FFh–001980h
	Info B	128 B 00197Fh–001900h	128 B 00197Fh–001900h	128 B 00197Fh–001900h
	Info C	128 B 0018FFh–001880h	128 B 0018FFh–001880h	128 B 0018FFh–001880h
	Info D	128 B 00187Fh–001800h	128 B 00187Fh–001800h	128 B 00187Fh–001800h
Bootloader (BSL) memory (flash)	BSL 3	512 B 0017FFh–001600h	512 B 0017FFh–001600h	512 B 0017FFh–001600h
	BSL 2	512 B 0015FFh–001400h	512 B 0015FFh–001400h	512 B 0015FFh–001400h
	BSL 1	512 B 0013FFh–001200h	512 B 0013FFh–001200h	512 B 0013FFh–001200h
	BSL 0	512 B 0011FFh–001000h	512 B 0011FFh–001000h	512 B 0011FFh–001000h
Peripherals	Size	4KB 000FFFh–000000h	4KB 000FFFh–000000h	4KB 000FFFh–000000h

(1) N/A = Not available.
(2) Backup RAM is accessed through the control registers BAKMEM0, BAKMEM1, BAKMEM2, and BAKMEM3.
(3) USB RAM can be used as general-purpose RAM when not used for USB operation.

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6.7 Bootloader (BSL)

The BSL lets users program the flash memory or RAM using various serial interfaces. Access to the device memory by the BSL is protected by an user-defined password. For complete description of the features of the BSL and its implementation, see *MSP430 Programming With the Bootloader (BSL)*.

6.7.1 USB BSL

All devices come preprogrammed with the USB BSL. Use of the USB BSL requires external access to six pins (see 表 6-5). In addition to these pins, the application must support external components necessary for normal USB operation; for example, the proper crystal on XT2IN and XT2OUT or proper decoupling.

表 6-5. USB BSL Pin Requirements and Functions

DEVICE SIGNAL	BSL FUNCTION
$\overline{\text{RST}}$/NMI/SBWTDIO	Entry sequence signal
PU.0/DP	USB data terminal DP
PU.1/DM	USB data terminal DM
PUR	USB pullup resistor terminal
VBUS	USB bus power supply
VSSU	USB ground supply

注

The default USB BSL evaluates the logic level of the PUR pin after a BOR reset. If the PUR pin is pulled high externally, the BSL is invoked. Therefore, unless the application is invoking the BSL, it is important to keep PUR pulled low after a BOR reset, even if BSL or USB is never used. TI recommends applying a 1-MΩ resistor to ground.

6.7.2 UART BSL

A UART BSL is also available that can be programmed by the user into the BSL memory by replacing the preprogrammed, factory supplied, USB BSL. Use of the UART BSL requires external access to six pins (see 表 6-6).

表 6-6. UART BSL Pin Requirements and Functions

DEVICE SIGNAL	BSL FUNCTION
$\overline{\text{RST}}$/NMI/SBWTDIO	Entry sequence signal
TEST/SBWTCK	Entry sequence signal
P1.1	Data transmit
P1.2	Data receive
VCC	Power supply
VSS	Ground supply

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6.8 JTAG Operation

6.8.1 JTAG Standard Interface

The MSP430 family supports the standard JTAG interface which requires four signals for sending and receiving data. The JTAG signals are shared with general-purpose I/O. The TEST/SBWTCK pin is used to enable the JTAG signals. In addition to these signals, the RST/NMI/SBWTDIO is required to interface with MSP430 development tools and device programmers. 表 6-7 lists the JTAG pin requirements. For further details on interfacing to development tools and device programmers, see the *MSP430 Hardware Tools User's Guide*. For a complete description of the features of the JTAG interface and its implementation, see *MSP430 Programming With the JTAG Interface*.

表 6-7. JTAG Pin Requirements and Functions

DEVICE SIGNAL	DIRECTION	FUNCTION
PJ.3/TCK	IN	JTAG clock input
PJ.2/TMS	IN	JTAG state control
PJ.1/TDI/TCLK	IN	JTAG data input, TCLK input
PJ.0/TDO	OUT	JTAG data output
TEST/SBWTCK	IN	Enable JTAG pins
RST/NMI/SBWTDIO	IN	External reset
VCC		Power supply
VSS		Ground supply

6.8.2 Spy-Bi-Wire Interface

In addition to the standard JTAG interface, the MSP430 family supports the two wire Spy-Bi-Wire interface. Spy-Bi-Wire can be used to interface with MSP430 development tools and device programmers. 表 6-8 lists the Spy-Bi-Wire interface pin requirements. For further details on interfacing to development tools and device programmers, see the *MSP430 Hardware Tools User's Guide*. For a complete description of the features of the JTAG interface and its implementation, see *MSP430 Programming With the JTAG Interface*.

表 6-8. Spy-Bi-Wire Pin Requirements and Functions

DEVICE SIGNAL	DIRECTION	FUNCTION
TEST/SBWTCK	IN	Spy-Bi-Wire clock input
RST/NMI/SBWTDIO	IN, OUT	Spy-Bi-Wire data input/output
VCC		Power supply
VSS		Ground supply

6.9 Flash Memory (Link to User's Guide)

The flash memory can be programmed by the JTAG port, Spy-Bi-Wire (SBW), the BSL, or in-system by the CPU. The CPU can perform single-byte, single-word, and long-word writes to the flash memory. Features of the flash memory include:

- Flash memory has n segments of main memory and four segments of information memory (A to D) of 128 bytes each. Each segment in main memory is 512 bytes in size.
- Segments 0 to n may be erased in one step, or each segment may be individually erased.
- Segments A to D can be erased individually, or as a group with segments 0 to n. Segments A to D are also called *information memory*.
- Segment A can be locked separately.

6.10 RAM (Link to User's Guide)

The RAM is made up of n sectors. Each sector can be completely powered down to save leakage; however, all data is lost. Features of the RAM include:

- RAM has n sectors. The size of a sector can be found in Memory Organization.
- Each sector 0 to n can be complete disabled; however, data retention is lost.
- Each sector 0 to n automatically enters low power retention mode when possible.
- For devices that contain USB memory, the USB memory can be used as normal RAM if USB is not required.

6.11 Backup RAM

The backup RAM provides a limited number of bytes of RAM that are retained during LPMx.5 and during operation from a backup supply if the Battery Backup System module is implemented.

Eight bytes of backup RAM are available. The backup RAM can be wordwise accessed by the control registers BAKMEM0, BAKMEM1, BAKMEM2, and BAKMEM3.

6.12 Peripherals

Peripherals are connected to the CPU through data, address, and control buses. Peripherals can be managed using all instructions. For complete module descriptions, see the *MSP430x5xx and MSP430x6xx Family User's Guide*.

6.12.1 Digital I/O (Link to User's Guide)

Up to nine 8-bit I/O ports are implemented: P1 through P6, P8, and P9 are complete, P7 contains six individual I/O ports, and PJ contains four individual I/O ports.

- All individual I/O bits are independently programmable.
- Any combination of input, output, and interrupt conditions is possible.
- Programmable pullup or pulldown on all ports.
- Programmable drive strength on all ports.
- All eight bits of ports P1, P2, P3, and P4 support edge-selectable interrupt input.
- All instructions support read and write access to port-control registers.
- Ports can be accessed byte-wise (P1 through P9) or word-wise in pairs (PA through PD).

6.12.2 Port Mapping Controller (Link to User's Guide)

The port mapping controller allows the flexible and reconfigurable mapping of digital functions to port P2. 表 6-9 lists the mnemonic for each function that can be assigned.

表 6-9. Port Mapping Mnemonics and Functions

VALUE	PxMAPy MNEMONIC	INPUT PIN FUNCTION	OUTPUT PIN FUNCTION
0	PM_NONE	None	DV_{SS}
1	PM_CBOUT	–	Comparator_B output
	PM_TB0CLK	Timer TB0 clock input	–
2	PM_ADC12CLK	–	ADC12CLK
	PM_DMAE0	DMAE0 Input	–
3	PM_SVMOUT	–	SVM output
	PM_TB0OUTH	Timer TB0 high-impedance input TB0OUTH	–
4	PM_TB0CCR0B	Timer TB0 CCR0 capture input CCI0B	Timer TB0: TB0.0 compare output Out0
5	PM_TB0CCR1B	Timer TB0 CCR1 capture input CCI1B	Timer TB0: TB0.1 compare output Out1
6	PM_TB0CCR2B	Timer TB0 CCR2 capture input CCI2B	Timer TB0: TB0.2 compare output Out2

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表 6-9. Port Mapping Mnemonics and Functions (continued)

VALUE	PxMAPy MNEMONIC	INPUT PIN FUNCTION	OUTPUT PIN FUNCTION
7	PM_TB0CCR3B	Timer TB0 CCR3 capture input CCI3B	Timer TB0: TB0.3 compare output Out3
8	PM_TB0CCR4B	Timer TB0 CCR4 capture input CCI4B	Timer TB0: TB0.4 compare output Out4
9	PM_TB0CCR5B	Timer TB0 CCR5 capture input CCI5B	Timer TB0: TB0.5 compare output Out5
10	PM_TB0CCR6B	Timer TB0 CCR6 capture input CCI6B	Timer TB0: TB0.6 compare output Out6
11	PM_UCA0RXD	USCI_A0 UART RXD (Direction controlled by USCI – input)	
	PM_UCA0SOMI	USCI_A0 SPI slave out master in (direction controlled by USCI)	
12	PM_UCA0TXD	USCI_A0 UART TXD (Direction controlled by USCI – output)	
	PM_UCA0SIMO	USCI_A0 SPI slave in master out (direction controlled by USCI)	
13	PM_UCA0CLK	USCI_A0 clock input/output (direction controlled by USCI)	
	PM_UCB0STE	USCI_B0 SPI slave transmit enable (direction controlled by USCI – input)	
14	PM_UCB0SOMI	USCI_B0 SPI slave out master in (direction controlled by USCI)	
	PM_UCB0SCL	USCI_B0 I^2C clock (open drain and direction controlled by USCI)	
15	PM_UCB0SIMO	USCI_B0 SPI slave in master out (direction controlled by USCI)	
	PM_UCB0SDA	USCI_B0 I^2C data (open drain and direction controlled by USCI)	
16	PM_UCB0CLK	USCI_B0 clock input/output (direction controlled by USCI)	
	PM_UCA0STE	USCI_A0 SPI slave transmit enable (direction controlled by USCI – input)	
17	PM_MCLK	–	MCLK
18	Reserved	Reserved for test purposes. Do not use this setting.	
19	Reserved	Reserved for test purposes. Do not use this setting.	
20–30	Reserved	None	DVSS
31 (0FFh) (1)	PM_ANALOG	Disables the output driver and the input Schmitt-trigger to prevent parasitic cross currents when applying analog signals.	

(1) The value of the PM_ANALOG mnemonic is set to 0FFh. The port mapping registers are 5 bits wide, and the upper bits are ignored, which results in a maximum value of 31.

表 6-10 lists the default values for all pins that support port mapping.

表 6-10. Default Mapping

PIN	PxMAPy MNEMONIC	INPUT PIN FUNCTION	OUTPUT PIN FUNCTION
P2.0/P2MAP0	PM_UCB0STE, PM_UCA0CLK	USCI_B0 SPI slave transmit enable (direction controlled by USCI – input), USCI_A0 clock input/output (direction controlled by USCI)	
P2.1/P2MAP1	PM_UCB0SIMO, PM_UCB0SDA	USCI_B0 SPI slave in master out (direction controlled by USCI), USCI_B0 I^2C data (open drain and direction controlled by USCI)	
P2.2/P2MAP2	PM_UCB0SOMI, PM_UCB0SCL	USCI_B0 SPI slave out master in (direction controlled by USCI), USCI_B0 I^2C clock (open drain and direction controlled by USCI)	
P2.3/P2MAP3	PM_UCB0CLK, PM_UCA0STE	USCI_B0 clock input/output (direction controlled by USCI), USCI_A0 SPI slave transmit enable (direction controlled by USCI – input)	
P2.4/P2MAP4	PM_UCA0TXD, PM_UCA0SIMO	USCI_A0 UART TXD (direction controlled by USCI – output), USCI_A0 SPI slave in master out (direction controlled by USCI)	
P2.5/P2MAP5	PM_UCA0RXD, PM_UCA0SOMI	USCI_A0 UART RXD (direction controlled by USCI – input), USCI_A0 SPI slave out master in (direction controlled by USCI)	
P2.6/P2MAP6	PM_NONE	–	DVSS
P2.7/P2MAP7	PM_NONE	–	DVSS

6.12.3 Oscillator and System Clock (Link to User's Guide)

The clock system is supported by the Unified Clock System (UCS) module that includes support for a 32-kHz watch crystal oscillator (in XT1 LF mode; XT1 HF mode is not supported), an internal very-low-power low-frequency oscillator (VLO), an internal trimmed low-frequency oscillator (REFO), an integrated internal digitally controlled oscillator (DCO), and a high-frequency crystal oscillator XT2. The UCS module is designed to meet the requirements of both low system cost and low power consumption. The UCS module features digital frequency-locked loop (FLL) hardware that, in conjunction with a digital modulator, stabilizes the DCO frequency to a programmable multiple of the watch-crystal frequency. The internal DCO provides a fast turnon clock source and stabilizes in 3 µs (typical). The UCS module provides the following clock signals:

- Auxiliary clock (ACLK), sourced from a 32-kHz watch crystal (XT1), a high-frequency crystal (XT2), the internal low-frequency oscillator (VLO), the trimmed low-frequency oscillator (REFO), or the internal digitally-controlled oscillator DCO.
- Main clock (MCLK), the system clock used by the CPU. MCLK can be sourced by same sources available to ACLK.
- Sub-Main clock (SMCLK), the subsystem clock used by the peripheral modules. SMCLK can be sourced by same sources available to ACLK.
- ACLK/n, the buffered output of ACLK, ACLK/2, ACLK/4, ACLK/8, ACLK/16, ACLK/32.

6.12.4 Power-Management Module (PMM) (Link to User's Guide)

The PMM includes an integrated voltage regulator that supplies the core voltage to the device and contains programmable output levels to provide for power optimization. The PMM also includes supply voltage supervisor (SVS) and supply voltage monitoring (SVM) circuitry, as well as brownout protection. The brownout circuit is implemented to provide the proper internal reset signal to the device during power-on and power-off. The SVS and SVM circuitry detects if the supply voltage drops below a user-selectable level and supports both supply voltage supervision (the device is automatically reset) and supply voltage monitoring (the device is not automatically reset). SVS and SVM circuitry is available on the primary supply and core supply.

6.12.5 Hardware Multiplier (MPY) (Link to User's Guide)

The multiplication operation is supported by a dedicated peripheral module. The module performs operations with 32-, 24-, 16-, and 8-bit operands. The module supports signed and unsigned multiplication as well as signed and unsigned multiply-and-accumulate operations.

6.12.6 Real-Time Clock (RTC_B) (Link to User's Guide)

The RTC_B module can be configured for real-time clock (RTC) or calendar mode providing seconds, minutes, hours, day of week, day of month, month, and year. Calendar mode integrates an internal calendar which compensates for months with less than 31 days and includes leap year correction. The RTC_B also supports flexible alarm functions and offset-calibration hardware. The implementation on this device supports operation in LPM3.5 mode and operation from a backup supply.

Using the MSP430 RTC_B Module With Battery Backup Supply describes how to use the RTC_B with battery backup supply functionality to retain the time and keep the RTC counting through loss of main power supply, and how to perform correct reinitialization when the main power supply is restored.

6.12.7 Watchdog Timer (WDT_A) (Link to User's Guide)

The primary function of the WDT_A module is to perform a controlled system restart after a software problem occurs. If the selected time interval expires, a system reset is generated. If the watchdog function is not needed in an application, the module can be configured as an interval timer and can generate interrupts at selected time intervals.

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6.12.8 System Module (SYS) (Link to User's Guide)

The SYS module handles many of the system functions within the device. These include power-on reset and power-up clear handling, NMI source selection and management, reset interrupt vector generators, bootloader entry mechanisms, and configuration management (device descriptors). SYS also includes a data exchange mechanism through JTAG called a JTAG mailbox that can be used in the application.

表 6-11 lists the SYS interrupt vector registers.

表 6-11. System Module Interrupt Vector Registers

INTERRUPT VECTOR REGISTER	INTERRUPT EVENT	WORD ADDRESS	OFFSET	PRIORITY
SYSRSTIV, System Reset	No interrupt pending	019Eh	00h	
	Brownout (BOR)		02h	Highest
	RST/NMI (BOR)		04h	
	PMMSWBOR (BOR)		06h	
	LPM3.5 or LPM4.5 wakeup (BOR)		08h	
	Security violation (BOR)		0Ah	
	SVSL (POR)		0Ch	
	SVSH (POR)		0Eh	
	SVML_OVP (POR)		10h	
	SVMH_OVP (POR)		12h	
	PMMSWPOR (POR)		14h	
	WDT time-out (PUC)		16h	
	WDT key violation (PUC)		18h	
	KEYV flash key violation (PUC)		1Ah	
	Reserved		1Ch	
	Peripheral area fetch (PUC)		1Eh	
	PMM key violation (PUC)		20h	
	Reserved		22h to 3Eh	Lowest
SYSSNIV, System NMI	No interrupt pending	019Ch	00h	
	SVMLIFG		02h	Highest
	SVMHIFG		04h	
	DLYLIFG		06h	
	DLYHIFG		08h	
	VMAIFG		0Ah	
	JMBINIFG		0Ch	
	JMBOUTIFG		0Eh	
	SVMLVLRIFG		10h	
	SVMHVLRIFG		12h	
	Reserved		14h to 1Eh	Lowest
SYSUNIV, User NMI	No interrupt pending	019Ah	00h	
	NMIIFG		02h	Highest
	OFIFG		04h	
	ACCVIFG		06h	
	BUSIFG		08h	
	Reserved		0Ah to 1Eh	Lowest
SYSBERRIV, Bus Error	No interrupt pending	0198h	00h	
	USB wait state time-out		02h	Highest
	Reserved		04h to 1Eh	Lowest

6.12.9 DMA Controller (Link to User's Guide)

The DMA controller allows movement of data from one memory address to another without CPU intervention. For example, the DMA controller can be used to move data from the ADC12_A conversion memory to RAM. Using the DMA controller can increase the throughput of peripheral modules. The DMA controller reduces system power consumption by allowing the CPU to remain in sleep mode, without having to awaken to move data to or from a peripheral. 表 6-12 lists the trigger assignments for each DMA channel.

The USB timestamp generator also uses the channel 0, 1, and 2 DMA trigger assignments.

表 6-12. DMA Trigger Assignments(1)

TRIGGER	CHANNEL					
	0	1	2	3	4	5
0	DMAREQ					
1	TA0CCR0 CCIFG					
2	TA0CCR2 CCIFG					
3	TA1CCR0 CCIFG					
4	TA1CCR2 CCIFG					
5	TA2CCR0 CCIFG					
6	TA2CCR2 CCIFG					
7	TBCCR0 CCIFG					
8	TBCCR2 CCIFG					
9	Reserved					
10	Reserved					
11	Reserved					
12	Reserved					
13	Reserved					
14	Reserved					
15	Reserved					
16	UCA0RXIFG					
17	UCA0TXIFG					
18	UCB0RXIFG					
19	UCB0TXIFG					
20	UCA1RXIFG					
21	UCA1TXIFG					
22	UCB1RXIFG					
23	UCB1TXIFG					
24	ADC12IFGx(2)					
25	DAC12_0IFG(3)					
26	DAC12_1IFG(3)					
27	USB FNRXD					
28	USB ready					
29	MPY ready					
30	DMA5IFG	DMA0IFG	DMA1IFG	DMA2IFG	DMA3IFG	DMA4IFG
31	DMAE0					

(1) Reserved DMA triggers may be used by other devices in the family. Reserved DMA triggers will not cause any DMA trigger event when selected.
(2) Only on devices with peripheral module ADC12_A. Reserved on devices without ADC.
(3) Only on devices with peripheral module DAC12_A. Reserved on devices without DAC.

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6.12.10 Universal Serial Communication Interface (USCI) (Links to User's Guide: UART Mode, SPI Mode, I²C Mode)

The USCI modules are used for serial data communication. The USCI module supports synchronous communication protocols such as SPI (3 or 4 pin) and I²C, and asynchronous communication protocols such as UART, enhanced UART with automatic baudrate detection, and IrDA. Each USCI module contains two portions, A and B.

The USCI_An module provides support for SPI (3 or 4 pin), UART, enhanced UART, or IrDA.

The USCI_Bn module provides support for SPI (3 or 4 pin) or I²C.

The MSP430F563x series includes two complete USCI modules (n = 0 or 1).

6.12.11 Timer TA0 (Link to User's Guide)

Timer TA0 is a 16-bit timer/counter (Timer_A type) with five capture/compare registers. TA0 can support multiple capture/compares, PWM outputs, and interval timing (see 表 6-13). TA0 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each capture/compare register.

表 6-13. Timer TA0 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	ZQW						PZ	ZQW
34-P1.0	L5-P1.0	TA0CLK	TACLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
34-P1.0	L5-P1.0	TA0CLK	$\overline{\text{TACLK}}$					
35-P1.1	M5-P1.1	TA0.0	CCI0A	CCR0	TA0	TA0.0	35-P1.1	M5-P1.1
		DV_{SS}	CCI0B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
36-P1.2	J6-P1.2	TA0.1	CCI1A	CCR1	TA1	TA0.1	36-P1.2	J6-P1.2
40-P1.6	J7-P1.6	TA0.1	CCI1B				40-P1.6	J7-P1.6
		DV_{SS}	GND				ADC12_A (internal)(1) ADC12SHSx = {1}	
		DV_{CC}	V_{CC}					
37-P1.3	H6-P1.3	TA0.2	CCI2A	CCR2	TA2	TA0.2	37-P1.3	H6-P1.3
41-P1.7	M7-P1.7	TA0.2	CCI2B				41-P1.7	M7-P1.7
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
38-P1.4	M6-P1.4	TA0.3	CCI3A	CCR3	TA3	TA0.3	38-P1.4	M6-P1.4
		DV_{SS}	CCI3B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
39-P1.5	L6-P1.5	TA0.4	CCI4A	CCR4	TA4	TA0.4	39-P1.5	L6-P1.5
		DV_{SS}	CCI4B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					

(1) Only on devices with peripheral module ADC12_A.

6.12.12 Timer TA1 (Link to User's Guide)

Timer TA1 is a 16-bit timer/counter (Timer_A type) with three capture/compare registers. TA1 supports multiple capture/compares, PWM outputs, and interval timing (see 表 6-14). TA1 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each capture/compare register.

表 6-14. Timer TA1 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	ZQW						PZ	ZQW
42-P3.0	L7-P3.0	TA1CLK	TACLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
42-P3.0	L7-P3.0	TA1CLK	$\overline{\text{TACLK}}$					
43-P3.1	H7-P3.1	TA1.0	CCI0A	CCR0	TA0	TA1.0	43-P3.1	H7-P3.1
		DV_{SS}	CCI0B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
44-P3.2	M8-P3.2	TA1.1	CCI1A	CCR1	TA1	TA1.1	44-P3.2	M8-P3.2
		CBOUT (internal)	CCI1B				DAC12_A(1) DAC12_0, DAC12_1 (internal)	
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
45-P3.3	L8-P3.3	TA1.2	CCI2A	CCR2	TA2	TA1.2	45-P3.3	L8-P3.3
		ACLK (internal)	CCI2B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					

(1) Only on devices with peripheral module DAC12_A.

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6.12.13 Timer TA2 (Link to User's Guide)

Timer TA2 is a 16-bit timer/counter (Timer_A type) with three capture/compare registers. TA2 supports multiple capture/compares, PWM outputs, and interval timing (see 表 6-15). TA2 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each capture/compare register.

表 6-15. Timer TA2 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	ZQW						PZ	ZQW
46-P3.4	J8-P3.4	TA2CLK	TACLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
46-P3.4	J8-P3.4	TA2CLK	$\overline{\text{TACLK}}$					
47-P3.5	M9-P3.5	TA2.0	CCI0A	CCR0	TA0	TA2.0	47-P3.5	M9-P3.5
		DV_{SS}	CCI0B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
48-P3.6	L9-P3.6	TA2.1	CCI1A	CCR1	TA1	TA2.1	48-P3.6	L9-P3.6
		CBOUT (internal)	CCI1B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
49-P3.7	M10-P3.7	TA2.2	CCI2A	CCR2	TA2	TA2.2	49-P3.7	M10-P3.7
		ACLK (internal)	CCI2B					
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					

6.12.14 Timer TB0 (Link to User's Guide)

Timer TB0 is a 16-bit timer/counter (Timer_B type) with seven capture/compare registers. TB0 supports multiple capture/compares, PWM outputs, and interval timing (see 表 6-16). TB0 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each capture/compare register.

表 6-16. Timer TB0 Signal Connections

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT SIGNAL	MODULE BLOCK	MODULE OUTPUT SIGNAL	DEVICE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PZ	ZQW						PZ	ZQW
58-P8.0 P2MAPx(1)	J11-P8.0 P2MAPx(1)	TB0CLK	TB0CLK	Timer	NA	NA		
		ACLK	ACLK					
		SMCLK	SMCLK					
58-P8.0 P2MAPx(1)	J11-P8.0 P2MAPx(1)	TB0CLK	$\overline{\text{TB0CLK}}$					
50-P4.0	J9-P4.0	TB0.0	CCI0A	CCR0	TB0	TB0.0	50-P4.0	J9-P4.0
P2MAPx(1)	P2MAPx(1)	TB0.0	CCI0B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND				ADC12 (internal) (2) ADC12SHSx = {2}	
		DV_{CC}	V_{CC}					
51-P4.1	M11-P4.1	TB0.1	CCI1A	CCR1	TB1	TB0.1	51-P4.1	M11-P4.1
P2MAPx(1)	P2MAPx(1)	TB0.1	CCI1B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND				ADC12 (internal) (2) ADC12SHSx = {3}	
		DV_{CC}	V_{CC}					
52-P4.2	L10-P4.2	TB0.2	CCI2A	CCR2	TB2	TB0.2	52-P4.2	L10-P4.2
P2MAPx(1)	P2MAPx(1)	TB0.2	CCI2B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND				DAC12_A(3) DAC12_0, DAC12_1 (internal)	
		DV_{CC}	V_{CC}					
53-P4.3	M12-P4.3	TB0.3	CCI3A	CCR3	TB3	TB0.3	53-P4.3	M12-P4.3
P2MAPx(1)	P2MAPx(1)	TB0.3	CCI3B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
54-P4.4	L12-P4.4	TB0.4	CCI4A	CCR4	TB4	TB0.4	54-P4.4	L12-P4.4
P2MAPx(1)	P2MAPx(1)	TB0.4	CCI4B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
55-P4.5	L11-P4.5	TB0.5	CCI5A	CCR5	TB5	TB0.5	55-P4.5	L11-P4.5
P2MAPx(1)	P2MAPx(1)	TB0.5	CCI5B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					
56-P4.6	K11-P4.6	TB0.6	CCI6A	CCR6	TB6	TB0.6	56-P4.6	K11-P4.6
P2MAPx(1)	P2MAPx(1)	TB0.6	CCI6B				P2MAPx(1)	P2MAPx(1)
		DV_{SS}	GND					
		DV_{CC}	V_{CC}					

(1) Timer functions selectable by the port mapping controller.
(2) Only on devices with peripheral module ADC12_A.
(3) Only on devices with peripheral module DAC12_A.

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6.12.15 Comparator_B (Link to User's Guide)

The primary function of the Comparator_B module is to support precision slope analog-to-digital conversions, battery voltage supervision, and monitoring of external analog signals.

6.12.16 ADC12_A (Link to User's Guide)

The ADC12_A module supports fast 12-bit analog-to-digital conversions. The module implements a 12-bit SAR core, sample select control, reference generator, and a 16-word conversion-and-control buffer. The conversion-and-control buffer allows up to 16 independent ADC samples to be converted and stored without any CPU intervention.

6.12.17 DAC12_A (Link to User's Guide)

The DAC12_A module is a 12-bit R-ladder voltage-output DAC. The DAC12_A may be used in 8-bit or 12-bit mode, and may be used with the DMA controller. When multiple DAC12_A modules are present, they may be grouped together for synchronous operation.

6.12.18 CRC16 (Link to User's Guide)

The CRC16 module produces a signature based on a sequence of entered data values and can be used for data checking purposes. The CRC16 module signature is based on the CRC-CCITT standard.

6.12.19 Voltage Reference (REF) Module (Link to User's Guide)

The REF module generates all of the critical reference voltages that can be used by the various analog peripherals in the device.

6.12.20 USB Universal Serial Bus (Link to User's Guide)

The USB module is a fully integrated USB interface that is compliant with the USB 2.0 specification. The module supports full-speed operation of control, interrupt, and bulk transfers. The module includes an integrated LDO, PHY, and PLL. The PLL is highly flexible and can support a wide range of input clock frequencies. USB RAM, when not used for USB communication, can be used by the system.

6.12.21 Embedded Emulation Module (EEM) (Link to User's Guide)

The EEM supports real-time in-system debugging. The L version of the EEM has the following features:

- Eight hardware triggers or breakpoints on memory access
- Two hardware triggers or breakpoints on CPU register write access
- Up to 10 hardware triggers can be combined to form complex triggers or breakpoints
- Two cycle counters
- Sequencer
- State storage
- Clock control on module level

6.12.22 Peripheral File Map

表 6-17 lists the register base address for all of the available peripheral modules.

表 6-17. Peripherals

MODULE NAME	BASE ADDRESS	OFFSET ADDRESS RANGE(1)
Special Functions (see 表 6-18)	0100h	000h–01Fh
PMM (see 表 6-19)	0120h	000h–010h
Flash Control (see 表 6-20)	0140h	000h–00Fh
CRC16 (see 表 6-21)	0150h	000h–007h
RAM Control (see 表 6-22)	0158h	000h–001h
Watchdog (see 表 6-23)	015Ch	000h–001h
UCS (see 表 6-24)	0160h	000h–01Fh
SYS (see 表 6-25)	0180h	000h–01Fh
Shared Reference (see 表 6-26)	01B0h	000h–001h
Port Mapping Control (see 表 6-27)	01C0h	000h–003h
Port Mapping Port P2 (see 表 6-27)	01D0h	000h–007h
Port P1, P2 (see 表 6-28)	0200h	000h–01Fh
Port P3, P4 (see 表 6-29)	0220h	000h–01Fh
Port P5, P6 (see 表 6-30)	0240h	000h–00Bh
Port P7, P8 (see 表 6-31)	0260h	000h–00Bh
Port P9 (see 表 6-32)	0280h	000h–00Bh
Port PJ (see 表 6-33)	0320h	000h–01Fh
Timer TA0 (see 表 6-34)	0340h	000h–02Eh
Timer TA1 (see 表 6-35)	0380h	000h–02Eh
Timer TB0 (see 表 6-36)	03C0h	000h–02Eh
Timer TA2 (see 表 6-37)	0400h	000h–02Eh
Battery Backup (see 表 6-38)	0480h	000h–01Fh
RTC_B (see 表 6-39)	04A0h	000h–01Fh
32-bit Hardware Multiplier (see 表 6-40)	04C0h	000h–02Fh
DMA General Control (see 表 6-41)	0500h	000h–00Fh
DMA Channel 0 (see 表 6-41)	0510h	000h–00Ah
DMA Channel 1 (see 表 6-41)	0520h	000h–00Ah
DMA Channel 2 (see 表 6-41)	0530h	000h–00Ah
DMA Channel 3 (see 表 6-41)	0540h	000h–00Ah
DMA Channel 4 (see 表 6-41)	0550h	000h–00Ah
DMA Channel 5 (see 表 6-41)	0560h	000h–00Ah
USCI_A0 (see 表 6-42)	05C0h	000h–01Fh
USCI_B0 (see 表 6-43)	05E0h	000h–01Fh
USCI_A1 (see 表 6-44)	0600h	000h–01Fh
USCI_B1 (see 表 6-45)	0620h	000h–01Fh
ADC12_A (see 表 6-46)	0700h	000h–03Fh
DAC12_A (see 表 6-47)	0780h	000h–01Fh
Comparator_B (see 表 6-48)	08C0h	000h–00Fh
USB configuration (see 表 6-49)	0900h	000h–014h
USB control (see 表 6-50)	0920h	000h–01Fh

(1) For a detailed description of the individual control register offset addresses, see the *MSP430x5xx and MSP430x6xx Family User's Guide*.

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表 6-18. Special Function Registers (Base Address: 0100h)

REGISTER DESCRIPTION	REGISTER	OFFSET
SFR interrupt enable	SFRIE1	00h
SFR interrupt flag	SFRIFG1	02h
SFR reset pin control	SFRRPCR	04h

表 6-19. PMM Registers (Base Address: 0120h)

REGISTER DESCRIPTION	REGISTER	OFFSET
PMM control 0	PMMCTL0	00h
PMM control 1	PMMCTL1	02h
SVS high-side control	SVSMHCTL	04h
SVS low-side control	SVSMLCTL	06h
PMM interrupt flags	PMMIFG	0Ch
PMM interrupt enable	PMMIE	0Eh
PMM power mode 5 control	PM5CTL0	10h

表 6-20. Flash Control Registers (Base Address: 0140h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Flash control 1	FCTL1	00h
Flash control 3	FCTL3	04h
Flash control 4	FCTL4	06h

表 6-21. CRC16 Registers (Base Address: 0150h)

REGISTER DESCRIPTION	REGISTER	OFFSET
CRC data input	CRC16DI	00h
CRC result	CRC16INIRES	04h

表 6-22. RAM Control Registers (Base Address: 0158h)

REGISTER DESCRIPTION	REGISTER	OFFSET
RAM control 0	RCCTL0	00h

表 6-23. Watchdog Registers (Base Address: 015Ch)

REGISTER DESCRIPTION	REGISTER	OFFSET
Watchdog timer control	WDTCTL	00h

表 6-24. UCS Registers (Base Address: 0160h)

REGISTER DESCRIPTION	REGISTER	OFFSET
UCS control 0	UCSCTL0	00h
UCS control 1	UCSCTL1	02h
UCS control 2	UCSCTL2	04h
UCS control 3	UCSCTL3	06h
UCS control 4	UCSCTL4	08h
UCS control 5	UCSCTL5	0Ah
UCS control 6	UCSCTL6	0Ch
UCS control 7	UCSCTL7	0Eh
UCS control 8	UCSCTL8	10h

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表 6-25. SYS Registers (Base Address: 0180h)

REGISTER DESCRIPTION	REGISTER	OFFSET
System control	SYSCTL	00h
Bootloader configuration area	SYSBSLC	02h
JTAG mailbox control	SYSJMBC	06h
JTAG mailbox input 0	SYSJMBI0	08h
JTAG mailbox input 1	SYSJMBI1	0Ah
JTAG mailbox output 0	SYSJMBO0	0Ch
JTAG mailbox output 1	SYSJMBO1	0Eh
Bus error vector generator	SYSBERRIV	18h
User NMI vector generator	SYSUNIV	1Ah
System NMI vector generator	SYSSNIV	1Ch
Reset vector generator	SYSRSTIV	1Eh

表 6-26. Shared Reference Registers (Base Address: 01B0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Shared reference control	REFCTL	00h

表 6-27. Port Mapping Registers (Base Address of Port Mapping Control: 01C0h, Port P2: 01D0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port mapping password	PMAPPWD	00h
Port mapping control	PMAPCTL	02h
Port P2.0 mapping	P2MAP0	00h
Port P2.1 mapping	P2MAP1	01h
Port P2.2 mapping	P2MAP2	02h
Port P2.3 mapping	P2MAP3	03h
Port P2.4 mapping	P2MAP4	04h
Port P2.5 mapping	P2MAP5	05h
Port P2.6 mapping	P2MAP6	06h
Port P2.7 mapping	P2MAP7	07h

表 6-28. Port P1, P2 Registers (Base Address: 0200h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P1 input	P1IN	00h
Port P1 output	P1OUT	02h
Port P1 direction	P1DIR	04h
Port P1 pullup/pulldown enable	P1REN	06h
Port P1 drive strength	P1DS	08h
Port P1 selection	P1SEL	0Ah
Port P1 interrupt vector word	P1IV	0Eh
Port P1 interrupt edge select	P1IES	18h
Port P1 interrupt enable	P1IE	1Ah
Port P1 interrupt flag	P1IFG	1Ch
Port P2 input	P2IN	01h
Port P2 output	P2OUT	03h
Port P2 direction	P2DIR	05h
Port P2 pullup/pulldown enable	P2REN	07h

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表 6-28. Port P1, P2 Registers (Base Address: 0200h) (continued)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P2 drive strength	P2DS	09h
Port P2 selection	P2SEL	0Bh
Port P2 interrupt vector word	P2IV	1Eh
Port P2 interrupt edge select	P2IES	19h
Port P2 interrupt enable	P2IE	1Bh
Port P2 interrupt flag	P2IFG	1Dh

表 6-29. Port P3, P4 Registers (Base Address: 0220h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P3 input	P3IN	00h
Port P3 output	P3OUT	02h
Port P3 direction	P3DIR	04h
Port P3 pullup/pulldown enable	P3REN	06h
Port P3 drive strength	P3DS	08h
Port P3 selection	P3SEL	0Ah
Port P3 interrupt vector word	P3IV	0Eh
Port P3 interrupt edge select	P3IES	18h
Port P3 interrupt enable	P3IE	1Ah
Port P3 interrupt flag	P3IFG	1Ch
Port P4 input	P4IN	01h
Port P4 output	P4OUT	03h
Port P4 direction	P4DIR	05h
Port P4 pullup/pulldown enable	P4REN	07h
Port P4 drive strength	P4DS	09h
Port P4 selection	P4SEL	0Bh
Port P4 interrupt vector word	P4IV	1Eh
Port P4 interrupt edge select	P4IES	19h
Port P4 interrupt enable	P4IE	1Bh
Port P4 interrupt flag	P4IFG	1Dh

表 6-30. Port P5, P6 Registers (Base Address: 0240h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P5 input	P5IN	00h
Port P5 output	P5OUT	02h
Port P5 direction	P5DIR	04h
Port P5 pullup/pulldown enable	P5REN	06h
Port P5 drive strength	P5DS	08h
Port P5 selection	P5SEL	0Ah
Port P6 input	P6IN	01h
Port P6 output	P6OUT	03h
Port P6 direction	P6DIR	05h
Port P6 pullup/pulldown enable	P6REN	07h
Port P6 drive strength	P6DS	09h
Port P6 selection	P6SEL	0Bh

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表 6-31. Port P7, P8 Registers (Base Address: 0260h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P7 input	P7IN	00h
Port P7 output	P7OUT	02h
Port P7 direction	P7DIR	04h
Port P7 pullup/pulldown enable	P7REN	06h
Port P7 drive strength	P7DS	08h
Port P7 selection	P7SEL	0Ah
Port P8 input	P8IN	01h
Port P8 output	P8OUT	03h
Port P8 direction	P8DIR	05h
Port P8 pullup/pulldown enable	P8REN	07h
Port P8 drive strength	P8DS	09h
Port P8 selection	P8SEL	0Bh

表 6-32. Port P9 Register (Base Address: 0280h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port P9 input	P9IN	00h
Port P9 output	P9OUT	02h
Port P9 direction	P9DIR	04h
Port P9 pullup/pulldown enable	P9REN	06h
Port P9 drive strength	P9DS	08h
Port P9 selection	P9SEL	0Ah

表 6-33. Port J Registers (Base Address: 0320h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Port PJ input	PJIN	00h
Port PJ output	PJOUT	02h
Port PJ direction	PJDIR	04h
Port PJ pullup/pulldown enable	PJREN	06h
Port PJ drive strength	PJDS	08h

表 6-34. TA0 Registers (Base Address: 0340h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TA0 control	TA0CTL	00h
Capture/compare control 0	TA0CCTL0	02h
Capture/compare control 1	TA0CCTL1	04h
Capture/compare control 2	TA0CCTL2	06h
Capture/compare control 3	TA0CCTL3	08h
Capture/compare control 4	TA0CCTL4	0Ah
TA0 counter	TA0R	10h
Capture/compare 0	TA0CCR0	12h
Capture/compare 1	TA0CCR1	14h
Capture/compare 2	TA0CCR2	16h
Capture/compare 3	TA0CCR3	18h
Capture/compare 4	TA0CCR4	1Ah
TA0 expansion 0	TA0EX0	20h
TA0 interrupt vector	TA0IV	2Eh

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表 6-35. TA1 Registers (Base Address: 0380h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TA1 control	TA1CTL	00h
Capture/compare control 0	TA1CCTL0	02h
Capture/compare control 1	TA1CCTL1	04h
Capture/compare control 2	TA1CCTL2	06h
TA1 counter	TA1R	10h
Capture/compare 0	TA1CCR0	12h
Capture/compare 1	TA1CCR1	14h
Capture/compare 2	TA1CCR2	16h
TA1 expansion 0	TA1EX0	20h
TA1 interrupt vector	TA1IV	2Eh

表 6-36. TB0 Registers (Base Address: 03C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TB0 control	TB0CTL	00h
Capture/compare control 0	TB0CCTL0	02h
Capture/compare control 1	TB0CCTL1	04h
Capture/compare control 2	TB0CCTL2	06h
Capture/compare control 3	TB0CCTL3	08h
Capture/compare control 4	TB0CCTL4	0Ah
Capture/compare control 5	TB0CCTL5	0Ch
Capture/compare control 6	TB0CCTL6	0Eh
TB0 counter	TB0R	10h
Capture/compare 0	TB0CCR0	12h
Capture/compare 1	TB0CCR1	14h
Capture/compare 2	TB0CCR2	16h
Capture/compare 3	TB0CCR3	18h
Capture/compare 4	TB0CCR4	1Ah
Capture/compare 5	TB0CCR5	1Ch
Capture/compare 6	TB0CCR6	1Eh
TB0 expansion 0	TB0EX0	20h
TB0 interrupt vector	TB0IV	2Eh

表 6-37. TA2 Registers (Base Address: 0400h)

REGISTER DESCRIPTION	REGISTER	OFFSET
TA2 control	TA2CTL	00h
Capture/compare control 0	TA2CCTL0	02h
Capture/compare control 1	TA2CCTL1	04h
Capture/compare control 2	TA2CCTL2	06h
TA2 counter	TA2R	10h
Capture/compare 0	TA2CCR0	12h
Capture/compare 1	TA2CCR1	14h
Capture/compare 2	TA2CCR2	16h
TA2 expansion 0	TA2EX0	20h
TA2 interrupt vector	TA2IV	2Eh

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表 6-38. Battery Backup Registers (Base Address: 0480h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Battery backup memory 0	BAKMEM0	00h
Battery backup memory 1	BAKMEM1	02h
Battery backup memory 2	BAKMEM2	04h
Battery backup memory 3	BAKMEM3	06h
Battery backup control	BAKCTL	1Ch
Battery charger control	BAKCHCTL	1Eh

表 6-39. Real-Time Clock Registers (Base Address: 04A0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
RTC control 0	RTCCTL0	00h
RTC control 1	RTCCTL1	01h
RTC control 2	RTCCTL2	02h
RTC control 3	RTCCTL3	03h
RTC prescaler 0 control	RTCPS0CTL	08h
RTC prescaler 1 control	RTCPS1CTL	0Ah
RTC prescaler 0	RTCPS0	0Ch
RTC prescaler 1	RTCPS1	0Dh
RTC interrupt vector word	RTCIV	0Eh
RTC seconds	RTCSEC	10h
RTC minutes	RTCMIN	11h
RTC hours	RTCHOUR	12h
RTC day of week	RTCDOW	13h
RTC days	RTCDAY	14h
RTC month	RTCMON	15h
RTC year low	RTCYEARL	16h
RTC year high	RTCYEARH	17h
RTC alarm minutes	RTCAMIN	18h
RTC alarm hours	RTCAHOUR	19h
RTC alarm day of week	RTCADOW	1Ah
RTC alarm days	RTCADAY	1Bh
Binary-to-BCD conversion	BIN2BCD	1Ch
BCD-to-binary conversion	BCD2BIN	1Eh

表 6-40. 32-Bit Hardware Multiplier Registers (Base Address: 04C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
16-bit operand 1 – multiply	MPY	00h
16-bit operand 1 – signed multiply	MPYS	02h
16-bit operand 1 – multiply accumulate	MAC	04h
16-bit operand 1 – signed multiply accumulate	MACS	06h
16-bit operand 2	OP2	08h
16 × 16 result low word	RESLO	0Ah
16 × 16 result high word	RESHI	0Ch
16 × 16 sum extension	SUMEXT	0Eh
32-bit operand 1 – multiply low word	MPY32L	10h
32-bit operand 1 – multiply high word	MPY32H	12h
32-bit operand 1 – signed multiply low word	MPYS32L	14h
32-bit operand 1 – signed multiply high word	MPYS32H	16h

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表 6-40. 32-Bit Hardware Multiplier Registers (Base Address: 04C0h) (continued)

REGISTER DESCRIPTION	REGISTER	OFFSET
32-bit operand 1 – multiply accumulate low word	MAC32L	18h
32-bit operand 1 – multiply accumulate high word	MAC32H	1Ah
32-bit operand 1 – signed multiply accumulate low word	MACS32L	1Ch
32-bit operand 1 – signed multiply accumulate high word	MACS32H	1Eh
32-bit operand 2 – low word	OP2L	20h
32-bit operand 2 – high word	OP2H	22h
32 × 32 result 0 – least significant word	RES0	24h
32 × 32 result 1	RES1	26h
32 × 32 result 2	RES2	28h
32 × 32 result 3 – most significant word	RES3	2Ah
MPY32 control 0	MPY32CTL0	2Ch

表 6-41. DMA Registers (Base Address DMA General Control: 0500h, DMA Channel 0: 0510h, DMA Channel 1: 0520h, DMA Channel 2: 0530h, DMA Channel 3: 0540h, DMA Channel 4: 0550h, DMA Channel 5: 0560h)

REGISTER DESCRIPTION	REGISTER	OFFSET
DMA general control: DMA module control 0	DMACTL0	00h
DMA general control: DMA module control 1	DMACTL1	02h
DMA general control: DMA module control 2	DMACTL2	04h
DMA general control: DMA module control 3	DMACTL3	06h
DMA general control: DMA module control 4	DMACTL4	08h
DMA general control: DMA interrupt vector	DMAIV	0Ah
DMA channel 0 control	DMA0CTL	00h
DMA channel 0 source address low	DMA0SAL	02h
DMA channel 0 source address high	DMA0SAH	04h
DMA channel 0 destination address low	DMA0DAL	06h
DMA channel 0 destination address high	DMA0DAH	08h
DMA channel 0 transfer size	DMA0SZ	0Ah
DMA channel 1 control	DMA1CTL	00h
DMA channel 1 source address low	DMA1SAL	02h
DMA channel 1 source address high	DMA1SAH	04h
DMA channel 1 destination address low	DMA1DAL	06h
DMA channel 1 destination address high	DMA1DAH	08h
DMA channel 1 transfer size	DMA1SZ	0Ah
DMA channel 2 control	DMA2CTL	00h
DMA channel 2 source address low	DMA2SAL	02h
DMA channel 2 source address high	DMA2SAH	04h
DMA channel 2 destination address low	DMA2DAL	06h
DMA channel 2 destination address high	DMA2DAH	08h
DMA channel 2 transfer size	DMA2SZ	0Ah
DMA channel 3 control	DMA3CTL	00h
DMA channel 3 source address low	DMA3SAL	02h
DMA channel 3 source address high	DMA3SAH	04h
DMA channel 3 destination address low	DMA3DAL	06h
DMA channel 3 destination address high	DMA3DAH	08h
DMA channel 3 transfer size	DMA3SZ	0Ah
DMA channel 4 control	DMA4CTL	00h

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表 6-41. DMA Registers (Base Address DMA General Control: 0500h, DMA Channel 0: 0510h, DMA Channel 1: 0520h, DMA Channel 2: 0530h, DMA Channel 3: 0540h, DMA Channel 4: 0550h, DMA Channel 5: 0560h) (continued)

REGISTER DESCRIPTION	REGISTER	OFFSET
DMA channel 4 source address low	DMA4SAL	02h
DMA channel 4 source address high	DMA4SAH	04h
DMA channel 4 destination address low	DMA4DAL	06h
DMA channel 4 destination address high	DMA4DAH	08h
DMA channel 4 transfer size	DMA4SZ	0Ah
DMA channel 5 control	DMA5CTL	00h
DMA channel 5 source address low	DMA5SAL	02h
DMA channel 5 source address high	DMA5SAH	04h
DMA channel 5 destination address low	DMA5DAL	06h
DMA channel 5 destination address high	DMA5DAH	08h
DMA channel 5 transfer size	DMA5SZ	0Ah

表 6-42. USCI_A0 Registers (Base Address: 05C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI control 0	UCA0CTL0	00h
USCI control 1	UCA0CTL1	01h
USCI baud rate 0	UCA0BR0	06h
USCI baud rate 1	UCA0BR1	07h
USCI modulation control	UCA0MCTL	08h
USCI status	UCA0STAT	0Ah
USCI receive buffer	UCA0RXBUF	0Ch
USCI transmit buffer	UCA0TXBUF	0Eh
USCI LIN control	UCA0ABCTL	10h
USCI IrDA transmit control	UCA0IRTCTL	12h
USCI IrDA receive control	UCA0IRRCTL	13h
USCI interrupt enable	UCA0IE	1Ch
USCI interrupt flags	UCA0IFG	1Dh
USCI interrupt vector word	UCA0IV	1Eh

表 6-43. USCI_B0 Registers (Base Address: 05E0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI synchronous control 0	UCB0CTL0	00h
USCI synchronous control 1	UCB0CTL1	01h
USCI synchronous bit rate 0	UCB0BR0	06h
USCI synchronous bit rate 1	UCB0BR1	07h
USCI synchronous status	UCB0STAT	0Ah
USCI synchronous receive buffer	UCB0RXBUF	0Ch
USCI synchronous transmit buffer	UCB0TXBUF	0Eh
USCI I2C own address	UCB0I2COA	10h
USCI I2C slave address	UCB0I2CSA	12h
USCI interrupt enable	UCB0IE	1Ch
USCI interrupt flags	UCB0IFG	1Dh
USCI interrupt vector word	UCB0IV	1Eh

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表 6-44. USCI_A1 Registers (Base Address: 0600h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI control 0	UCA1CTL0	00h
USCI control 1	UCA1CTL1	01h
USCI baud rate 0	UCA1BR0	06h
USCI baud rate 1	UCA1BR1	07h
USCI modulation control	UCA1MCTL	08h
USCI status	UCA1STAT	0Ah
USCI receive buffer	UCA1RXBUF	0Ch
USCI transmit buffer	UCA1TXBUF	0Eh
USCI LIN control	UCA1ABCTL	10h
USCI IrDA transmit control	UCA1IRTCTL	12h
USCI IrDA receive control	UCA1IRRCTL	13h
USCI interrupt enable	UCA1IE	1Ch
USCI interrupt flags	UCA1IFG	1Dh
USCI interrupt vector word	UCA1IV	1Eh

表 6-45. USCI_B1 Registers (Base Address: 0620h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USCI synchronous control 0	UCB1CTL0	00h
USCI synchronous control 1	UCB1CTL1	01h
USCI synchronous bit rate 0	UCB1BR0	06h
USCI synchronous bit rate 1	UCB1BR1	07h
USCI synchronous status	UCB1STAT	0Ah
USCI synchronous receive buffer	UCB1RXBUF	0Ch
USCI synchronous transmit buffer	UCB1TXBUF	0Eh
USCI I2C own address	UCB1I2COA	10h
USCI I2C slave address	UCB1I2CSA	12h
USCI interrupt enable	UCB1IE	1Ch
USCI interrupt flags	UCB1IFG	1Dh
USCI interrupt vector word	UCB1IV	1Eh

表 6-46. ADC12_A Registers (Base Address: 0700h)

REGISTER DESCRIPTION	REGISTER	OFFSET
ADC12 control 0	ADC12CTL0	00h
ADC12 control 1	ADC12CTL1	02h
ADC12 control 2	ADC12CTL2	04h
Interrupt flag	ADC12IFG	0Ah
Interrupt enable	ADC12IE	0Ch
Interrupt vector word	ADC12IV	0Eh
ADC memory control 0	ADC12MCTL0	10h
ADC memory control 1	ADC12MCTL1	11h
ADC memory control 2	ADC12MCTL2	12h
ADC memory control 3	ADC12MCTL3	13h
ADC memory control 4	ADC12MCTL4	14h
ADC memory control 5	ADC12MCTL5	15h
ADC memory control 6	ADC12MCTL6	16h
ADC memory control 7	ADC12MCTL7	17h
ADC memory control 8	ADC12MCTL8	18h

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表 6-46. ADC12_A Registers (Base Address: 0700h) (continued)

REGISTER DESCRIPTION	REGISTER	OFFSET
ADC memory control 9	ADC12MCTL9	19h
ADC memory control 10	ADC12MCTL10	1Ah
ADC memory control 11	ADC12MCTL11	1Bh
ADC memory control 12	ADC12MCTL12	1Ch
ADC memory control 13	ADC12MCTL13	1Dh
ADC memory control 14	ADC12MCTL14	1Eh
ADC memory control 15	ADC12MCTL15	1Fh
Conversion memory 0	ADC12MEM0	20h
Conversion memory 1	ADC12MEM1	22h
Conversion memory 2	ADC12MEM2	24h
Conversion memory 3	ADC12MEM3	26h
Conversion memory 4	ADC12MEM4	28h
Conversion memory 5	ADC12MEM5	2Ah
Conversion memory 6	ADC12MEM6	2Ch
Conversion memory 7	ADC12MEM7	2Eh
Conversion memory 8	ADC12MEM8	30h
Conversion memory 9	ADC12MEM9	32h
Conversion memory 10	ADC12MEM10	34h
Conversion memory 11	ADC12MEM11	36h
Conversion memory 12	ADC12MEM12	38h
Conversion memory 13	ADC12MEM13	3Ah
Conversion memory 14	ADC12MEM14	3Ch
Conversion memory 15	ADC12MEM15	3Eh

表 6-47. DAC12_A Registers (Base Address: 0780h)

REGISTER DESCRIPTION	REGISTER	OFFSET
DAC12_A channel 0 control 0	DAC12_0CTL0	00h
DAC12_A channel 0 control 1	DAC12_0CTL1	02h
DAC12_A channel 0 data	DAC12_0DAT	04h
DAC12_A channel 0 calibration control	DAC12_0CALCTL	06h
DAC12_A channel 0 calibration data	DAC12_0CALDAT	08h
DAC12_A channel 1 control 0	DAC12_1CTL0	10h
DAC12_A channel 1 control 1	DAC12_1CTL1	12h
DAC12_A channel 1 data	DAC12_1DAT	14h
DAC12_A channel 1 calibration control	DAC12_1CALCTL	16h
DAC12_A channel 1 calibration data	DAC12_1CALDAT	18h
DAC12_A interrupt vector word	DAC12IV	1Eh

表 6-48. Comparator_B Registers (Base Address: 08C0h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Comp_B control 0	CBCTL0	00h
Comp_B control 1	CBCTL1	02h
Comp_B control 2	CBCTL2	04h
Comp_B control 3	CBCTL3	06h
Comp_B interrupt	CBINT	0Ch
Comp_B interrupt vector word	CBIV	0Eh

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表 6-49. USB Configuration Registers (Base Address: 0900h)

REGISTER DESCRIPTION	REGISTER	OFFSET
USB key/ID	USBKEYID	00h
USB module configuration	USBCNF	02h
USB PHY control	USBPHYCTL	04h
USB power control	USBPWRCTL	08h
USB power voltage setting	USBPWRVSR	0Ah
USB PLL control	USBPLLCTL	10h
USB PLL divider	USBPLLDIV	12h
USB PLL interrupts	USBPLLIR	14h

表 6-50. USB Control Registers (Base Address: 0920h)

REGISTER DESCRIPTION	REGISTER	OFFSET
Input endpoint_0 configuration	USBIEPCNF_0	00h
Input endpoint_0 byte count	USBIEPCNT_0	01h
Output endpoint_0 configuration	USBOEPCNF_0	02h
Output endpoint_0 byte count	USBOEPCNT_0	03h
Input endpoint interrupt enables	USBIEPIE	0Eh
Output endpoint interrupt enables	USBOEPIE	0Fh
Input endpoint interrupt flags	USBIEPIFG	10h
Output endpoint interrupt flags	USBOEPIFG	11h
USB interrupt vector	USBIV	12h
USB maintenance	USBMAINT	16h
Timestamp	USBTSREG	18h
USB frame number	USBFN	1Ah
USB control	USBCTL	1Ch
USB interrupt enables	USBIE	1Dh
USB interrupt flags	USBIFG	1Eh
Function address	USBFUNADR	1Fh

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6.13 Input/Output Diagrams

6.13.1 Port P1 (P1.0 to P1.7) Input/Output With Schmitt Trigger

图 6-2 shows the pin diagram. 表 6-51 summarizes how to select the pin function.

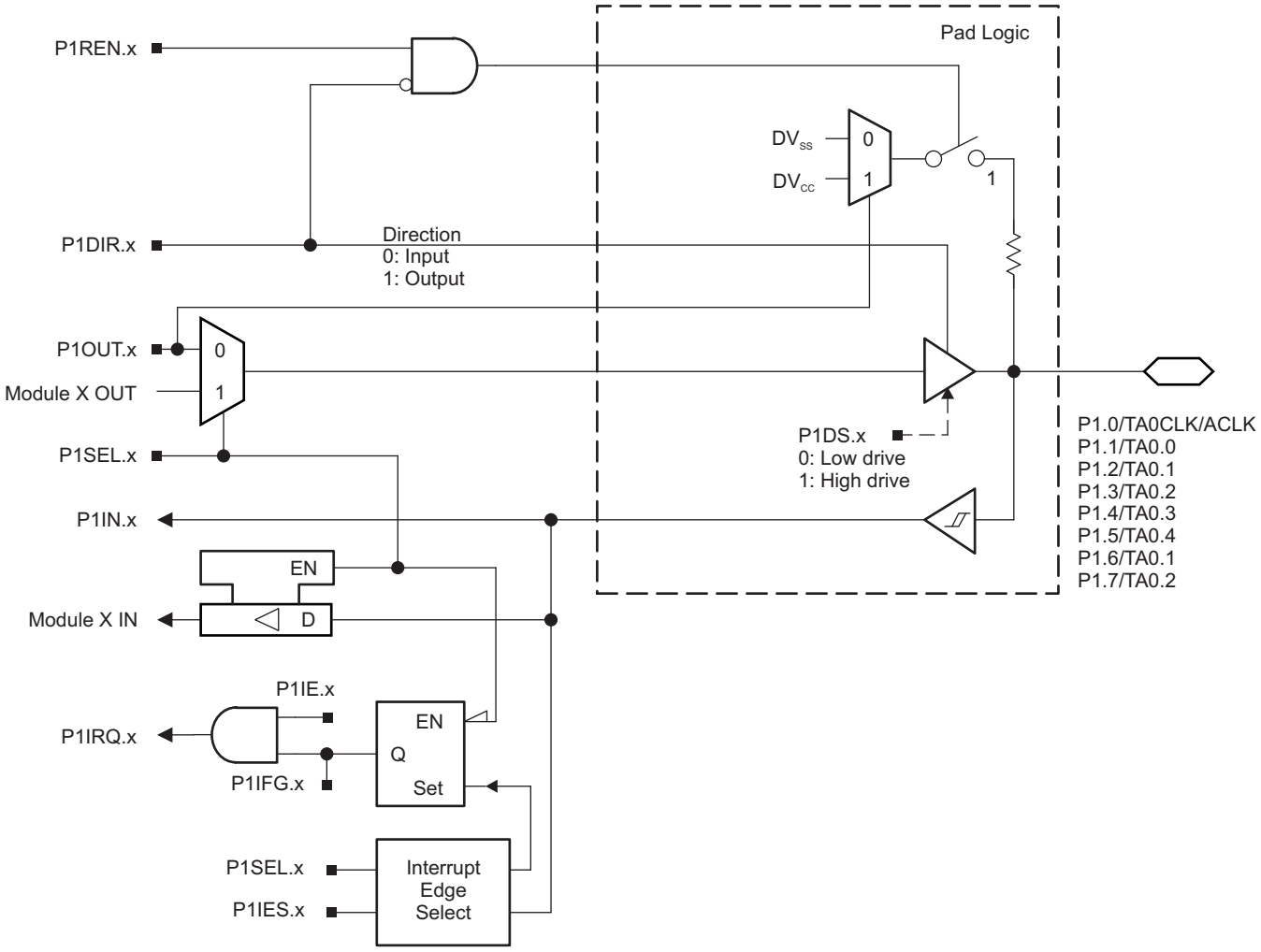


图 6-2. Port P1 (P1.0 to P1.7) Diagram

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表 6-51. Port P1 (P1.0 to P1.7) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS	
			P1DIR.x	P1SEL.x
P1.0/TA0CLK/ACLK	0	P1.0 (I/O)	I: 0; O: 1	0
		Timer TA0.TA0CLK	0	1
		ACLK	1	1
P1.1/TA0.0	1	P1.1 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI0A capture input	0	1
		Timer TA0.0 output	1	1
P1.2/TA0.1	2	P1.2 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI1A capture input	0	1
		Timer TA0.1 output	1	1
P1.3/TA0.2	3	P1.3 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI2A capture input	0	1
		Timer TA0.2 output	1	1
P1.4/TA0.3	4	P1.4 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI3A capture input	0	1
		Timer TA0.3 output	1	1
P1.5/TA0.4	5	P1.5 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI4A capture input	0	1
		Timer TA0.4 output	1	1
P1.6/TA0.1	6	P1.6 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI1B capture input	0	1
		Timer TA0.1 output	1	1
P1.7/TA0.2	7	P1.7 (I/O)	I: 0; O: 1	0
		Timer TA0.CCI2B capture input	0	1
		Timer TA0.2 output	1	1

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6.13.2 Port P2 (P2.0 to P2.7) Input/Output With Schmitt Trigger

图 6-3 shows the pin diagram. 表 6-52 summarizes how to select the pin function.

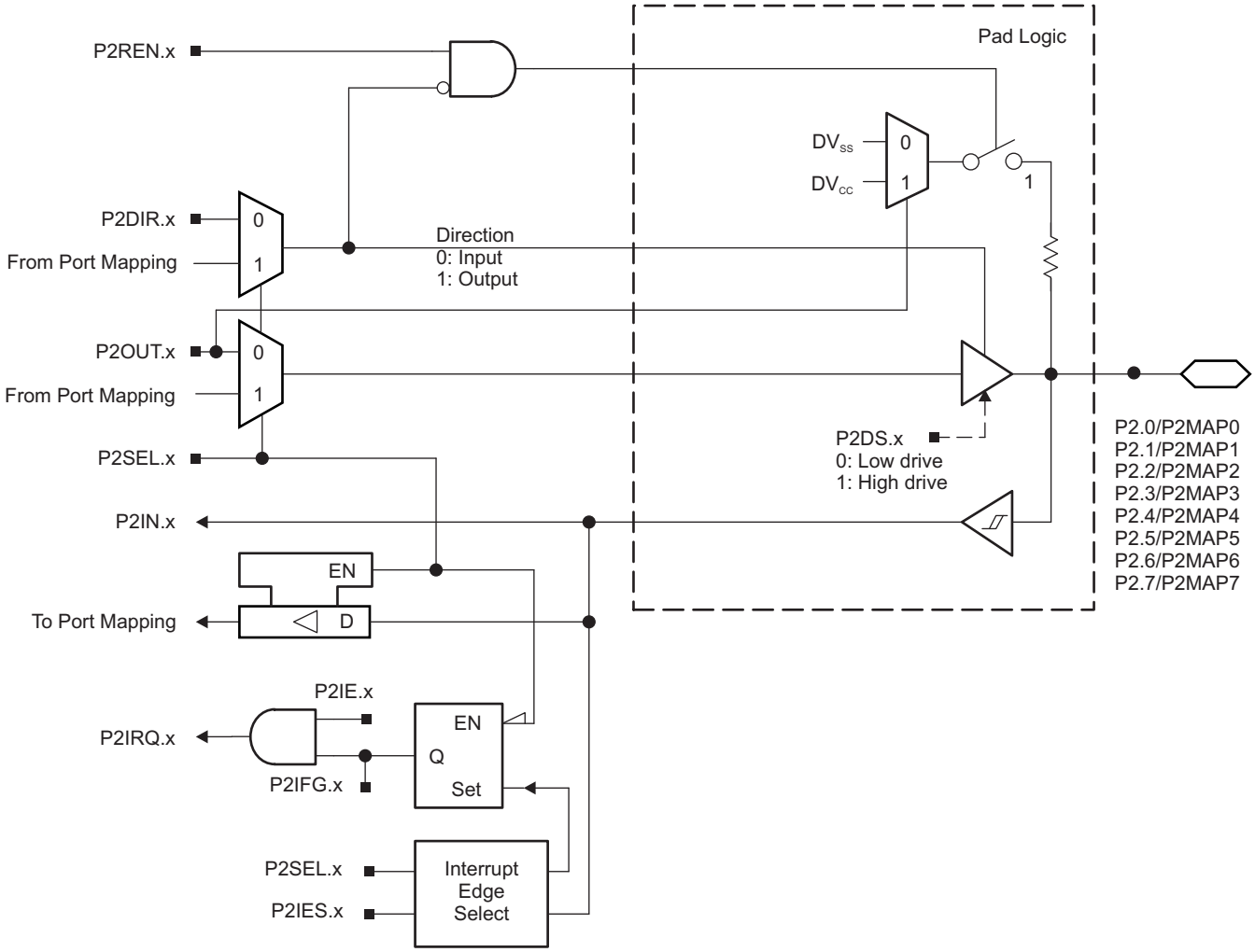


图 6-3. Port P2 (P2.0 to P2.7) Diagram

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表 6-52. Port P2 (P2.0 to P2.7) Pin Functions

PIN NAME (P2.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)		
			P2DIR.x	P2SEL.x	P2MAPx
P2.0/P2MAP0	0	P2.0 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.1/P2MAP1	1	P2.1 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.2/P2MAP2	2	P2.2 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.3/P2MAP3	3	P2.3 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.4/P2MAP4	4	P2.4 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.5/P2MAP5	5	P2.5 (I/O	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.6/P2MAP6	6	P2.6 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19
P2.7/P2MAP7	7	P2.7 (I/O)	I: 0; O: 1	0	
		Mapped secondary digital function	X	1	≤ 19

(1) X = Don't care

6.13.3 Port P3 (P3.0 to P3.7) Input/Output With Schmitt Trigger

图 6-4 shows the pin diagram. 表 6-53 summarizes how to select the pin function.

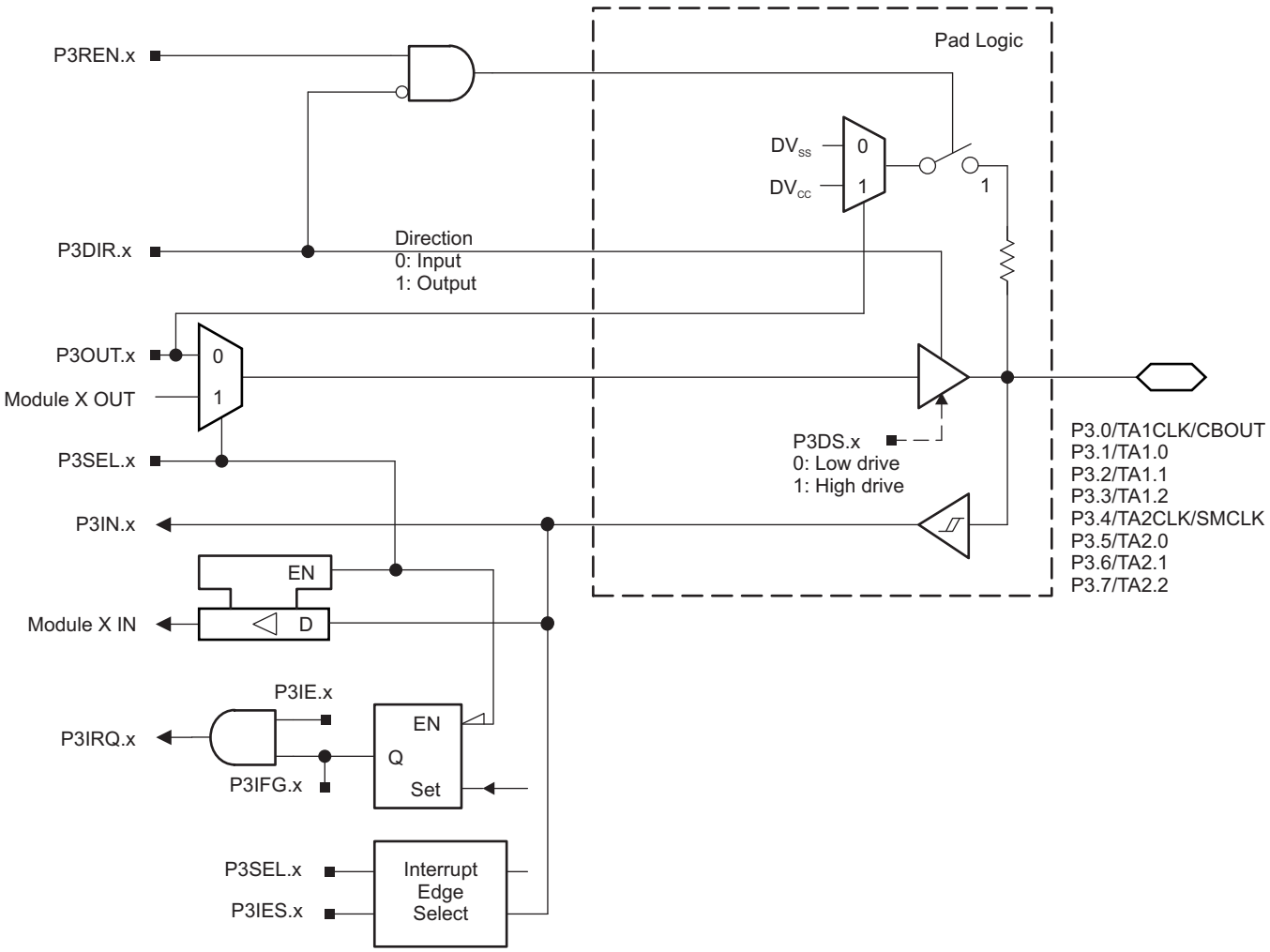


图 6-4. Port P3 (P3.0 to P3.7) Diagram

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表 6-53. Port P3 (P3.0 to P3.7) Pin Functions

PIN NAME (P3.x)	x	FUNCTION	CONTROL BITS OR SIGNALS	
			P3DIR.x	P3SEL.x
P3.0/TA1CLK/CBOUT	0	P3.0 (I/O)	I: 0; O: 1	0
		Timer TA1.TA1CLK	0	1
		CBOUT	1	1
P3.1/TA1.0	1	P3.1 (I/O)	I: 0; O: 1	0
		Timer TA1.CCI0A capture input	0	1
		Timer TA1.0 output	1	1
P3.2/TA1.1	2	P3.2 (I/O)	I: 0; O: 1	0
		Timer TA1.CCI1A capture input	0	1
		Timer TA1.1 output	1	1
P3.3/TA1.2	3	P3.3 (I/O)	I: 0; O: 1	0
		Timer TA1.CCI2A capture input	0	1
		Timer TA1.2 output	1	1
P3.4/TA2CLK/SMCLK	4	P3.4 (I/O)	I: 0; O: 1	0
		Timer TA2.TA2CLK	0	1
		SMCLK	1	1
P3.5/TA2.0	5	P3.5 (I/O)	I: 0; O: 1	0
		Timer TA2.CCI0A capture input	0	1
		Timer TA2.0 output	1	1
P3.6/TA2.1	6	P3.6 (I/O)	I: 0; O: 1	0
		Timer TA2.CCI1A capture input	0	1
		Timer TA2.1 output	1	1
P3.7/TA2.2	7	P3.7 (I/O)	I: 0; O: 1	0
		Timer TA2.CCI2A capture input	0	1
		Timer TA2.2 output	1	1

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6.13.4 Port P4 (P4.0 to P4.7) Input/Output With Schmitt Trigger

图 6-5 shows the pin diagram. 表 6-54 summarizes how to select the pin function.

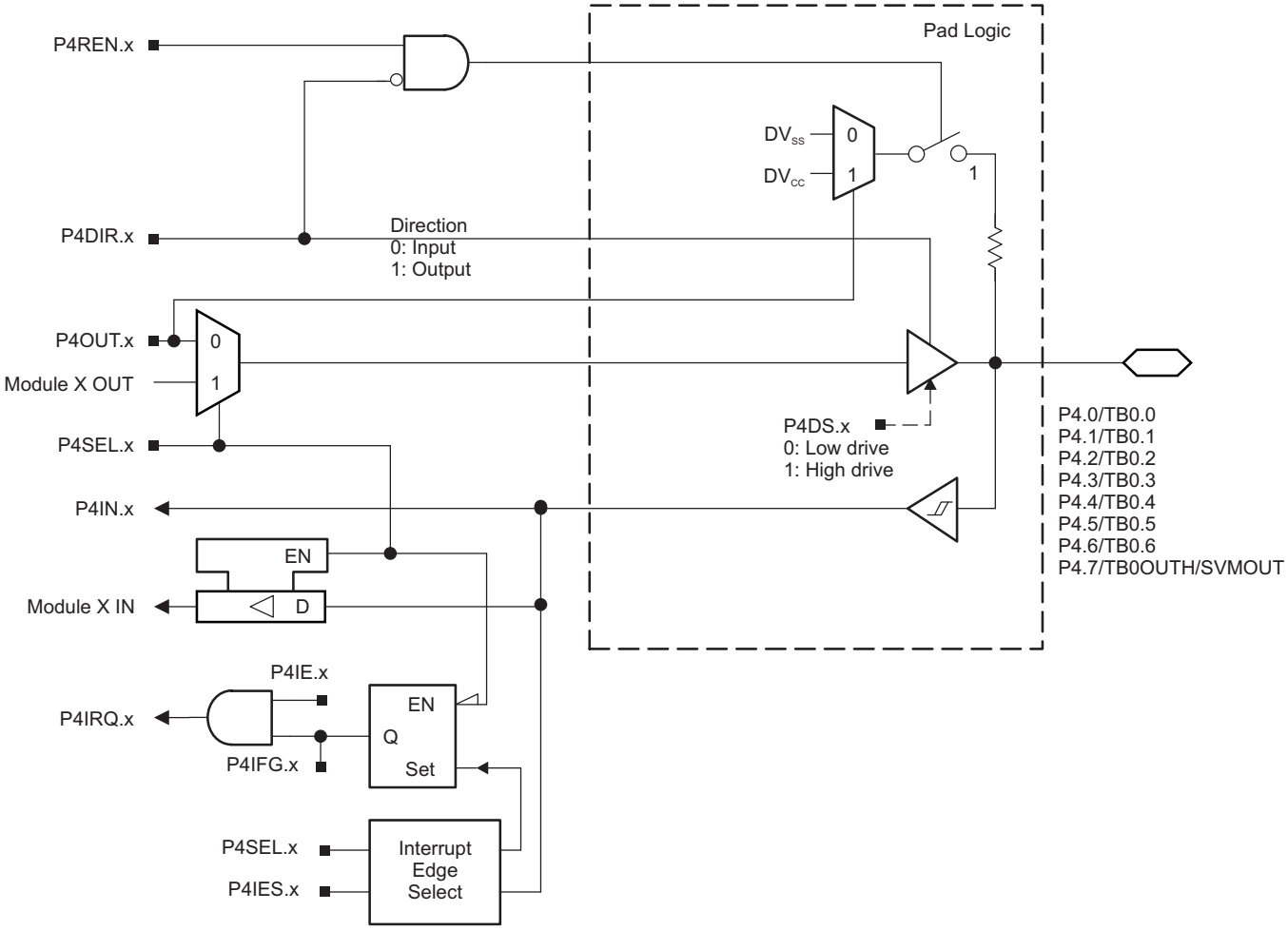


图 6-5. Port P4 (P4.0 to P4.7) Diagram

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表 6-54. Port P4 (P4.0 to P4.7) Pin Functions

PIN NAME (P4.x)	x	FUNCTION	CONTROL BITS OR SIGNALS	
			P4DIR.x	P4SEL.x
P4.0/TB0.0	0	P4.0 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI0A capture input	0	1
		Timer TB0.0 output(1)	1	1
P4.1/TB0.1	1	P4.1 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI1A capture input	0	1
		Timer TB0.1 output(1)	1	1
P4.2/TB0.2	2	P4.2 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI2A capture input	0	1
		Timer TB0.2 output(1)	1	1
P4.3/TB0.3	3	P4.3 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI3A capture input	0	1
		Timer TB0.3 output(1)	1	1
P4.4/TB0.4	4	P4.4 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI4A capture input	0	1
		Timer TB0.4 output(1)	1	1
P4.5/TB0.5	5	P4.5 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI5A capture input	0	1
		Timer TB0.5 output(1)	1	1
P4.6/TB0.6	6	P4.6 (I/O)	I: 0; O: 1	0
		Timer TB0.CCI6A capture input	0	1
		Timer TB0.6 output(1)	1	1
P4.7/TB0OUTH/ SVMOUT	7	P4.7 (I/O)	I: 0; O: 1	0
		Timer TB0.TB0OUTH	0	1
		SVMOUT	1	1

(1) Setting TB0OUTH causes all Timer_B configured outputs to be set to high impedance.

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6.13.5 Port P5 (P5.0 and P5.1) Input/Output With Schmitt Trigger

图 6-6 shows the pin diagram. 表 6-55 summarizes how to select the pin function.

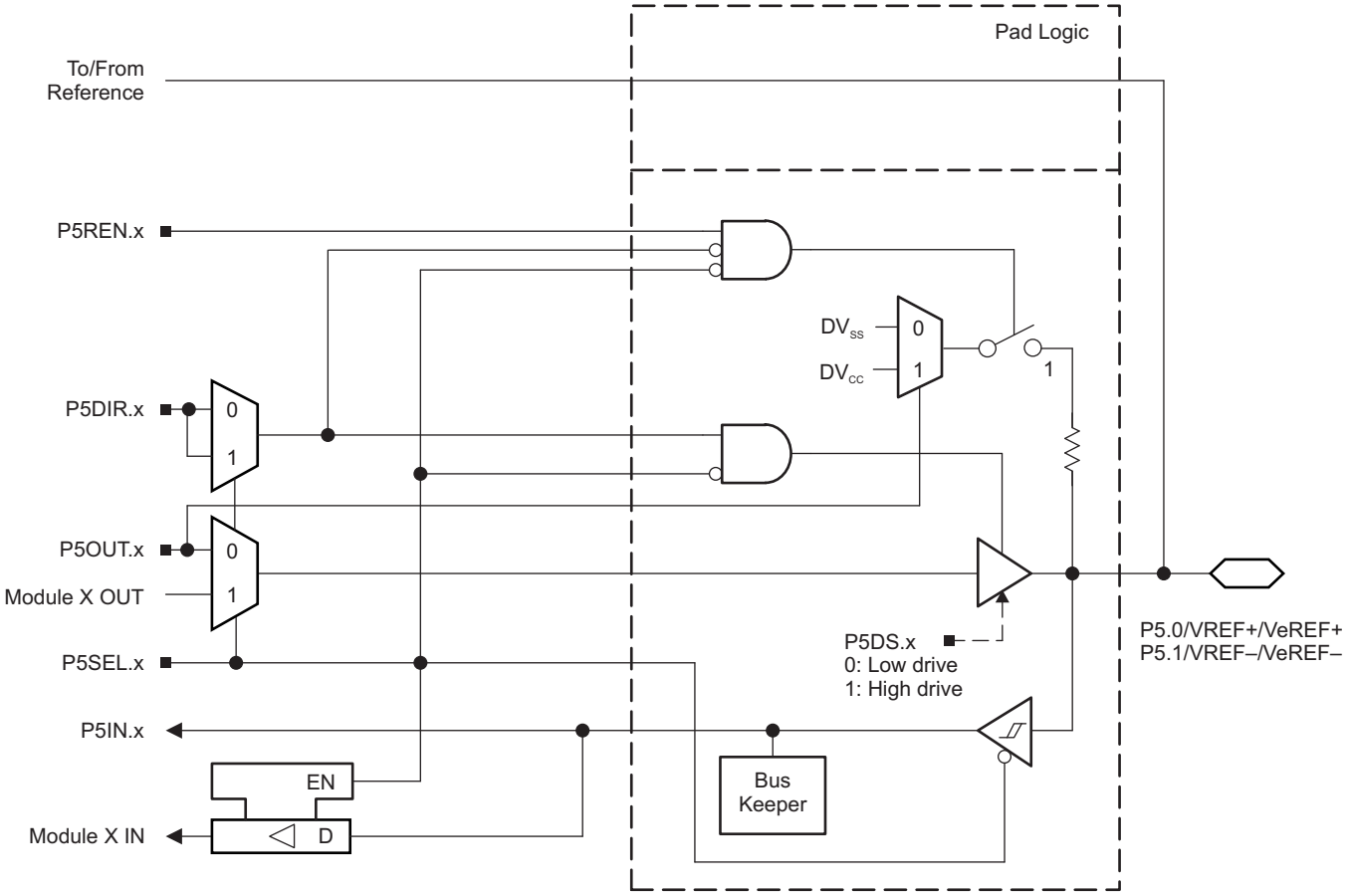


图 6-6. Port P5 (P5.0 and P5.1) Diagram

表 6-55. Port P5 (P5.0 and P5.1) Pin Functions

PIN NAME (P5.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)		
			P5DIR.x	P5SEL.x	REFOUT
P5.0/VREF+/VeREF+	0	P5.0 (I/O)(2)	I: 0; O: 1	0	X
		VeREF+(3)	X	1	0
		VREF+(4)	X	1	1
P5.1/VREF-/VeREF-	1	P5.1 (I/O)(2)	I: 0; O: 1	0	X
		VeREF-(5)	X	1	0
		VREF-(6)	X	1	1

(1) X = Don't care
(2) Default condition
(3) Setting the P5SEL.0 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. An external voltage can be applied to VeREF+ and used as the reference for the ADC12_A, Comparator_B, or DAC12_A.
(4) Setting the P5SEL.0 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. The ADC12_A VREF+ reference is available at the pin.
(5) Setting the P5SEL.1 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. An external voltage can be applied to VeREF- and used as the reference for the ADC12_A, Comparator_B, or DAC12_A.
(6) Setting the P5SEL.1 bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. The ADC12_A VREF- reference is available at the pin.

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6.13.6 Port P5 (P5.2 to P5.7) Input/Output With Schmitt Trigger

图 6-7 shows the pin diagram. 表 6-56 summarizes how to select the pin function.

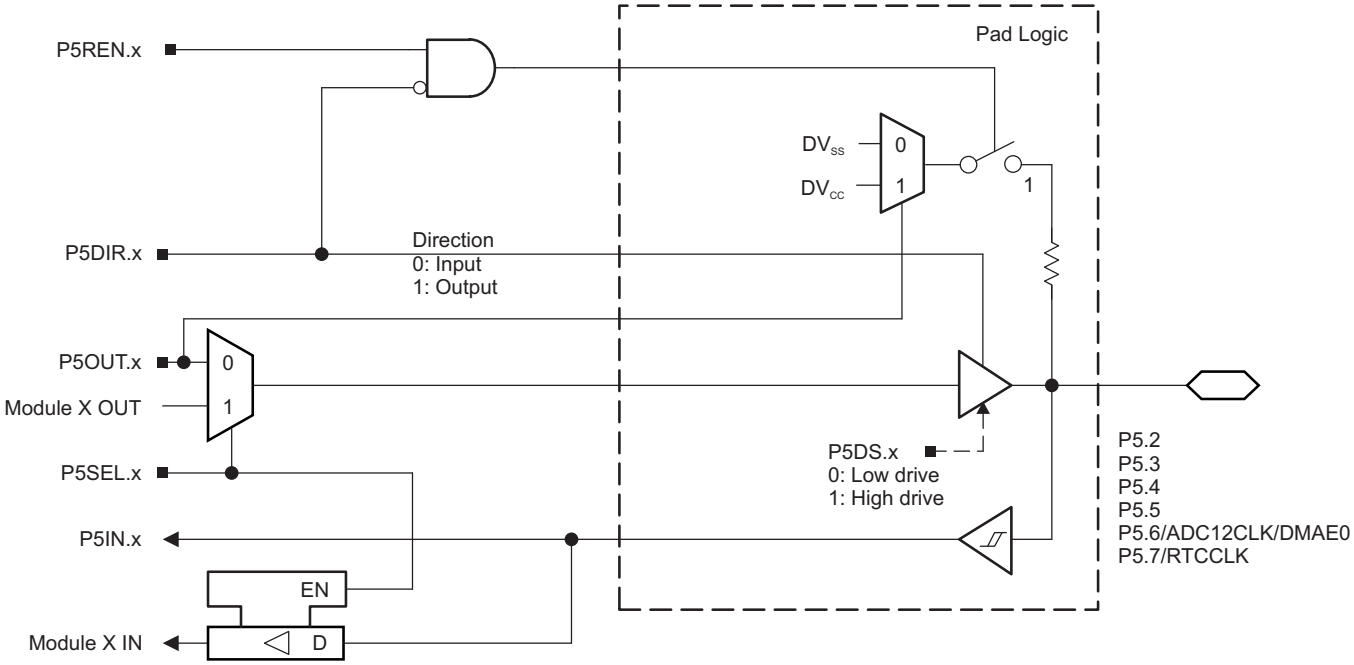


图 6-7. Port P5 (P5.2 to P5.7) Diagram

表 6-56. Port P5 (P5.2 to P5.7) Pin Functions

PIN NAME (P5.x)	x	FUNCTION	CONTROL BITS OR SIGNALS	
			P5DIR.x	P5SEL.x
P5.2	2	P5.2 (I/O)	I: 0; O: 1	0
P5.3	3	P5.3 (I/O)	I: 0; O: 1	0
P5.4	4	P5.4 (I/O)	I: 0; O: 1	0
P5.5	5	P5.5 (I/O)	I: 0; O: 1	0
P5.6/ADC12CLK/DMAE0	6	P5.6 (I/O)	I: 0; O: 1	0
		ADC12CLK	1	1
		DMAE0	0	1
P5.7/RTCCLK	7	P5.7 (I/O)	I: 0; O: 1	0
		RTCCLK	1	1

6.13.7 Port P6 (P6.0 to P6.7) Input/Output With Schmitt Trigger

图 6-8 shows the pin diagram. 表 6-57 summarizes how to select the pin function.

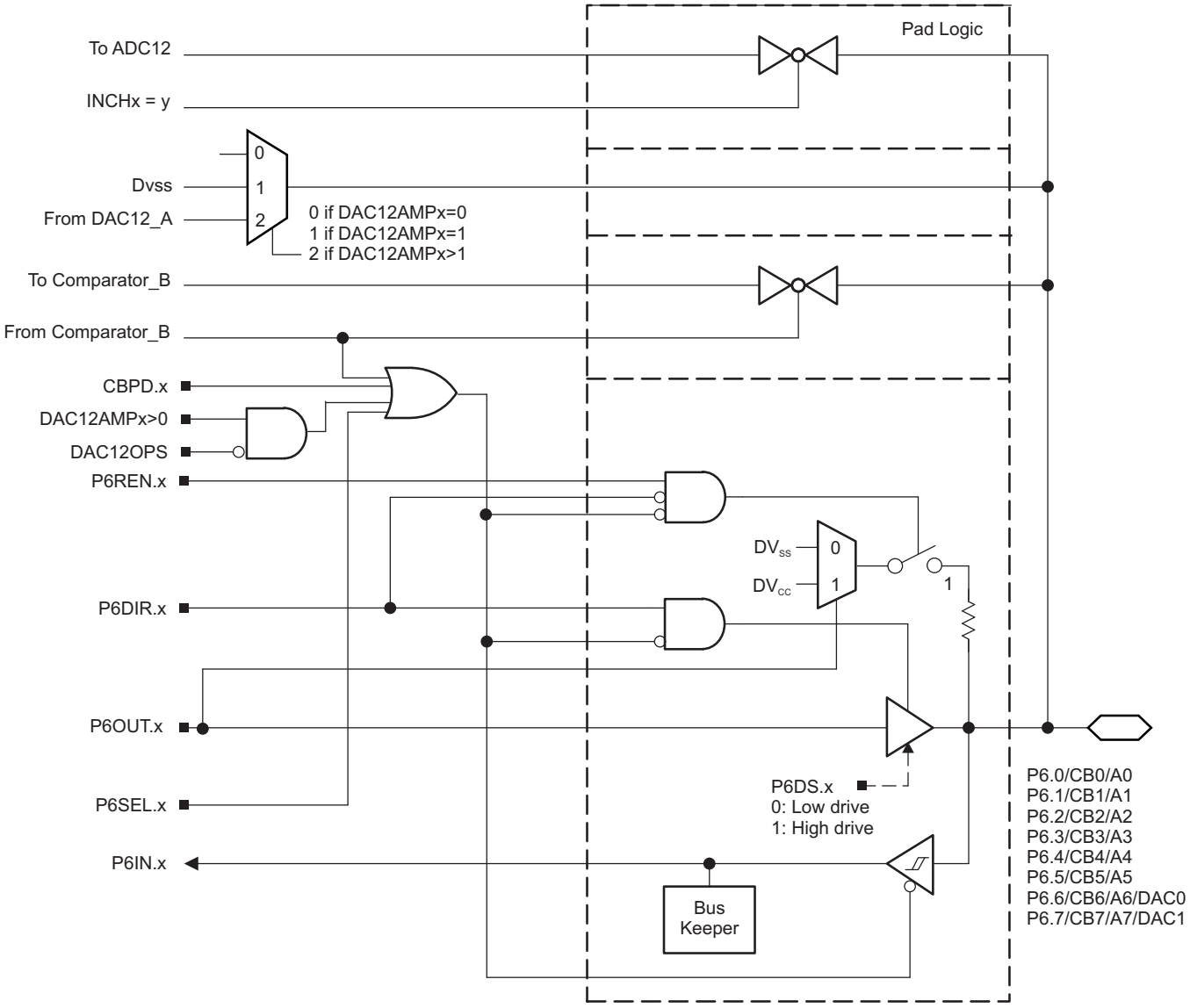


图 6-8. Port P6 (P6.0 to P6.7) Diagram

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表 6-57. Port P6 (P6.0 to P6.7) Pin Functions

PIN NAME (P6.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)				
			P6DIR.x	P6SEL.x	CBPD.x	DAC12OPS	DAC12AMPx
P6.0/CB0/A0	0	P6.0 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		CB0	X	X	1	n/a	n/a
		A0(2) (3)	X	1	X	n/a	n/a
P6.1/CB1/A1	1	P6.1 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		CB1	X	X	1	n/a	n/a
		A1(2) (3)	X	1	X	n/a	n/a
P6.2/CB2/A2	2	P6.2 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		CB2	X	X	1	n/a	n/a
		A2(2) (3)	X	1	X	n/a	n/a
P6.3/CB3/A3	3	P6.3 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		CB3	X	X	1	n/a	n/a
		A3(2) (3)	X	1	X	n/a	n/a
P6.4/CB4/A4	4	P6.4 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		CB4	X	X	1	n/a	n/a
		A4(2) (3)	X	1	X	n/a	n/a
P6.5/CB5/A5	5	P6.5 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		CB5	X	X	1	n/a	n/a
		A5 (2) (3)	X	1	X	n/a	n/a
P6.6/CB6/A6/DAC0	6	P6.6 (I/O)	I: 0; O: 1	0	0	X	0
		CB6	X	X	1	X	0
		A6(2) (3)	X	1	X	X	0
		DAC0	X	X	X	0	>1
P6.7/CB7/A7/DAC1	7	P6.7 (I/O)	I: 0; O: 1	0	0	X	0
		CB7	X	X	1	X	0
		A7(2) (3)	X	1	X	X	0
		DAC1	X	X	X	0	>1

(1) X = Don't care
(2) Setting the P6SEL.x bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.
(3) The ADC12_A channel Ax is connected internally to AV_{SS} if not selected by the respective INCHx bits.

6.13.8 Port P7 (P7.2) Input/Output With Schmitt Trigger

图 6-9 shows the pin diagram. 表 6-58 summarizes how to select the pin function.

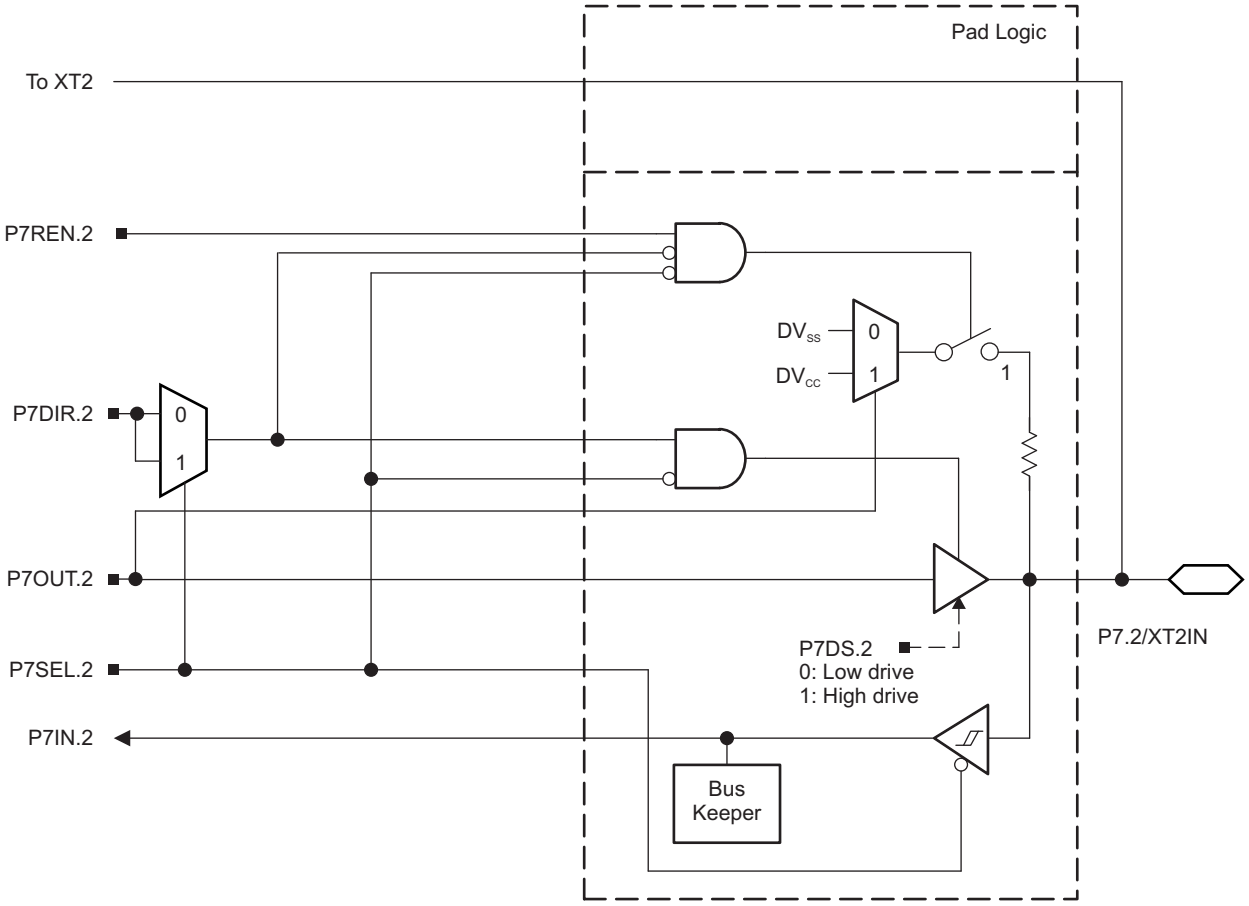


图 6-9. Port P7 (P7.2) Diagram

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6.13.9 Port P7 (P7.3) Input/Output With Schmitt Trigger

图 6-10 shows the pin diagram. 表 6-58 summarizes how to select the pin function.

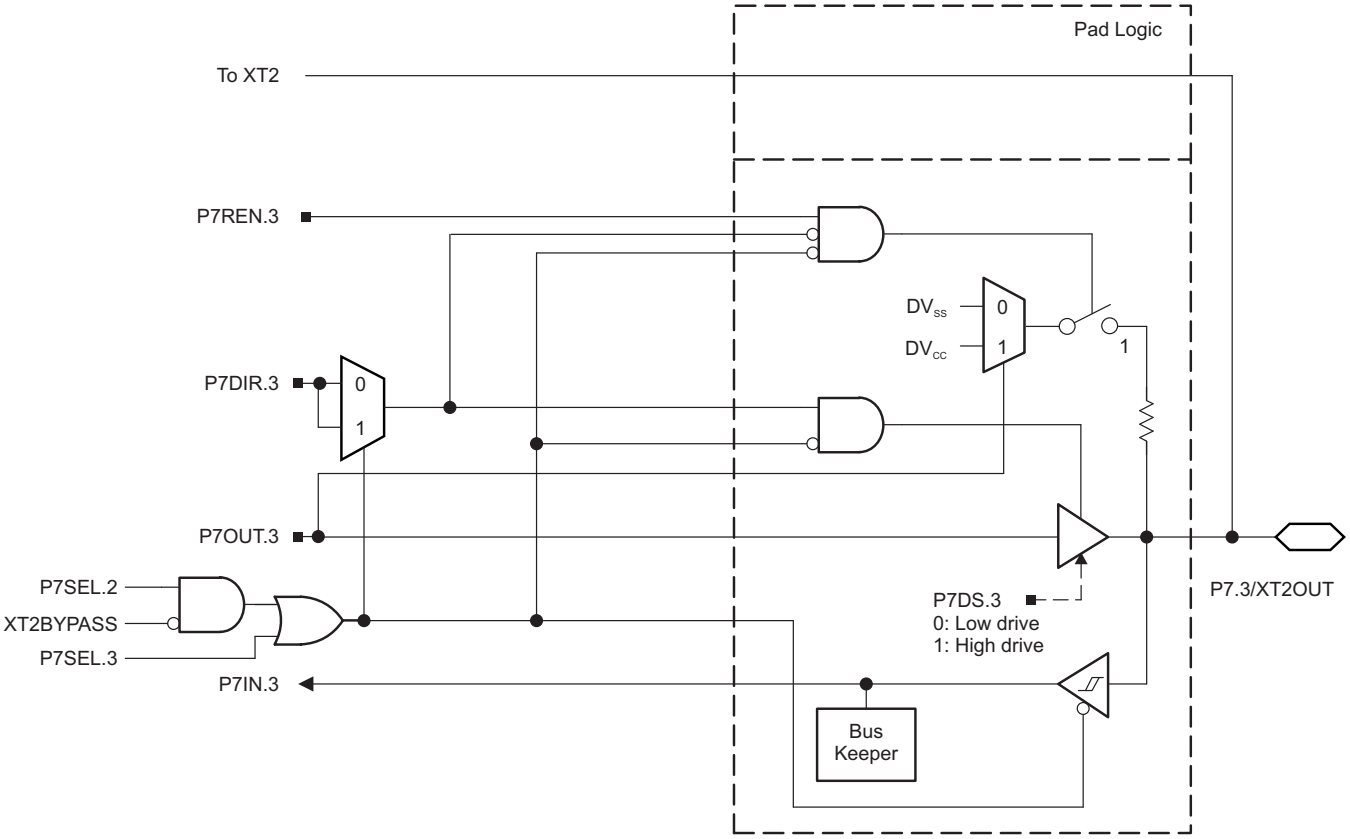


图 6-10. Port P7 (P7.3) Diagram

表 6-58. Port P7 (P7.2 and P7.3) Pin Functions

PIN NAME (P5.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)			
			P7DIR.x	P7SEL.2	P7SEL.3	XT2BYPASS
P7.2/XT2IN	2	P7.2 (I/O)	I: 0; O: 1	0	X	X
		XT2IN crystal mode(2)	X	1	X	0
		XT2IN bypass mode(2)	X	1	X	1
P7.3/XT2OUT	3	P7.3 (I/O)	I: 0; O: 1	0	0	X
		XT2OUT crystal mode(3)	X	1	X	0
		P7.3 (I/O)(3)	X	1	0	1

(1) X = Don't care
(2) Setting P7SEL.2 causes the general-purpose I/O to be disabled. Pending the setting of XT2BYPASS, P7.2 is configured for crystal mode or bypass mode.
(3) Setting P7SEL.2 causes the general-purpose I/O to be disabled in crystal mode. When using bypass mode, P7.3 can be used as general-purpose I/O.

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6.13.10 Port P7 (P7.4 to P7.7) Input/Output With Schmitt Trigger

图 6-11 shows the pin diagram. 表 6-59 summarizes how to select the pin function.

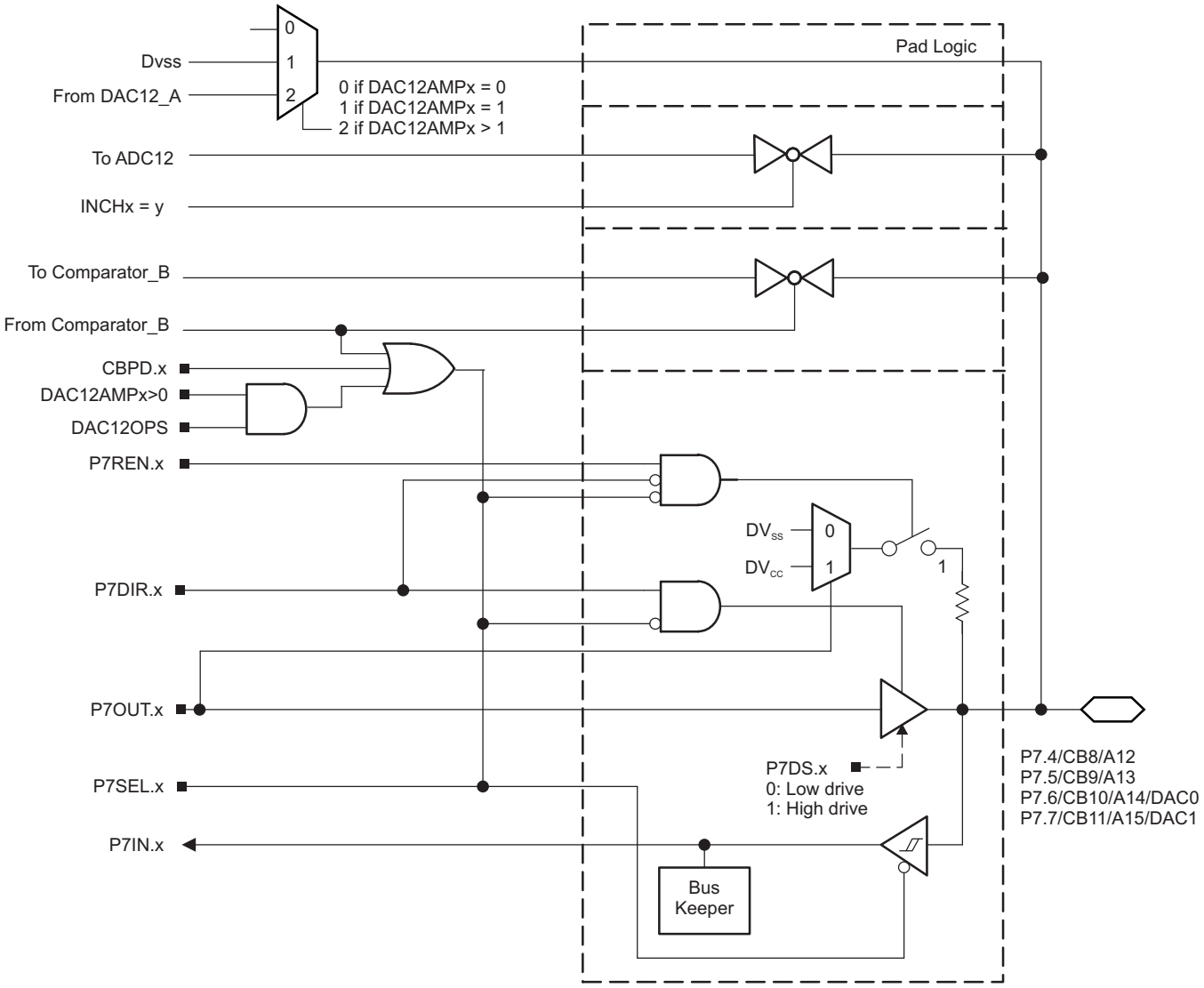


图 6-11. Port P7 (P7.4 to P7.7) Diagram

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表 6-59. Port P7 (P7.4 to P7.7) Pin Functions

PIN NAME (P7.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)				
			P7DIR.x	P7SEL.x	CBPD.x	DAC12OPS	DAC12AMPx
P7.4/CB8/A12	4	P7.4 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		Comparator_B input CB8	X	X	1	n/a	n/a
		A12(2) (3)	X	1	X	n/a	n/a
P7.5/CB9/A13	5	P7.5 (I/O)	I: 0; O: 1	0	0	n/a	n/a
		Comparator_B input CB9	X	X	1	n/a	n/a
		A13(2) (3)	X	1	X	n/a	n/a
P7.6/CB10/A14/DAC0	6	P7.6 (I/O)	I: 0; O: 1	0	0	X	0
		Comparator_B input CB10	X	X	1	X	0
		A14(2) (3)	X	1	X	X	0
		DAC12_A output DAC0	X	X	X	1	>1
P7.7/CB11/A15/DAC1	7	P7.7 (I/O)	I: 0; O: 1	0	0	X	0
		Comparator_B input CB11	X	X	1	X	0
		A15(2) (3)	X	1	X	X	0
		DAC12_A output DAC1	X	X	X	1	>1

(1) X = Don't care
(2) Setting the P7SEL.x bit disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.
(3) The ADC12_A channel Ax is connected internally to AV_{SS} if not selected by the respective INCHx bits.

6.13.11 Port P8 (P8.0 to P8.7) Input/Output With Schmitt Trigger

图 6-12 shows the pin diagram. 表 6-60 summarizes how to select the pin function.

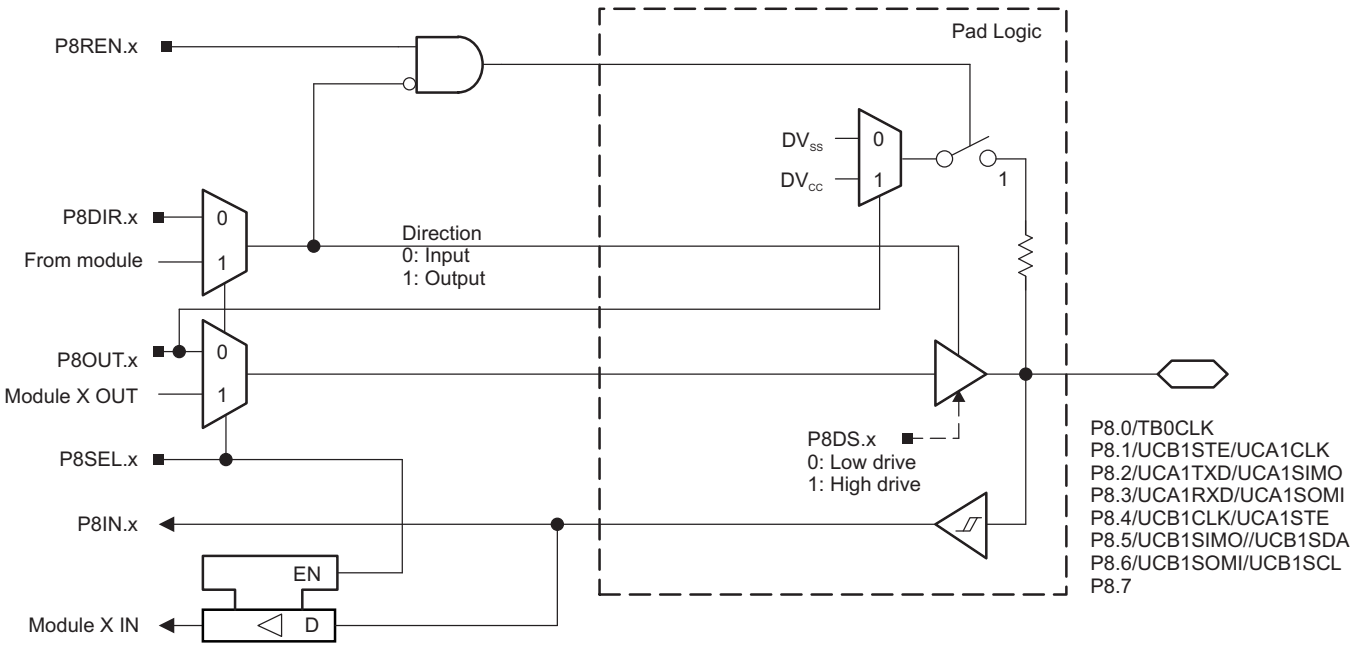


图 6-12. Port P8 (P8.0 to P8.7) Diagram

表 6-60. Port P8 (P8.0 to P8.7) Pin Functions

PIN NAME (P9.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)	
			P8DIR.x	P8SEL.x
P8.0/TB0CLK	0	P8.0 (I/O)	I: 0; O: 1	0
		Timer TB0.TB0CLK clock input	0	1
P8.1/UCB1STE/UCA1CLK	1	P8.1 (I/O)	I: 0; O: 1	0
		UCB1STE/UCA1CLK	X	1
P8.2/UCA1TXD/UCA1SIMO	2	P8.2 (I/O)	I: 0; O: 1	0
		UCA1TXD/UCA1SIMO	X	1
P8.3/UCA1RXD/UCA1SOMI	3	P8.3 (I/O)	I: 0; O: 1	0
		UCA1RXD/UCA1SOMI	X	1
P8.4/UCB1CLK/UCA1STE	4	P8.4 (I/O)	I: 0; O: 1	0
		UCB1CLK/UCA1STE	X	1
P8.5/UCB1SIMO/UCB1SDA	5	P8.5 (I/O)	I: 0; O: 1	0
		UCB1SIMO/UCB1SDA	X	1
P8.6/UCB1SOMI/UCB1SCL	6	P8.6 (I/O)	I: 0; O: 1	0
		UCB1SOMI/UCB1SCL	X	1
P8.7	7	P8.7 (I/O)	I: 0; O: 1	0

(1) X = Don't care

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6.13.12 Port P9 (P9.0 to P9.7) Input/Output With Schmitt Trigger

图 6-13 shows the pin diagram. 表 6-61 summarizes how to select the pin function.

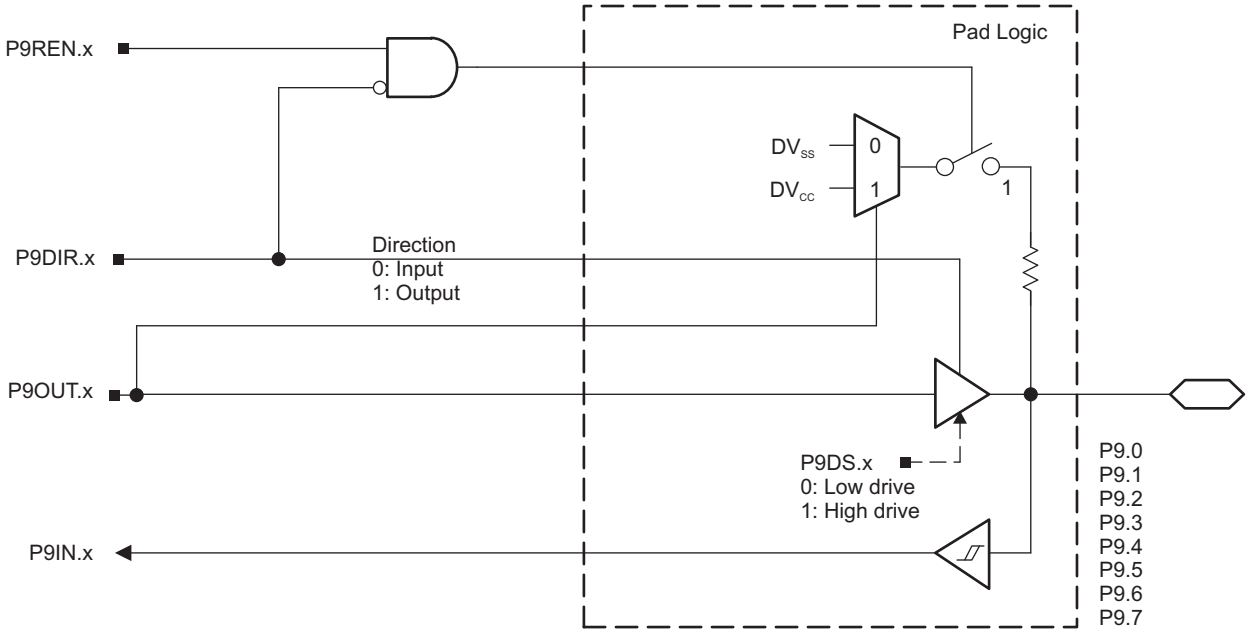


图 6-13. Port P9 (P9.0 to P9.7) Diagram

表 6-61. Port P9 (P9.0 to P9.7) Pin Functions

PIN NAME (P9.x)	x	FUNCTION	CONTROL BITS OR SIGNALS	
			P9DIR.x	P9SEL.x
P9.0	0	P9.0 (I/O)	I: 0; O: 1	0
P9.1	1	P9.1 (I/O)	I: 0; O: 1	0
P9.2	2	P9.2 (I/O)	I: 0; O: 1	0
P9.3	3	P9.3 (I/O)	I: 0; O: 1	0
P9.4	4	P9.4 (I/O)	I: 0; O: 1	0
P9.5	5	P9.5 (I/O)	I: 0; O: 1	0
P9.6	6	P9.6 (I/O)	I: 0; O: 1	0
P9.7	7	P9.7 (I/O)	I: 0; O: 1	0

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6.13.13 Port PU (PU.0/DP, PU.1/DM, PUR) USB Ports

图 6-14 shows the pin diagram. 表 6-62 summarizes how to select the pin function.

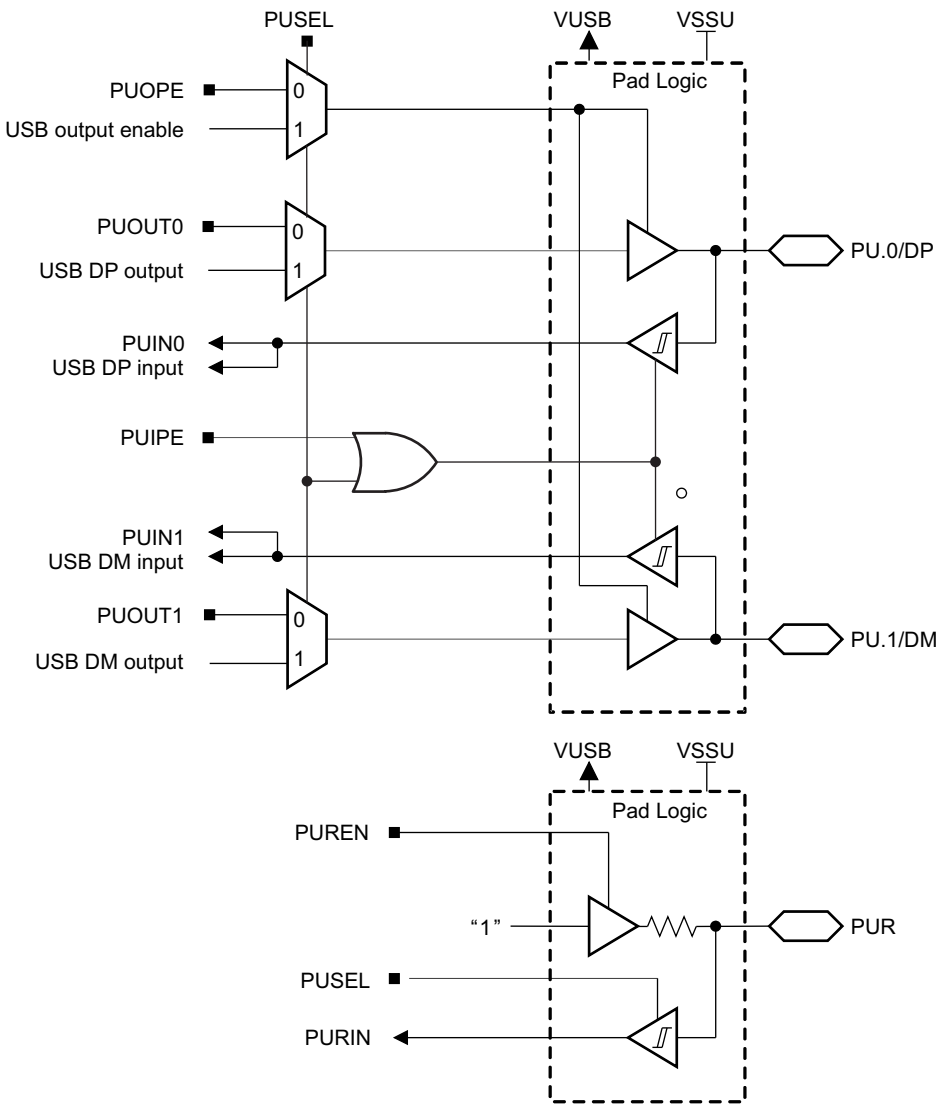


图 6-14. Port PU (PU.0 and PU.1) Diagram

表 6-62. Port PU.0/DP and PU.1/DM Output Functions

CONTROL BITS				PIN NAME		FUNCTION
PUSEL	PUDIR	PUOUT1	PUOUT0	PU.1/DM	PU.0/DP	
0	0	X	X	Hi-Z	Hi-Z	Outputs off
0	1	0	0	0	0	Outputs enabled
0	1	0	1	0	1	Outputs enabled
0	1	1	0	1	0	Outputs enabled
0	1	1	1	1	1	Outputs enabled
1	X	X	X	DM	DP	Direction set by USB module

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表 6-63. Port PUR Input Functions

CONTROL BITS		FUNCTION
PUSEL	PUREN	
0	0	Input disabled Pullup disabled
0	1	Input disabled Pullup enabled
1	0	Input enabled Pullup disabled
1	1	Input enabled Pullup enabled

6.13.14 Port PJ (PJ.0) JTAG Pin TDO, Input/Output With Schmitt Trigger or Output

图 6-15 shows the pin diagram. 表 6-64 summarizes how to select the pin function.

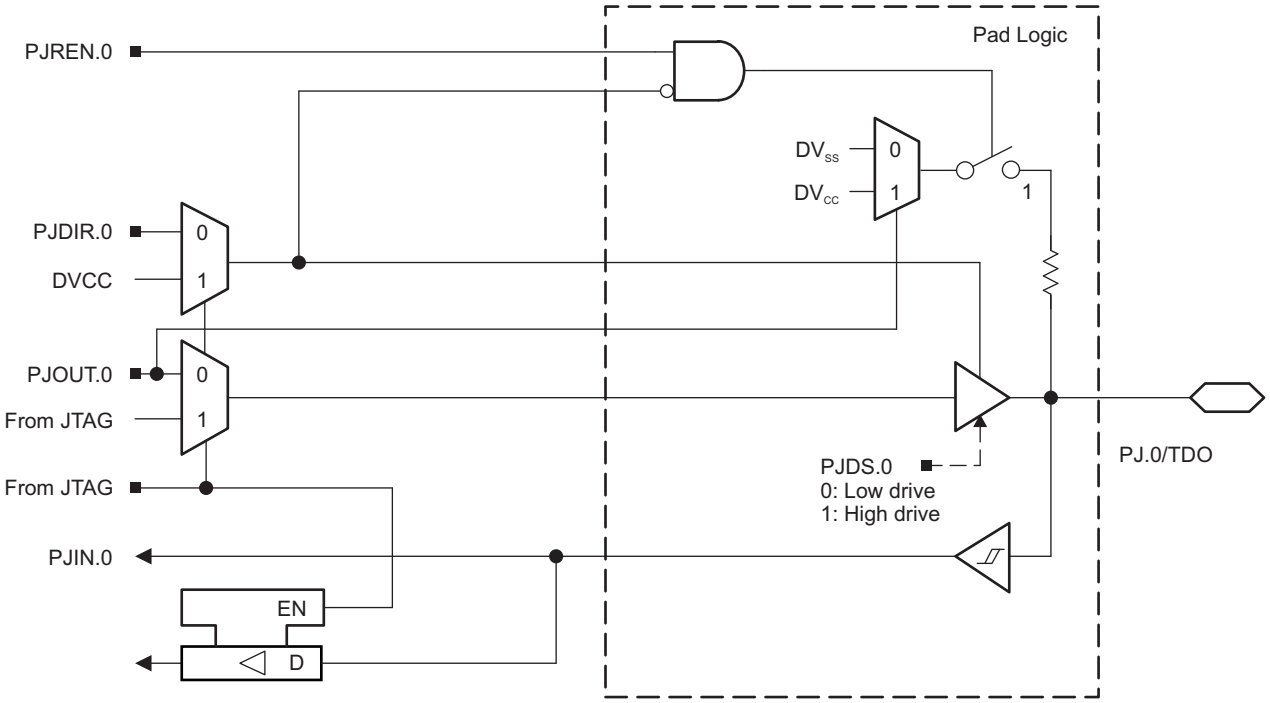


图 6-15. Port J (PJ.0) Diagram

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6.13.15 Port PJ (PJ.1 to PJ.3) JTAG Pins TMS, TCK, TDI/TCLK, Input/Output With Schmitt Trigger or Output

图 6-16 shows the pin diagram. 表 6-64 summarizes how to select the pin function.

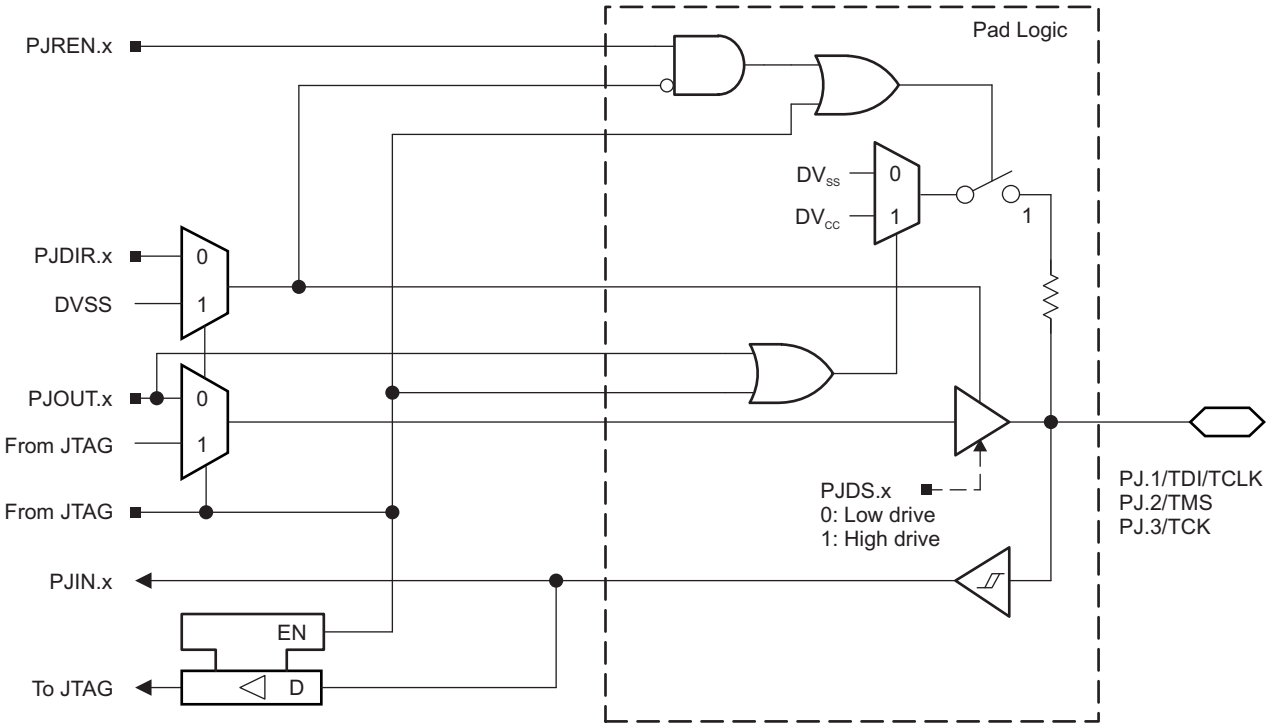


图 6-16. Port PJ (PJ.1 to PJ.3) Diagram

表 6-64. Port PJ (PJ.0 to PJ.3) Pin Functions

PIN NAME (PJ.x)	x	FUNCTION	CONTROL BITS OR SIGNALS(1)
			PJDIR.x
PJ.0/TDO	0	PJ.0 (I/O)(2)	I: 0; O: 1
		TDO(3)	X
PJ.1/TDI/TCLK	1	PJ.1 (I/O)(2)	I: 0; O: 1
		TDI/TCLK(3) (4)	X
PJ.2/TMS	2	PJ.2 (I/O)(2)	I: 0; O: 1
		TMS(3) (4)	X
PJ.3/TCK	3	PJ.3 (I/O)(2)	I: 0; O: 1
		TCK(3) (4)	X

(1) X = Don't care
(2) Default condition
(3) The pin direction is controlled by the JTAG module.
(4) In JTAG mode, pullups are activated automatically on TMS, TCK, and TDI/TCLK. PJREN.x are don't care.

6.14 Device Descriptors

表 6-65 list the contents of the device descriptor tag-length-value (TLV) structure.

表 6-65. MSP430F563x Device Descriptor Table(1)

DESCRIPTION		ADDRESS	SIZE (bytes)	VALUE								
				F5638	F5637	F5636	F5635	F5634	F5633	F5632	F5631	F5630
Info Block	Info length	01A00h	1	06h	06h	06h	06h	06h	06h	06h	06h	06h
	CRC length	01A01h	1	06h	06h	06h	06h	06h	06h	06h	06h	06h
	CRC value	01A02h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	Device ID	01A04h	2	8014h	8012h	8010h	800Eh	8044h	8042h	8040h	803Eh	803Ch
	Hardware revision	01A06h	1	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	Firmware revision	01A07h	1	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
Die Record	Die record tag	01A08h	1	08h	08h	08h	08h	08h	08h	08h	08h	08h
	Die record length	01A09h	1	0Ah	0Ah	0Ah	0Ah	0Ah	0Ah	0Ah	0Ah	0Ah
	Lot/wafer ID	01A0Ah	4	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	Die X position	01A0Eh	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	Die Y position	01A10h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	Test results	01A12h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
ADC12 Calibration	ADC12 calibration tag	01A14h	1	11h	11h	11h	11h	11h	11h	11h	11h	11h
	ADC12 calibration length	01A15h	1	10h	10h	10h	10h	10h	10h	10h	10h	10h
	ADC gain factor	01A16h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC offset	01A18h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC 1.5-V reference temp. I 30°C	01A1Ah	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC 1.5-V reference Temperature sensor 85°C	01A1Ch	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC 2.0-V reference Temperature sensor 30°C	01A1Eh	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC 2.0-V reference Temperature sensor 85°C	01A20h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC 2.5-V reference Temperature sensor 30°C	01A22h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit
	ADC 2.5-V reference Temperature sensor 85°C	01A24h	2	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit	per unit

(1) NA = Not applicable

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7 器件和文档支持

7.1 入门和后续步骤

有关 MSP430™系列器件、工具和库的更多相关信息，请访问 入门 页面。

7.2 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

MSP – Fully qualified production device

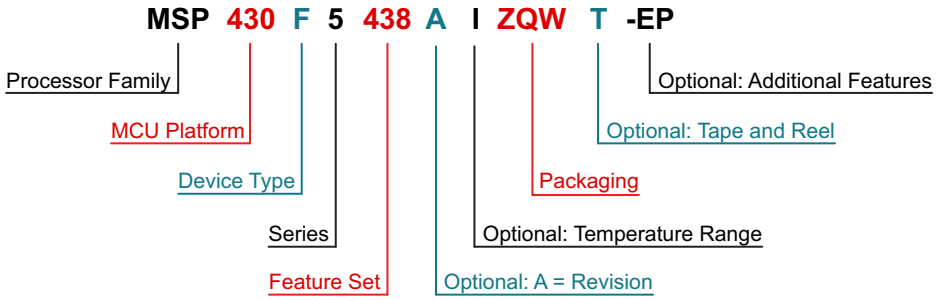
XMS devices are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format. 图 7-1 provides a legend for reading the complete device name.



Processor Family	CC = Embedded RF Radio MSP = Mixed-Signal Processor XMS = Experimental Silicon PMS = Prototype Device	
MCU Platform	430 = MSP430 low-power microcontroller platform	
Device Type	**Memory Type** C = ROM F = Flash FR = FRAM G = Flash or FRAM (Value Line) L = No Nonvolatile Memory	**Specialized Application** AFE = Analog Front End BQ = Contactless Power CG = ROM Medical FE = Flash Energy Meter FG = Flash Medical FW = Flash Electronic Flow Meter
Series	1 = Up to 8 MHz 2 = Up to 16 MHz 3 = Legacy 4 = Up to 16 MHz with LCD	5 = Up to 25 MHz 6 = Up to 25 MHz with LCD 0 = Low-Voltage Series
Feature Set	Various levels of integration within a series	
Optional: A = Revision	N/A	
Optional: Temperature Range	S = 0°C to 50°C C = 0°C to 70°C I = –40°C to 85°C T = –40°C to 105°C	
Packaging	http://www.ti.com/packaging	
Optional: Tape and Reel	T = Small reel R = Large reel No markings = Tube or tray	
Optional: Additional Features	-EP = Enhanced Product (–40°C to 105°C) -HT = Extreme Temperature Parts (–55°C to 150°C) -Q1 = Automotive Q100 Qualified	

图 7-1. Device Nomenclature

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7.3 工具与软件

所有 MSP 微控制器均受多种软件和硬件开发工具的支持。相关工具由 TI 以及多家第三方供应商提供。可从低功耗 MCU 开发套件和软件获取全部信息。

表 7-1 列出了 MSP430F563x MCU 的调试功能。关于可用特性的详细信息，请参见《*适用于 MSP430 的 Code Composer Studio 用户指南*》。

表 7-1. 硬件调试 特性

MSP430 架构	四线制 JTAG	2 线 JTAG	断点 (N)	范围断点	时钟控制	状态序列发生器	跟踪缓冲器	LPMx.5 调试支持
MSP430Xv2	有	是	8	是	是	是	是	否

设计套件与评估模块

MSP-TS430PZ100USB - 适用于 MSP430F5x 和 MSP430F6x MCU 的 100 引脚目标开发板 MSP-TS430PZ100USB 是一款独立的 100 引脚 ZIF 插座目标板，用于通过 JTAG 接口或 Spy Bi-Wire（2 线 JTAG）协议在系统内对 MSP430 MCU 进行编程和调试。

适用于 MSP430F5x 和 MSP430F6x MCU 的 100 引脚目标开发板和 MSP-FET 编程器捆绑包 MSP-FET 是一款强大的闪存仿真工具，可在 MSP430 MCU 上快速开始应用开发。它包含 USB 调试接口，用于通过 JTAG 接口或节省引脚的 Spy Bi-Wire（2 线 JTAG）协议在系统内对 MSP430 进行编程和调试。只需使用几次按键即可在数秒钟内擦除闪存并对其进行编程，此外，由于 MSP430 闪存具有超低功耗，因此无需外部电源。

软件

MSP430Ware™ 软件 MSP430Ware 软件集合了所有 MSP430 器件的代码示例、数据表以及其他设计资源，打包提供给用户。除了提供已有 MSP430 设计资源的完整集合外，MSP430Ware 软件还包含名为 MSP430 驱动程序库的高级 API。借助该库可以轻松地对 MSP430 硬件进行编程。MSP430Ware 软件以 CCS 组件或独立软件包两种形式提供。

MSP430F563x、MSP430F663x 代码示例 根据不同应用需求配置各集成外设的每个 MSP 器件均具备相应的 C 代码示例。

MSP 驱动程序库 驱动程序库的抽象化 API 通过提供易于使用的函数调用使您不再拘泥于 MSP430 硬件的细节。完整的文档通过具有帮助意义的 API 指南交付，其中包括有关每个函数调用和经过验证的参数的详细信息。开发人员可以使用驱动程序库功能，以最低开销编写完整项目。

MSP EnergyTrace™ 技术 适用于 MSP430 微控制器的 EnergyTrace 技术是基于电能的代码分析工具，用于测量和显示应用的电能系统配置并帮助优化应用以实现超低功耗。

ULP（超低功耗）Advisor ULP Advisor™软件是一款辅助工具，旨在指导开发人员编写更为高效的代码，从而充分利用 MSP 和 MSP432 微控制器独特的 超低功耗 功能。ULP Advisor 的目标人群是微控制器的资深开发者和开发新手，可以根据详尽的 ULP 检验表检查代码，以便最大限度地利用应用程序。在编译时，ULP Advisor 会提供通知和备注以突出显示代码中可以进一步优化的区域，进而实现更低功耗。

IEC60730 软件包 IEC60730 MSP430 软件包经过专门开发，用于协助客户达到 IEC 60730-1:2010（家用及类似用途的自动化电气控制 - 第 1 部分：一般要求）B 类产品的要求。其中涵盖家用电器、电弧检测器、电源转换器、电动工具、电动自行车及其他诸多产品。IEC60730 MSP430 软件包可以嵌入在 MSP430 中 运行的客户应用， 从而帮助客户简化其消费类器件在功能安全方面遵循 IEC 60730-1:2010 B 类规范的认证工作。

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适用于 MSP 的定点数学运算库 MSP IQmath 和 Qmath 库是为 C 语言开发者提供的一套经过高度优化的高精度数学运算函数集合，能够将浮点算法无缝嵌入 MSP430 和 MSP432 器件的定点代码中。这些例程通常用于计算密集型实时 应用， 而优化的执行速度、高精度以及超低能耗通常是影响这些实时应用的关键因素。与使用浮点数学算法编写的同等代码相比，使用 IQmath 和 Qmath 库可以大幅提高执行速度并显著降低能耗。

适用于 MSP430 的浮点数学运算库 TI 在低功耗和低成本微控制器领域锐意创新，为您提供 MSPMATHLIB。这是标量函数的浮点数学运算库，能够充分利用器件的智能外设，使性能提 升高达 26 倍。Mathlib 能够轻松集成到您的设计中。该运算库免费使用并集成在 Code Composer Studio 和 IAR IDE 中。如需深入了解该数学运算库及相关基准，请阅读用户指南。

开发工具

适用于 MSP 微控制器的 Code Composer Studio™ 集成开发环境 Code Composer Studio 是一种集成开发环境 (IDE)，支持所有 MSP 微控制器。Code Composer Studio 包含一整套开发和调试嵌入式应用 的嵌入式软件实用程序的工具。它包含了优化的 C/C++ 编译器、源代码编辑器、项目构建环境、调试器、描述器以及其他多种 功能。直观的 IDE 提供了单个用户界面，有助于完成应用程序开发流程的每个步骤。熟悉的实用程序和界面可提升用户的入门速度。Code Composer Studio 将 Eclipse 软件框架的优点和 TI 先进的嵌入式调试功能相结合，为嵌入式开发人员提供了一种功能丰富的优异开发环境。当 CCS 与 MSP MCU 搭配使用时，可以使用独特而强大的插件和嵌入式软件实用程序，从而充分利用 MSP 微控制器的功能。

命令行编程器 MSP Flasher 是一款基于 shell 的开源接口，可使用 JTAG 或 Spy-Bi-Wire (SBW) 通信通过 FET 编程器或 eZ430 对 MSP 微控制器进行编程。MSP Flasher 可用于将二进制文件（.txt 或 .hex 文件）直接下载到 MSP 微控制器，而无需使用 IDE。

MSP MCU 编程器和调试器 MSP-FET 是一款强大的仿真开发工具（通常称为调试探针），可帮助用户在 MSP 低功耗微控制器 (MCU) 中快速开发应用。创建 MCU 软件通常需要将生成的二进制程序下载到 MSP 器件，以进行验证和调试。MSP-FET 在主机和目标 MSP 间提供调试通信通道。此外，MSP-FET 还可在计算机的 USB 接口和 MSP UART 间提供反向通道 UART 连接。这为 MSP 编程器提供了一种在 MSP 和计算机上运行的终端之间进行串行通信的便捷方法。它还支持使用 BSL（引导加载程序）通过 UART 和 I^2C 通信协议将程序（通常称为固件）加载到 MSP 目标中。

MSP-GANG 生产编程器 MSP Gang 编程器是一款 MSP430 或 MSP432 器件编程器，可同时对多达八个完全相同的 MSP430 或 MSP432 闪存或 FRAM 器件进行编程。MSP Gang 编程器可使用标准的 RS-232 或 USB 连接与主机 PC 相连并提供灵活的编程选项，允许用户完全自定义流程。MSP Gang 编程器配有扩展板，即“Gang 分离器”，可在 MSP Gang 编程器和多个目标器件间实施互连。提供了八条电缆，用于将扩展板与八个目标器件相连（通过 JTAG 或 SPY-Bi-Wire 连接器）。编程工作可在 PC 或独立设备上完成。PC 端具备基于 DLL 的图形化用户界面。

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7.4 文档支持

以下文档对 MSP430F563x MCU 进行了介绍。www.ti.com.cn 网站上提供了这些文档的副本。

接收文档更新通知

要接收文档更新通知（包括器件勘误表），请转至 ti.com 上相关器件的产品文件夹（请参阅节 7.5）。请单击右上角的“通知我”按钮。点击注册后，即可收到产品信息更改每周摘要（如有）。有关更改的详细信息，请查阅已修订文档的修订历史记录。

勘误

《MSP430F5638 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5637 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5636 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5635 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5634 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5633 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5632 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5631 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

《MSP430F5630 器件勘误表》 说明了该器件已知的功能技术规格例外情况。

用户指南

《MSP430x5xx 和 MSP430x6xx 系列用户指南》 详细介绍了该器件系列提供的模块和外设。

《适用于 MSP430 的 Code Composer Studio 用户指南》 此用户指南介绍如何将 TI Code Composer Studio IDE 与 MSP430 超低功耗微控制器结合使用。

《适用于 MSP430 的 IAR Embedded Workbench 用户指南》 本手册介绍了 MSP430 超低功率微控制器在 IAR 嵌入式工作平台 (EW430) 的使用。

《MSP430™ 闪存器件引导加载程序 (BSL) 用户指南》 MSP430 引导加载程序（BSL，之前称为引导装载程序）方便用户在原型建模阶段、最终生产和维修期间与 MSP430 微控制器中的嵌入式存储器进行通信。可编程存储器（闪存）和数据存储器 (RAM) 能够按照要求进行变更。不要将此处的引导加载程序与某些数字信号处理器 (DSP) 中将外部存储器中的程序代码（和数据）自动加载到 DSP 内部存储器的引导装载程序混为一谈。

《通过 JTAG 接口对 MSP430 进行编程》 此文档介绍了使用 JTAG 通信端口擦除、编程和验证基于 MSP430 闪存和 FRAM 的微控制器系列的存储器模块所需的功能。此外，该文档还介绍了如何编程所有 MSP430 器件上均具备的 JTAG 访问安全保险丝。此文档介绍了使用标准四线制 JTAG 接口和两线制 JTAG 接口（也称为 Spy-Bi-Wire (SBW)）的器件访问。

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《MSP430 硬件工具用户指南》 此手册介绍了 TI MSP-FET430 闪存仿真工具 (FET) 的硬件。FET 是针对 MSP430 超低功耗微控制器的程序开发工具。文中对提供的接口类型，即并行端口接口和 USB 接口进行了说明。

应用报告

《MSP430 32kHz 晶体振荡器》 选择合适的晶体、正确的负载电路和适当的电路板布局是实现稳定的晶体振荡器的关键。该应用报告总结了晶体振荡器的功能，介绍了用于选择合适的晶体以实现 MSP430 超低功耗运行的参数。此外，还给出了正确电路板布局的提示和示例。此外，为了确保振荡器在大规模生产后能够稳定运行，还可能需要进行一些振荡器测试，该文档中提供了有关这些测试的详细信息。

《MSP430 系统级 ESD 注意事项》 随着硅晶技术向更低电压方向发展以及设计具有成本效益的超低功耗组件的需求的出现，系统级 ESD 要求变得越来越苛刻。该应用报告介绍了三个不同的 ESD 主题，旨在帮助电路板设计人员和 OEM 理解并设计出稳健耐用的系统级设计。

7.5 相关链接

表 7-2 列出了快速访问链接。类别包括技术文档、支持与社区资源、工具和软件，以及申请样片或购买产品的快速链接。

表 7-2. 相关链接

器件	产品文件夹	立即订购	技术文档	工具与软件	支持和社区
MSP430F5638	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5637	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5636	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5635	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5634	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5633	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5632	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5631	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
MSP430F5630	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处

7.6 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参见 TI 的 《使用条款》 。

TI E2E™ 社区

TI 的工程师交流 (E2E) 社区. 此社区的创建目的是为了促进工程师之间协作。在 e2e.ti.com 中，您可以提问、共享知识、拓展思路，在同领域工程师的帮助下解决问题。

TI 嵌入式处理器维基网页

德州仪器 (TI) 嵌入式处理器维基网页。此网站的建立是为了帮助开发人员熟悉德州仪器 (TI) 的嵌入式处理器，并且也为了促进与这些器件相关的硬件和软件的总体知识的创新和增长。

7.7 商标

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7.8 静电放电警告

ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。 精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

7.9 Export Control Notice

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Recipient agrees to not knowingly export or re-export, directly or indirectly, any product or technical data (as defined by the U.S., EU, and other Export Administration Regulations) including software, or any controlled product restricted by other applicable national regulations, received from disclosing party under nondisclosure obligations (if any), or any direct product of such technology, to any destination to which such export or re-export is restricted or prohibited by U.S. or other applicable laws, without obtaining prior authorization from U.S. Department of Commerce and other competent Government authorities to the extent required by those laws.

7.10 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

8 机械，封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MSP430F5630IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5630	Samples
MSP430F5630IZQWR	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5630	Samples
MSP430F5630IZQWT	NRND	BGA MICROSTAR JUNIOR	ZQW	113	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5630	
MSP430F5631IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5631	Samples
MSP430F5632IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5632	Samples
MSP430F5632IPZR	ACTIVE	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5632	Samples
MSP430F5632IZQWR	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5632	Samples
MSP430F5632IZQWT	LIFEBUY	BGA MICROSTAR JUNIOR	ZQW	113	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5632	
MSP430F5633IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5633	Samples
MSP430F5633IPZR	ACTIVE	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5633	Samples
MSP430F5633IZQWR	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5633	Samples
MSP430F5633IZQWT	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5633	Samples
MSP430F5634IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5634	Samples
MSP430F5634IZQWT	NRND	BGA MICROSTAR JUNIOR	ZQW	113	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5634	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MSP430F5635IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5635	Samples
MSP430F5635IPZR	ACTIVE	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5635	Samples
MSP430F5635IZQWR	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5635	Samples
MSP430F5635IZQWT	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5635	Samples
MSP430F5636IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5636	Samples
MSP430F5636IPZR	ACTIVE	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5636	Samples
MSP430F5636IZQWR	LIFEBUY	BGA MICROSTAR JUNIOR	ZQW	113	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5636	
MSP430F5637IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5637	Samples
MSP430F5637IPZR	ACTIVE	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5637	Samples
MSP430F5638IPZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5638	Samples
MSP430F5638IPZR	ACTIVE	LQFP	PZ	100	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F5638	Samples
MSP430F5638IZQWR	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5638	Samples
MSP430F5638IZQWT	ACTIVE	BGA MICROSTAR JUNIOR	ZQW	113	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	M430F5638	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

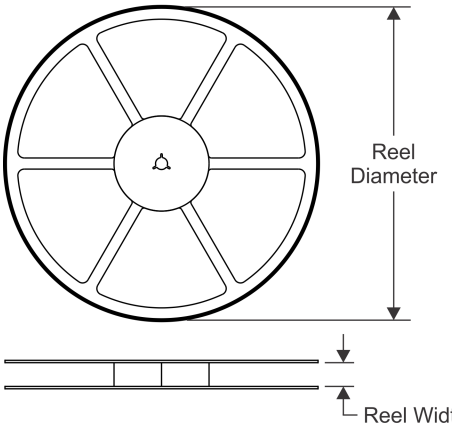
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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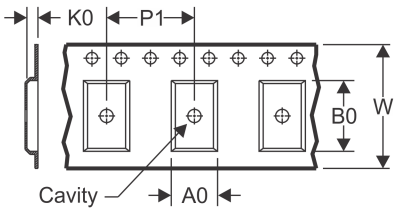
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

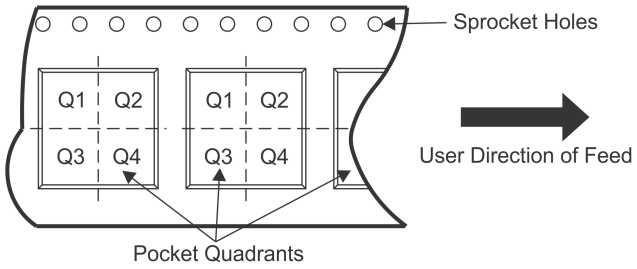


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

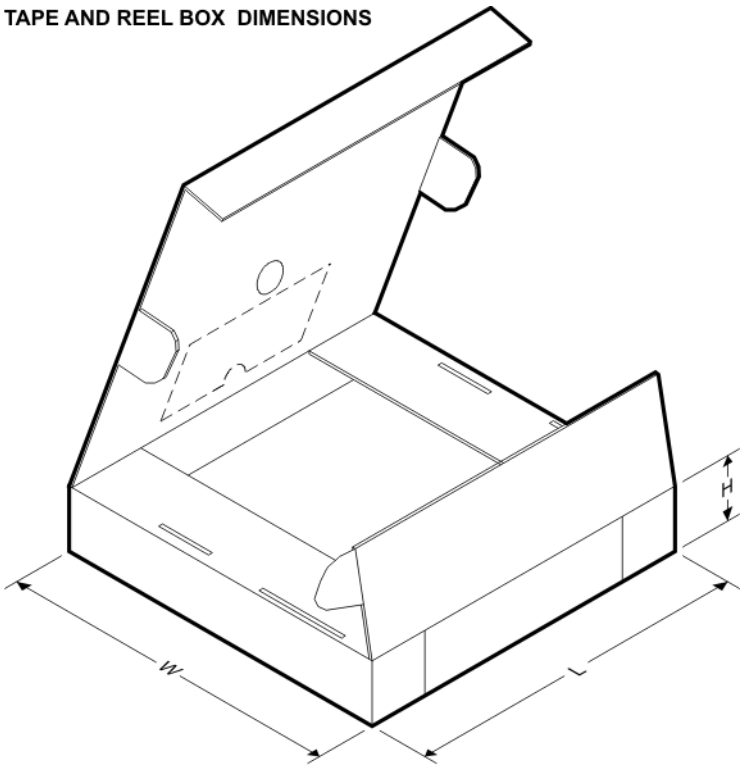


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MSP430F5630IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5630IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5632IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F5632IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5632IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5633IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F5633IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MSP430F5633IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5634IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5635IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F5635IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5635IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5636IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5637IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F5638IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1
MSP430F5638IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



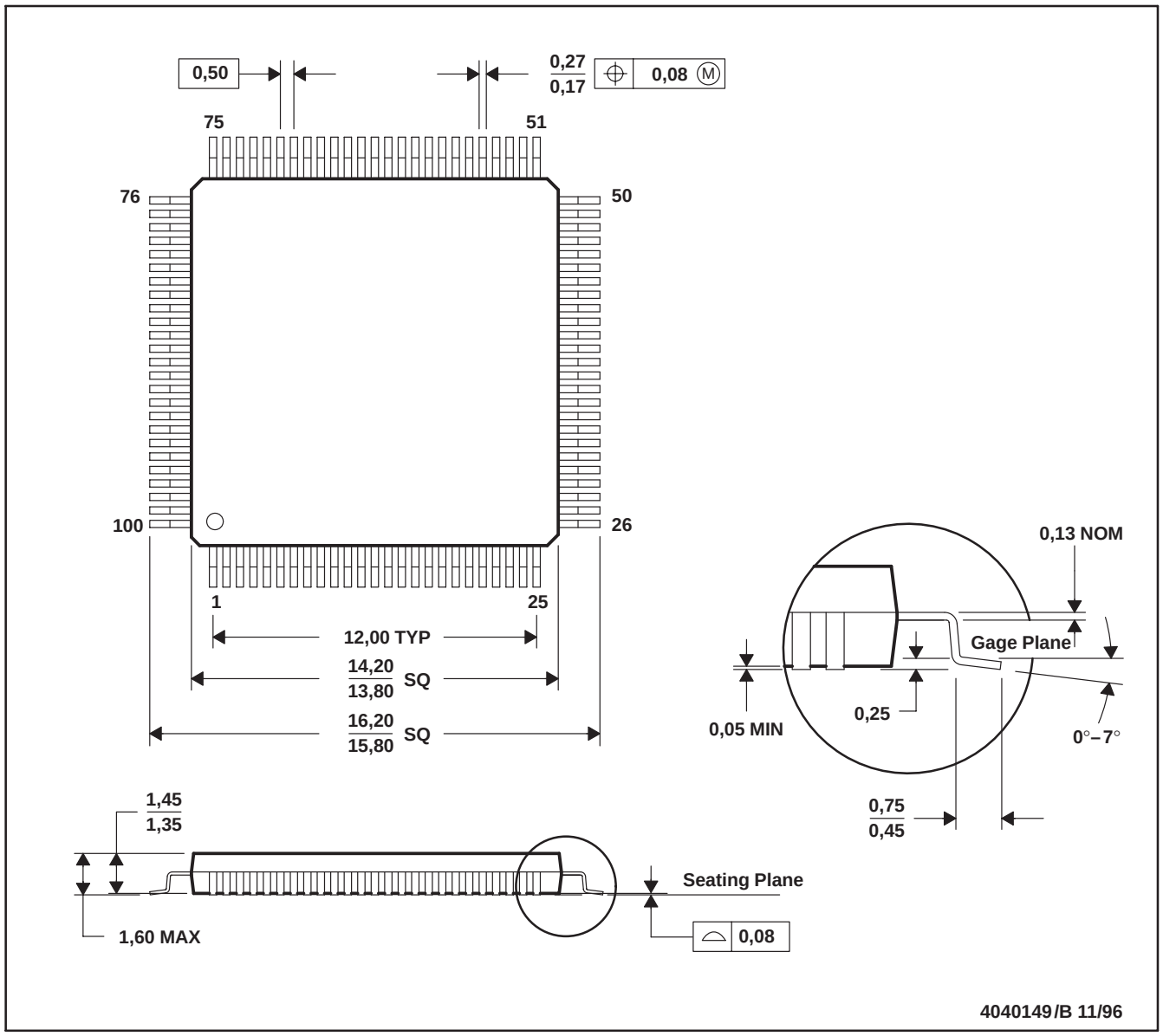
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MSP430F5630IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	350.0	350.0	43.0
MSP430F5630IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	213.0	191.0	55.0
MSP430F5632IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0
MSP430F5632IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	350.0	350.0	43.0
MSP430F5632IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	213.0	191.0	55.0
MSP430F5633IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0
MSP430F5633IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	350.0	350.0	43.0
MSP430F5633IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	213.0	191.0	55.0
MSP430F5634IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	213.0	191.0	55.0
MSP430F5635IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0
MSP430F5635IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	350.0	350.0	43.0
MSP430F5635IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	213.0	191.0	55.0
MSP430F5636IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	350.0	350.0	43.0
MSP430F5637IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MSP430F5638IZQWR	BGA MICROSTAR JUNIOR	ZQW	113	2500	350.0	350.0	43.0
MSP430F5638IZQWT	BGA MICROSTAR JUNIOR	ZQW	113	250	213.0	191.0	55.0

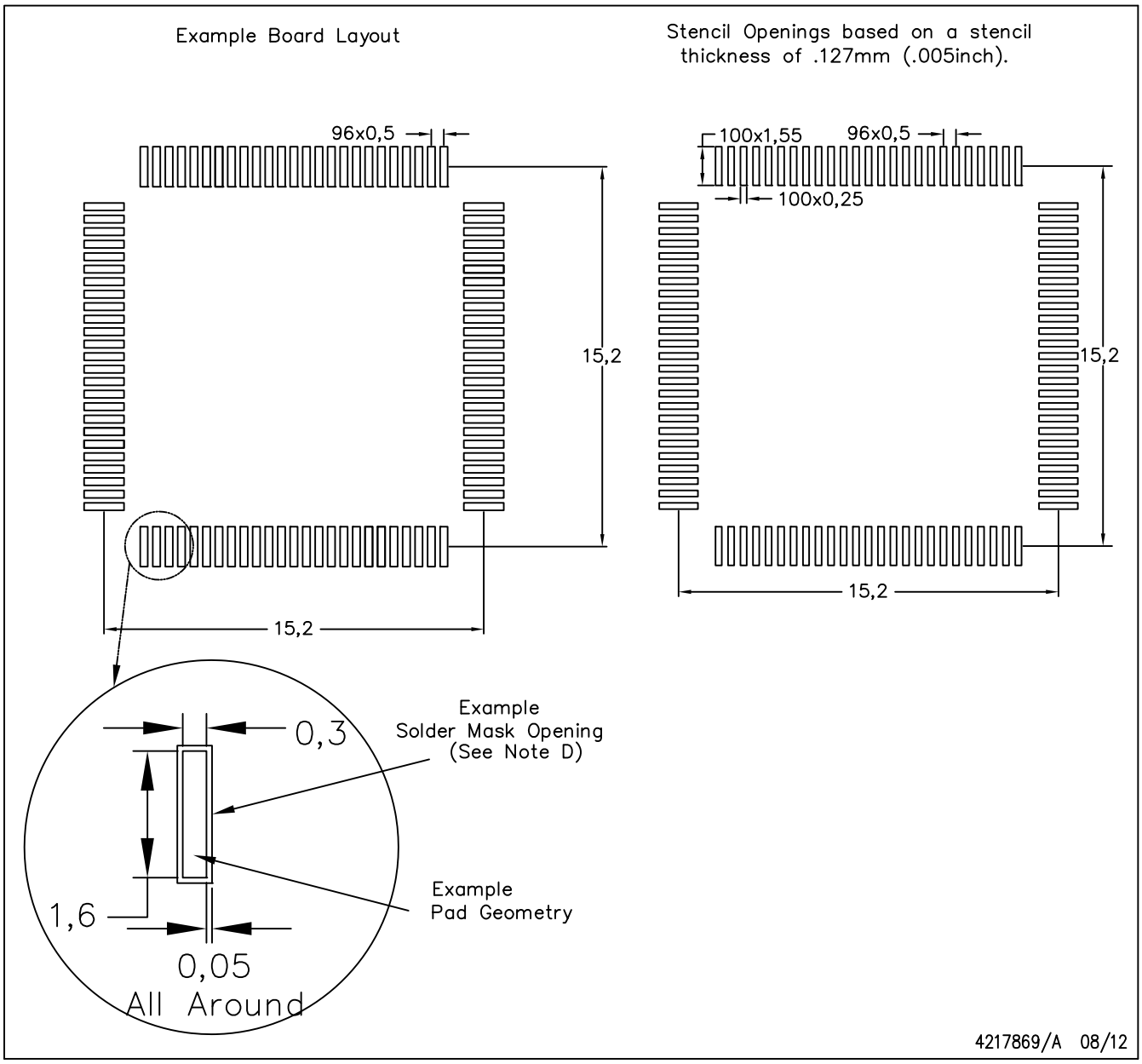
MTQF013A – OCTOBER 1994 – REVISED DECEMBER 1996

PZ (S-PQFP-G100) **PLASTIC QUAD FLATPACK**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-026

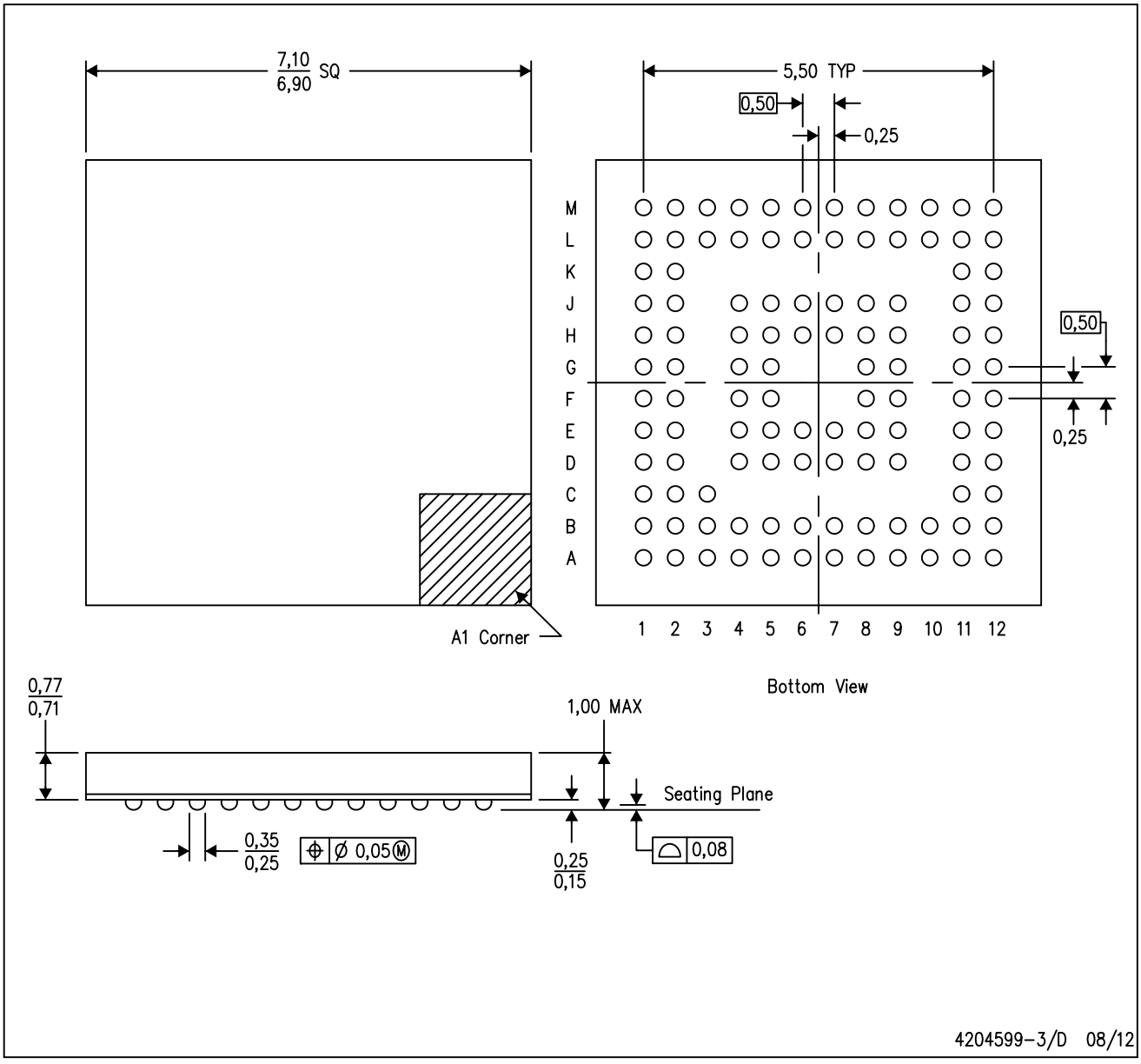
PZ (S–PQFP–G100) PLASTIC QUAD FLAT PACK



NOTES:

A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.
D. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

ZQW (S–PBGA–N113) PLASTIC BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO–225
D. This is a Pb–free solder ball design.

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